DISCRETE CLOCK GENERATOR AND TIMING/FREQUENCY REFERENCE

In various embodiments, the invention provides a discrete clock generator and/or a timing and frequency reference using an LC-oscillator topology, having a frequency controller to control and provide a stable resonant frequency, which may then be provided to other, second circuitry such as a processor or controller. Frequency stability is provided over variations in a selected parameter such as temperature and fabrication process variations. The various apparatus embodiments include a sensor adapted to provide a signal in response to at least one parameter of a plurality of parameters; and a frequency controller adapted to modify the resonant frequency in response to the second signal. In exemplary embodiments, the sensor is implemented as a current source responsive to temperature fluctuations, and the frequency controller is implemented as a plurality of controlled reactance modules which are selectively coupleable to the resonator or to one or more control voltages. The controlled reactance modules may include fixed or variable capacitances or inductances, and may be binary weighted. Arrays of resistive modules are also provided, to generate one or more control voltages.

53 Claims, 44 Drawing Sheets
FIG. 2

[Diagram showing the connections between Frequency Controller (215), Mode Selector (225), Oscillator (210), Frequency Divider (220), and Frequency Selector (205), with an output signal (200).]
**FIG. 5A**

![Graph showing current injection and waveform distortion over time](image)

**FIG. 5B**

![Graph showing temperature/bias dependence](image)

- **CURRENT (mA)**
- **VOLTAGE (V)**
- **TIME (ns)**

- **T = -40°C**
- **T = 30°C**
- **T = 100°C**

*TEMPERATURE/BIAS DEPENDENCE*
**FIG. 7A**

\[ I_{CTAT} \approx \frac{V_{BE}(T)}{R(T)} \]

**FIG. 7B**

\[ I_{PTAT} \approx \frac{V_T(T)}{R(T)} \ln \left( \frac{C}{W/L} \right) \]

\[ \approx \frac{V_T(T)}{R(T)} \ln C \]
FIG. 7C

\[ I_{PTAT}^2 \frac{2\beta_{14}}{\beta_{13}} \left( \frac{V_T(T)}{\ln\left(\frac{\beta_{11}}{\beta_{12}}\right)} \right)^2 \]

\[ \beta = K'(W/L) \]

\[ K' \text{ UNITS} = (A/V^2) \]

FIG. 7D
FIG. 12

TO NODES 470/475

$2^{y-1}C_{trim}$

$V_{i_{n_{y-1}}}$

$r_{y-1}$

$V_{in_{y-1}}$

$860$

$865_{y-1}$$865_1$$865_0$

$V_{in_{0}}$
FIG. 13

DIGITAL FREQUENCY DIVIDER

FREQUENCY DETECTOR (COUNTER-BASED)

DIGITAL PULSE COUNTER

CLOCK GENERATOR

CALIBRATION REGISTER

900
FIG. 19

START 1220

GENERATE A RESONANT SIGNAL HAVING A RESONANT FREQUENCY 1225

ADJUST THE RESONANT FREQUENCY IN RESPONSE TO TEMPERATURE 1230

ADJUST THE RESONANT FREQUENCY IN RESPONSE TO FABRICATION PROCESS VARIATION 1235

DIVIDE THE RESONANT SIGNAL HAVING THE RESONANT FREQUENCY INTO A PLURALITY OF SECOND SIGNALS HAVING A PLURALITY OF FREQUENCIES SUBSTANTIALLY EQUAL TO OR LOWER THAN THE RESONANT FREQUENCY 1240

SELECT AN OUTPUT SIGNAL FROM THE PLURALITY OF SECOND SIGNALS 1245

CONVERT DIFFERENTIAL SINUSOIDAL SIGNAL(S) TO SINGLE-ENDED, SUBSTANTIALLY SQUARE WAVE SIGNALS, HAVING SUBSTANTIALLY EQUAL HIGH AND LOW DUTY CYCLES, AS NEEDED 1250

SELECT AN OPERATING MODE OF A PLURALITY OF OPERATING Modes, INCLUDING CLOCK, TIMING/FREQUENCY REFERENCE, POWER CONSERVATION, AND PULSE MODE 1255

REFERENCE MODE? 1260

REFERENCE MODE? NO 1265

YES

SYNCHRONIZE A THIRD SIGNAL IN RESPONSE TO THE OUTPUT SIGNAL 1270

RETURN
FIG. 28

FIG. 29

CONTROL / COEFFICIENTS
FIG. 30

2200

2205
VOLTAGE SENSOR

2210
RESISTANCE SENSOR

2215
CURRENT SENSOR

2220
ADC

2225
REGISTER
CURRENT V INITIAL V
CURRENT R INITIAL R
CURRENT I INITIAL I

2230
COMPARATOR
AGE COMPENSATION SIGNAL

2235

2240
MEMORY

COEFFICIENTS AND/OR CONTROL SIGNALS
DISCRETE CLOCK GENERATOR AND TIMING/FREQUENCY REFERENCE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims priority to and is a continuation of McCorquodale, Michael S. et al., U.S. patent application Ser. No. 11/384,973, filed Mar. 20, 2006, entitled “Discrete Clock Generator and Timing/Frequency Reference”, which is commonly assigned herewith, the contents of all of which are incorporated herein in their entiries by reference, and with priority claimed for all commonly disclosed subject matter.


FIELD OF THE INVENTION

The present invention, in general, relates to oscillation or clocking signal generation, and more particularly, relates to a discrete clock signal generator and timing/frequency reference which is free-running, self-referenced, accurate over fabrication process, voltage and temperature, has low jitter.

BACKGROUND OF THE INVENTION

Accurate clock generators or timing references have generally relied upon crystal oscillators, such as quartz oscillators, which provide a mechanical, resonant vibration at a particular frequency. The difficulty with such crystal oscillators is that they cannot be fabricated as part of the same integrated circuit (“IC”) that is to be driven by their clock signal. For example, microprocessors such as the Intel Pentium processor require a separate clock IC. As a consequence, virtually every circuit requiring an accurate clock signal requires an off-chip clock generator.

There are several consequences for such non-integrated solutions. For example, because such a processor must be connected through outside circuitry (such as on a printed circuit board (PCB)), power dissipation is comparatively increased. In applications which rely on a finite power supply, such as battery power in mobile communications, such additional power dissipation is detrimental.

In addition, such non-integrated solutions, by requiring an additional IC, increase space and area requirements, whether on the PCB or within the finished product, which is also detrimental in mobile environments. Moreover, such additional components increase manufacturing and production costs, as an additional IC must be fabricated and assembled with the primary circuitry (such as a microprocessor).

Other clock generators which have been produced as integrated circuits with other circuits are generally not sufficiently accurate, particularly over fabrication process, voltage, and temperature (“PVT”) variations. For example, ring, relaxation and phase shift oscillators may provide a clock signal suitable for some low-sensitivity applications, but have been incapable of providing the higher accuracy required in more sophisticated electronics, such as in applications requiring significant processing capability or data communications. In addition, these clock generators or oscillators often exhibit considerable frequency drift, jitter, have a comparatively low Q-value, and are subject to other distortions from noise and other interference.

As a consequence, a need remains for a clock generator or timing reference which may be integrated monolithically with other circuitry, as a single IC, and which is highly accurate over PVT variations. Such a clock generator or timing reference should be free-running and self-referencing, and should not require locking or referencing to another reference signal. Such a clock generator or timing reference should exhibit minimal frequency drift and have comparitively low jitter, and should be suitable for applications requiring a highly accurate system clock. Such a clock generator or timing reference should also provide multiple operating modes, including a clock mode, a reference mode, a power conservation mode, and a pulsed mode. Lastly, such a clock generator or timing reference should provide for control over output frequency, to provide a stable and desired frequency in response to variation in ambient or junction temperature or variation in other parameters such as voltage, fabrication process, frequency, and age.

SUMMARY OF THE INVENTION

In various exemplary embodiments, the invention provides an apparatus which generates a frequency reference signal. The apparatus comprises a resonator, which may be implemented using one or more inductors and capacitors (as an “LC-tank”), a transconductance amplifier, a frequency controller and a temperature compensator for use in providing open-loop frequency control and selection for a low-jitter, free-running and self-referencing clock generator and/or a timing and frequency reference which is highly accurate over PVT and aging (time) variations and which can be integrated monolithically with other circuitry, to form a singular integrated circuit. No separate reference oscillator is required, and the exemplary embodiments are not phase-locked, delay-locked or otherwise locked to any other frequency reference.

Instead, the exemplary embodiments may be utilized as such
a reference oscillator which generates a frequency reference signal, which may then be locked to by one or more phase-locked or delay-locked loops. Various exemplary embodiments of the invention include features for highly accurate frequency generation over fabrication process, voltage, and temperature ("PVT") variations. These features include frequency tuning and selection, and compensation for frequency variations which may be caused due to temperature and/or voltage fluctuations, fabrication process variations, and varia-
tions due to aging of the integrated circuitry.

The invention may be provided as a discrete integrated circuit which provides a clock signal or other frequency reference signal, which may then be combined with other integrated circuits for any user application. The inventive apparatus may be configured or programmed for frequency selection, signal selection, input/output ("I/O") selection, I/O pin selection, spread-spectrum selection, and other options. Several methods are provided for such configuration and programming, including mask programmability during IC design and fabrication, manufacturer or distributor programmability post-fabrication of the IC, and user programmability post-fabrication of the IC.

The invention also may be combined with other integrated circuits to form a singular component, typically provided in a single IC package. For example, the inventive clock generator and/or a timing and frequency reference may be combined with any other, second circuitry, of any kind or type, for any function or application, such as various processors, controllers, digital signal processors, and so on, to provide an integrated, free-running clock for the second circuitry which does not require synchronization or locking to an external reference such as a crystal oscillator.

For example and without limitation, the clock generator and/or a timing and frequency reference may be combined with any of the following types of processors: a microprocessor; a digital signal processor; a controller; a microcontroller; a universal serial bus (USB) controller; a Peripheral Component Interconnect (PCI) controller; a Peripheral Component Interconnect Express (PCI-e) controller; a Firewire controller; an AT Attachment (ATA) interface controller; an Integrated Drive Electronics (IDE) controller; a Small Computer Systems Interface (SCSI) controller; a television controller; a local area network (LAN) controller; an Ethernet controller; a video controller; an audio controller; a modem processor; an MPEG controller; a multimedia controller; a communication controller; a mobile communication controller; an IEEE 802.11 controller; a GSM controller; a GPRS controller; a PCS controller; an AMPS controller; a CDMA controller; a WCDMA controller; a spread spectrum controller; a wireless LAN controller; an IEEE 802.11 controller; a DSL controller; a T1 controller; a ISDN controller; or a cable modem controller. Innumerable other types of second circuitry for integration with the inventive clock generator and/or a timing and frequency reference are also within the scope of the invention.

For such exemplary embodiments, the clock generator and/or a timing and frequency reference provides a first reference signal having a first frequency $f_o$. The first reference signal may be utilized in any of a plurality of ways, such as: (1) utilized directly by second circuitry as a clocking or frequency reference signal; (2) provided to one or more square-wave generators or divider circuits, with the resulting substantially square or divided signal(s) provided as output (as one or more second reference signals at a selected frequency or frequencies (e.g., having frequencies $f_{o1}, f_{o2}, ...$ through $f_{on}$), any one or more of which are then utilized by second circuitry as a clocking or frequency reference signal; (3) utilized for locking by a locking circuit, such as one or more phase-locked loops, delay-locked loops, or injection locking circuits, or by a combination of dividers and locking circuits, also to provide as output one or more second reference signals, at a selected frequency or frequencies (e.g., having frequencies $f_{o1}, f_{o2}, ...$ through $f_{on}$), to second circuitry.

These or more second reference signals can be switched, multiplexed or provided directly to any second circuitry, such as a processor, memory and input/output interface, as a clock or reference signal at a selected frequency. These signals may also be provided in any of a plurality of forms, such as single-ended, differential, phase-shifted quadrature, including in inverted and/or non-inverted forms.

Frequency selection for any of the frequencies $f_{o1}, f_{o2}, ...,$ through $f_{on}$ may be provided in a plurality of ways, depending upon the selected embodiment. The frequency selection may occur as part of design and fabrication, such as through selection of the number and size of inductors and capacitors utilized in the LC oscillator of the clock generator and/or a timing and frequency reference. For example, the size(s) and/or shape(s) of the one or more inductors may be selected through a suitable metal layer mask, and capacitors may be sized for generation of particular frequencies or range of frequencies. Frequency selection also may occur post-fabrication, through the use of the various calibration and control coefficients or signals, discussed in greater detail below. In addition, frequency selection may be performed through the configuration of the one or more locking circuits, such as through selection of the divide ratio(s) through programmable counters in phase-locked loops, which may be as part of the design and fabrication of the IC, or may be programmed post-fabrication, also through use of calibration and control coefficients or signals, or by switching dividers in or out of the divide chain. Additional configuration methods are discussed in greater detail below.

Additional embodiments also provide for generating a plurality of frequency reference signals, whether sinusoidal or square-wave, such as for use as one or more clock signals or reference frequency sources. In exemplary embodiments, the clock/frequency reference of the invention is coupled to one or more phase-locked loops ("PLLs") or delay-locked loops ("DLLs"), to provide a corresponding plurality of output reference signals at selected frequencies. Various exemplary embodiments may be configurable or programmable, through control signals or stored coefficients, such as to adjust the divide ratios of the PLLs or DLLs for corresponding frequency selection.

For applications potentially requiring a high Q value, low jitter and low phase noise, the resonator typically comprises one or more inductors and capacitors, forming one or more LC-tanks or LC resonators. In a first embodiment, a double-balanced, differential LC oscillator topology is utilized. In other exemplary embodiments, differential or single-ended LC oscillator topologies may be utilized, such as a differential n-MOS cross-coupled topology; a differential p-MOS cross-coupled topology; a single-ended Colpitts LC oscillator, a single-ended Hartley LC oscillator, a differential Colpitts LC oscillator (both common base and common collector versions), a differential Hartley LC oscillator (also both common base and common collector versions), a single-ended Pierce LC oscillator, a quadrature oscillator (e.g., formed from at least two double-balanced, differential LC oscillators). In any of these embodiments, an active inductor may be utilized in the LC oscillator or in the other reactive components. Any of these LC topologies may be implemented to be balanced, cross-coupled, differential, or single-ended, and may utilize any type of transistors, such as n-MOS, p-MOS, or BJT, for example. Additional LC oscillator topologies, now known or
which become known, are considered equivalent and within the scope of the present invention.

Exemplary embodiments of the present invention also provide several different levels and types of control. For example, both discrete and continuous control are provided, in real time, for control over output frequency of the free-running oscillator in light of such variations. In addition, such control is provided generally as an open-loop, without requiring or necessitating a feedback connection and without requiring continuous locking of the oscillator to another reference signal.

In addition, exemplary embodiments of the invention provide a clock generator and/or a timing and frequency reference having multiple operating modes, including modes such as a power conservation mode, a clock mode, a reference mode, and a pulsed mode. In addition, the various embodiments provide multiple output signals at different frequencies, and provide low-latency and glitch-free switching between these various signals.

Significantly, various exemplary embodiments of the invention generate a significantly and comparatively high frequency, such as in the hundreds of MHz and GHz range, which is then divided to a plurality of lower frequencies. Each such division by “N” (a rational number, as a ratio of integers) results in a significant noise reduction, with phase noise reduced by N and phase noise power reduced by N². As a consequence, exemplary embodiments of the invention result in significantly less relative period jitter than other oscillators that generate their output directly or through frequency multiplications.

Various apparatus embodiments include a resonator, an amplifier, and a frequency controller, which may include various components or modules such as a temperature compensator, a process variation compensator, a voltage isolator and/or voltage compensator, an age (time) variation compensator, a frequency divider, and a frequency selector. The resonator provides a first signal having a resonant frequency. A temperature compensator adjusts the resonant frequency in response to temperature, and the process variation compensator adjusts the resonant frequency in response to fabrication process variation. In addition, the various embodiments may also include a frequency divider to divide the first signal having the resonant frequency into a plurality of second signals having a corresponding plurality of frequencies which are substantially equal to or lower than the resonant frequency; and a frequency selector to provide an output signal from the plurality of second signals. The frequency selector may further include a glitch-suppressor. The output signal may be provided in any of various forms, such as differential or single-ended, and substantially square-wave or sinusoidal.

Exemplary embodiments of the present invention provide an apparatus for frequency control of an integrated, free-running harmonic oscillator, comprising a resonator adapted to provide a first signal having a resonant frequency; a sensor adapted to provide a second signal, such as a control voltage, in response to at least one parameter of a plurality of parameters; and a frequency controller coupled to the sensor and coupled to the resonator, with the frequency controller adapted to modify a reactance element coupled to the resonator in response to the second signal to modify the resonant frequency. The plurality of parameters are variable and comprise at least one of the following parameters: temperature, fabrication process, voltage, frequency, and age (i.e., elapsed time).

In the exemplary embodiments, the frequency controller is further adapted to modify an effective reactance or impedance element coupled to the resonator in response to the second signal, such as modifying a total capacitance of the resonator in response to the second signal, coupling to the resonator or decoupling from the resonator a fixed or variable capacitance, modifying an effective reactance of the resonator by varying or switching a varactor to a selected control voltage, or equivalently, modifying an inductance or resistance of the resonator in response to the second signal, such as by coupling to the resonator or decoupling from the resonator a fixed or variable inductance or resistance. In other embodiments, differentially weighted or sized reactances, such as variable capacitors (varactors), may be switched to or from the resonator, switched to or from a plurality of different, selectable control voltages, or both. For example, in selected embodiments, the reactance of one or more variable capacitors which are coupled to the resonator may be varied by switching the one or more variable capacitors to a selected control voltage, or a plurality of control voltages, resulting in differentially or differentially-weighted effective reactances coupled to the resonator.

For example, a plurality of fixed capacitances (having different, binary weighted or otherwise differentially-weighted capacitances), may be coupled to the resonator to provide a discrete level of frequency control, and a varactor coupled to the resonator may be provided with a selected control voltage, or a plurality of control voltages, which varies in response to temperature, which may be utilized to maintain a constant frequency over such temperature fluctuations, and which provides a continuous level of frequency control. In addition, any of such control voltages may either vary in response to a selected parameter, such as temperature, or may be constant with respect to such a parameter. The differing weights of the various reactances utilized may be embodied in a plurality of forms, such as binary weighted, linearly weighted, or weighted utilizing any other desirable scheme, all of which are considered equivalent and within the scope of the present invention.

It should be noted that the terms “fixed” and “variable” are utilized as known in the art, with “fixed” being understood to mean configured generally to be non-varying with respect to a selected parameter, and “variable” meaning configured generally to be varying with respect to the selected parameter. For example, a fixed capacitor generally means that its capacitance does not vary as a function of an applied voltage, while a variable capacitor (varactor) will have a capacitance which does vary as a function of applied voltage. Both, however, may have and generally will have capacitances which vary as a function of fabrication process variation. In addition, a fixed capacitor may be formed as a varactor coupled to a constant voltage, for example. Similarly, components may be coupled to each other either directly or indirectly or, stated another way, operatively coupled or coupled via signal transmission. For example, one component may be coupled to a second component via a third component, such as through a switching arrangement, a divider, a multiplier, etc. Those of skill in the art will recognize these various circumstances and contexts, as illustrated and as discussed below, and what is meant when such terms are utilized.

In the exemplary embodiments, the frequency controller may further comprise: a coefficient register adapted to store a first plurality of coefficients; and a first array having a plurality of switchable capacitive modules coupled to the coefficient register and coupleable to the resonator, each switchable capacitive module having a fixed capacitance and a variable capacitance, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch between the fixed capacitance and the variable capacitance and to switch each variable capacitance to a
control voltage. The plurality of switchable capacitive modules may be binary-weighted. The frequency controller may further comprise a second array having a plurality of switchable resistive modules coupled to the coefficient register and further having a capacitive module, the capacitive module and the plurality of switchable resistive modules further coupled to a node to provide the control voltage, with each switchable resistive module responsive to a corresponding coefficient of a second plurality of coefficients stored in the coefficient register to switch the switchable resistive module to the control voltage node. In selected embodiments, the sensor further comprises a current source responsive to temperature, wherein the current source is coupled through a current mirror to the second array to generate the control voltage across at least one switchable resistive module of the plurality of switchable resistive modules. Also in selected embodiments, the current source has at least one complementary to absolute temperature (“CTAT”) configuration, proportional to absolute temperature (“PTAT”) configuration, proportional to absolute temperature squared (“PTAT²”) configuration, or combinations of these configurations. In addition, each switchable resistive module of the plurality of switchable resistive modules has a different temperature response for a selected current.

In other exemplary embodiments, the sensor is a parameter (temperature, process, voltage, age, etc.) sensor and varies the second signal in response to variation of the selected parameter; for example, the sensor may be a temperature or voltage sensor and varies the second signal in response to temperature or voltage variation. The selected embodiments may also include an analog-to-digital converter coupled to the sensor to provide a digital output signal in response to the second signal, and a control logic block to convert the digital output signal to the first plurality of coefficients.

In other exemplary embodiments, the frequency controller further comprises a process variation compensator coupled to the resonator and adapted to modify the resonant frequency in response to a fabrication process parameter of the plurality of parameters. The process variation compensator may further comprise a coefficient register adapted to store a plurality of coefficients; and an array having a plurality of binary-weighted switchable capacitive modules coupled to the coefficient register and to the resonator, each switchable capacitive module having a first fixed capacitance and a second fixed capacitance, with each switchable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between the first fixed capacitance and the second fixed capacitance. In other exemplary embodiments, the process variation compensator may further comprise a coefficient register adapted to store a plurality of coefficients; and an array having a plurality of switchable variable capacitive modules coupled to the coefficient register and to the resonator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between a first voltage and a second voltage, such as switching to a selected control voltage.

In other exemplary embodiments, frequency controller further comprises a coefficient register adapted to store a first plurality of coefficients; and a first array having a plurality of switchable, capacitive modules coupled to the coefficient register and couplable to the resonator, each switchable capacitive module having a variable capacitance, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch the variable capacitance to a selected control voltage of a plurality of control voltages. In other exemplary embodiments, the process variation compensator may further comprise a coefficient register adapted to store at least one coefficient; and at least one switchable variable capacitive module coupled to the coefficient register and to the resonator, which is responsive to the at least one coefficient to switch to a selected control voltage. The sensor may comprises a current source responsive to temperature, and the frequency controller may also include a second array having a plurality of resistive modules coupled through a current mirror to the current source, the plurality of resistive modules adapted to provide the plurality of control voltages, and wherein each resistive module of the plurality of resistive modules has a different response to temperature and is adapted to provide a corresponding control voltage, of the plurality of control voltages, in response to a current from the current source.

In other exemplary embodiments, an apparatus for frequency control of a resonator comprises a coefficient register adapted to store a first plurality of coefficients; and a first array having a plurality of switchable reactance or impedance modules coupled to the coefficient register and to the resonator, each switchable reactance module responsive to a corresponding coefficient of the plurality of coefficients to switch a corresponding reactance to modify the resonant frequency. The corresponding reactance or impedance may be a fixed or variable inductance, a fixed or variable capacitance, a fixed or variable resistance, or any combination thereof. The corresponding reactance may be switched to the resonator or, when coupled to the resonator, may be switched to a control voltage, a power supply voltage or a ground potential, and the control voltage may be determined by a current source responsive to temperature. For example, the corresponding reactance is variable and is coupled to the resonator and switched to a selected control voltage of a plurality of control voltages. In selected embodiments, the first plurality of coefficients are calibrated or are determined by a sensor responsive to at least one parameter of a plurality of variable parameters, such as temperature, fabrication process, voltage, frequency and age.

In other exemplary embodiments, an apparatus for frequency control of an integrated, free-running harmonic oscillator comprises: a plurality of resistive modules adapted to generate a plurality of control voltages; a plurality of controlled reactance modules coupled to the harmonic oscillator; and a plurality of switches coupled to the plurality of resistive modules and to the plurality of controlled reactance modules, with the plurality of switches responsive to a control signal to couple a first control voltage of the plurality of control voltages to a first controlled reactance module of the plurality of controlled reactance modules to modify a resonant frequency of the harmonic oscillator.

As illustrated above, the apparatus may also include a current source coupled to the plurality of resistive modules, with the current source adapted to provide a parameter-dependent current to at least one resistive module of the plurality of resistive modules to generate at least one control voltage, of the plurality of control voltages, which is parameter-dependent. In other embodiments, the current source is adapted to provide a substantially parameter-independent current to at least one resistive module of the plurality of resistive modules to generate at least one control voltage, of the plurality of control voltages, which is substantially parameter-independent. Depending upon the exemplary embodiment, each switchable resistive module of the plurality of switchable resistive modules may have a different temperature response for a selected current. As a consequence, when the parameter is temperature, at least one control voltage of the plurality of control voltages is temperature-depend-
dent and at least one control voltage of the plurality of control voltages is substantially temperature-independent.

The exemplary apparatus may also comprise a coefficient register coupled to the plurality of switches and adapted to store a first plurality of coefficients, wherein the control signal is provided by at least one coefficient of the first plurality of coefficients. The plurality of controlled reactance modules may further comprise a plurality of differentially weighted fixed capacitances and variable capacitances, and wherein the plurality of switches are responsive to the first plurality of coefficients to couple a fixed capacitance to the harmonic oscillator and to couple a first control voltage of the plurality of control voltages to a variable capacitance coupled to the harmonic oscillator. The plurality of resistive modules may further comprise a plurality of switchable resistive modules coupled to the coefficient register and a capacitive module, the capacitive module and the plurality of switchable resistive modules further coupled to a node to provide the first control voltage, with each switchable resistive module responsive to a corresponding coefficient of a second plurality of coefficients stored in the coefficient register to switch the switchable resistive module to the control voltage node.

In exemplary embodiments, an analog-to-digital converter may be coupled to the plurality of switchable resistive modules to provide a digital output signal in response to the first control voltage, to, for example, convert a temperature-dependent current (as a sensor) to a digital form; and a control logic block to convert the digital output signal to the first plurality of coefficients or to the control signal.

Also in exemplary embodiments, the plurality of controlled reactance modules further comprise: a plurality of switchable capacitive modules coupled to the coefficient register and coupleable to the harmonic oscillator, with each switchable capacitive module having a variable capacitance, and with each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch the variable capacitance to a selected control voltage of the plurality of control voltages. Depending upon the embodiment, a current source which is responsive to a parameter of a plurality of variable parameters is coupled through a current mirror to the plurality of resistive modules; wherein each resistive module of the plurality of resistive modules has a different response to the parameter and is adapted to provide a corresponding control voltage, of the plurality of control voltages, in response to a current from the current source. Depending upon the embodiment, at least one control voltage of the plurality of control voltages is substantially parameter-dependent and at least one control voltage of the plurality of control voltages is substantially parameter-independent.

Also in exemplary embodiments, the plurality of controlled reactance modules further comprise: a plurality of differentially-weighted switchable capacitive modules coupled to the coefficient register and to the harmonic oscillator, each switchable capacitive module having a first fixed capacitance and a second fixed capacitance, each switchable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between the first fixed capacitance and the second fixed capacitance. In other embodiments, the plurality of controlled reactance modules further comprise: a plurality of switchable variable capacitive modules coupled to the coefficient register and to the harmonic oscillator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between a first voltage and a second voltage of a plurality of control voltages. And in other embodiments, the plurality of controlled reactance modules further comprise: a plurality of switchable variable capacitive modules coupled to the coefficient register and to the harmonic oscillator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch to a selected control voltage of a plurality of control voltages, the plurality of control voltages comprising a plurality of different magnitude voltages, and wherein the selected control voltage is substantially constant over temperature variations.

Also in exemplary embodiments, the apparatus may further comprise: a plurality of switchable resistors responsive to a control signal to switch a corresponding resistance to the harmonic oscillator to modify the resonant frequency. The apparatus may include a voltage divider coupled to the plurality of controlled reactance modules and adapted to provide a selected control voltage responsive to voltage variations. In addition, an age variation compensator may be coupled to the resonator and adapted to compare a current value of a selected parameter of the plurality of parameters to an initial value of the selected parameter and to modify the resonant frequency in response to a difference between the current value and the initial value of the selected parameter.

Numerous other exemplary embodiments are illustrated and described in detail below, and include additional modulators and compensators for voltage variations and age (IC lifetime) variations.

The present invention may also include a mode selector coupled to the frequency selector, wherein the mode selector is adapted to provide a plurality of operating modes, which may be selected from a group comprising a clock mode, a timing and frequency reference mode, a power conservation mode, and a pulsed (or pulse) mode.

For a reference mode, the invention may also include a synchronization circuit coupled to the mode selector; and a controlled oscillator coupled to the synchronization circuit and adapted to provide a third signal; wherein in the timing and reference mode, the mode selector is further adapted to couple the output signal to the synchronization circuit to control timing and frequency of the third signal. Such a synchronization circuit may be a delay-locked loop, a phase-locked loop, or an injection locking circuit.

These and additional embodiments are discussed in greater detail below. Numerous other advantages and features of the present invention will become readily apparent from the following detailed description of the invention and the embodiments thereof, from the claims and from the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

The objects, features and advantages of the present invention will be more readily appreciated upon reference to the following disclosure when considered in conjunction with the accompanying drawings and examples which form a portion of the specification, wherein like reference numerals are used to identify identical or similar components in the various views, in which:

FIG. 1 is a block diagram illustrating a first exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 2 is a block diagram illustrating a first exemplary apparatus embodiment in accordance with the teachings of the present invention.

FIG. 3 is a block diagram illustrating a second exemplary apparatus embodiment in accordance with the teachings of the present invention.
FIG. 4 is a high-level schematic and block diagram illustrating exemplary frequency controller, oscillator and frequency calibration embodiments in accordance with the teachings of the present invention.

FIG. 5A is an exemplary graph illustrating oscillator voltage waveform (frequency) distortion due to a harmonic content of current injected into an oscillator with a specific filter response.

FIG. 5B is an exemplary graph illustrating oscillator voltage waveform (frequency) shown in FIG. 5A as a function of temperature.

FIG. 6C is an exemplary graph illustrating oscillator frequency as a function of the transconductance of a sustaining amplifier.

FIG. 6 is a circuit diagram illustrating first exemplary negative transconductance amplifier, temperature-responsive current generator (II(T)), and LC tank oscillator embodiments in accordance with the teachings of the present invention.

FIG. 7A is a circuit diagram illustrating an exemplary temperature-responsive CTAT current generator in accordance with the teachings of the present invention.

FIG. 7B is a circuit diagram illustrating an exemplary temperature-responsive PTAT current generator in accordance with the teachings of the present invention.

FIG. 7C is a circuit diagram illustrating an exemplary temperature-responsive PTAT current generator in accordance with the teachings of the present invention.

FIG. 7D is a circuit diagram illustrating an exemplary selectable and scalable temperature-responsive current generator, with selected CTAT, PTAT, and PTAT^2 configurations, in accordance with the teachings of the present invention.

FIG. 8 is a circuit and block diagram illustrating second exemplary negative transconductance amplifier, temperature-responsive current generator (II(T)), and LC tank oscillator embodiments in accordance with the teachings of the present invention.

FIG. 9 is a circuit diagram illustrating an exemplary first controlled (or controllable) capacitance module utilized in a frequency-temperature compensation module in accordance with the teachings of the present invention.

FIG. 10 is a circuit diagram illustrating an exemplary first voltage control module utilized in a frequency-temperature compensation module in accordance with the teachings of the present invention.

FIG. 11 is a circuit diagram illustrating an exemplary first process variation compensation module in accordance with the teachings of the present invention.

FIG. 12 is a circuit diagram illustrating an exemplary second process variation compensation module in accordance with the teachings of the present invention.

FIG. 13 is a block diagram illustrating an exemplary frequency calibration module in accordance with the teachings of the present invention.

FIG. 14 is a block diagram illustrating an exemplary first frequency divider, square wave generator, asynchronous frequency selector and glitch suppression module in accordance with the teachings of the present invention.

FIG. 15 is a graphical diagram illustrating exemplary low latency frequency switching in accordance with the teachings of the present invention.

FIG. 16 is a block diagram illustrating an exemplary second frequency divider in accordance with the teachings of the present invention.

FIG. 17 is a block diagram illustrating an exemplary power mode selection module in accordance with the teachings of the present invention.

FIG. 18 is a block diagram illustrating an exemplary synchronization module for a second oscillator in accordance with the teachings of the present invention.

FIG. 19 is a flow diagram illustrating an exemplary method in accordance with the teachings of the present invention.

FIG. 20 is a block and circuit diagram illustrating an exemplary controlled impedance module utilized in a compensation module in accordance with the teachings of the present invention.

FIG. 21 is a block diagram illustrating a first exemplary frequency controller and apparatus in accordance with the teachings of the present invention.

FIG. 22 is a circuit diagram illustrating an exemplary second controlled capacitance module utilized in a frequency-temperature compensation module in accordance with the teachings of the present invention.

FIG. 23 is a circuit diagram illustrating an exemplary second voltage control module utilized in a frequency-temperature compensation module in accordance with the teachings of the present invention.

FIG. 24 is a graph illustrating exemplary frequency control in response to temperature variation in accordance with the teachings of the present invention.

FIG. 25 is a block diagram illustrating a second exemplary frequency controller and apparatus in accordance with the teachings of the present invention.

FIG. 26 is a circuit diagram illustrating an exemplary third controlled capacitance module and an exemplary third voltage control module utilized in a parameter compensation module in accordance with the teachings of the present invention.

FIG. 27 is a circuit and block diagram illustrating an exemplary voltage variation compensation module in accordance with the teachings of the present invention.

FIG. 28 is a circuit diagram illustrating an exemplary fourth voltage control module utilized in frequency and process compensation modules in accordance with the teachings of the present invention.

FIG. 29 is a circuit diagram illustrating an exemplary resistive control module in accordance with the teachings of the present invention.

FIG. 30 is a block diagram illustrating an exemplary voltage variation compensator in accordance with the teachings of the present invention.

FIG. 31 is a circuit diagram illustrating a third exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 32 is a circuit diagram illustrating a fourth exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 33 is a circuit diagram illustrating a fifth exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 34 is a circuit diagram illustrating a sixth exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 35 is a circuit diagram illustrating a seventh exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 36 is a circuit diagram illustrating an eighth exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.

FIG. 37 is a circuit diagram illustrating a ninth exemplary LC oscillator which may be utilized in accordance with the teachings of the present invention.
FIG. 38 is a block diagram illustrating an active inductor embodiment in accordance with the teachings of the present invention.

FIG. 39 is a block diagram illustrating a second exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 40 is a block diagram illustrating a third exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 41 is a block diagram illustrating a fourth exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 42 is a block diagram illustrating a fifth exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 43 is a block diagram illustrating a sixth exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 44 is a block diagram illustrating a seventh exemplary system embodiment in accordance with the teachings of the present invention.

FIG. 45 is a block diagram illustrating an exemplary first discrete apparatus embodiment in accordance with the teachings of the present invention.

FIG. 46 is a block diagram illustrating an exemplary second discrete apparatus embodiment in accordance with the teachings of the present invention.

FIG. 47 is a block diagram illustrating an exemplary third discrete apparatus embodiment in accordance with the teachings of the present invention.

FIG. 48 is a block diagram illustrating an exemplary fourth discrete apparatus embodiment in accordance with the teachings of the present invention.

DETAILED DESCRIPTION OF THE EXEMPLARY EMBODIMENTS

While the present invention is susceptible of embodiment in many different forms, there are shown in the drawings and will be described herein in detail specific examples and embodiments thereof, with the understanding that the present disclosure is to be considered as an exemplification of the principles of the invention and is not intended to limit the invention to the specific examples and embodiments illustrated.

As indicated above, the various embodiments of the invention provide numerous advantages, including the ability to integrate a highly accurate (over PVT and age), low-jitter, free-running and self-referring clock generator and/or a timing and frequency reference with other circuitry, such as illustrated in FIG. 1. FIG. 1 is a block diagram illustrating an exemplary system embodiment in accordance with the teachings of the present invention. As illustrated in FIG. 1, the system is a single integrated circuit, having a clock generator and/or timing/frequency reference of the present invention integrated monolithically with other, or second, circuitry, together with interface (I/F) or input/output (I/O) circuitry. The interface will generally provide power, such as from a power supply (not illustrated), ground, and other lines or busses to the clock generator, such as for calibration and frequency selection. As illustrated, one or more output clock signals are provided on bus 125, as a plurality of frequencies, such as a first frequency (f1), a second frequency (f2), and so on, through an (n+1)th frequency (f(n+1)). In addition, a power conservation mode (or low power mode) is provided (also on bus 125). The second circuitry (or the I/F) may also provide input into the clock generator, such as through selection signals (Sn, S1, through S(n)), and one or more calibration signals (C0, C1, through C(n)). Alternatively, the selection signals (Sn, S1, through S(n)) and one or more calibration signals (C0, C1, through C(n)) may be provided directly to the clock generator 100 through the interface 120, such as on bus 135, along with power (on line 140) and ground (on line 145).

The clock generator and/or timing/frequency reference 100, in addition to a low power mode, has additional modes discussed in greater detail below. For example, in a clock mode, the apparatus 100 will provide one or more clock signals, as output signals, to the second circuitry 180. The second circuitry 180 may be any type or kind of circuitry, such as a microprocessor, a digital signal processor (“DSP”), a radio-frequency circuit, for example, or any other circuitry which could utilize the one or more output clock signals. Also for example, in a timing or frequency reference mode, the output signal from the apparatus 100 may be a reference signal, such as a reference signal for synchronization for a second oscillator. As a consequence, the terminology clock generator and/or timing/frequency reference will be utilized interchangeably herein, with the understanding that the clock generator will also generally provide a square-wave signal, which may or may not be provided with a timing/frequency reference, which may utilize a substantially sinusoidal signal instead. In addition, as discussed in greater detail below, the various embodiments of the invention also provided a pulsed mode, in which the output signal from clock generator and/or timing/frequency reference 100 is provided in bursts or intervals, for increased instruction processing efficiency and lower power consumption, for example.

It should be noted that the various signals, voltages, parameter-independent current sources, and so on, are referred to as “substantially” sinusoidal or square-wave signals, substantially constant control voltages, or substantially parameter-independent voltages or currents, for example. This is to accommodate the various fluctuations, noise sources and other distortions introduced which may cause such signals, voltages or currents to differ in practice from the more ideal depictions found in textbooks. For example, as discussed in greater detail below, exemplary “substantially” square-wave signals are depicted in FIGS. 15A and 15B, and exhibit a variety of distortions, such as undershoots, overshoots, and other variations, and are nonetheless considered to be very high quality square-waves in practice. Several important features of the present invention are in system 150. First, a highly accurate, low-jitter, free-running and self-referring clock generator 100 is integrated monolithically with other (second) circuitry 180, to form a singular integrated circuit (system 150). This is in sharp contrast with the prior art, in which a reference oscillator is used to provide a clock signal, such as a crystal reference oscillator, which cannot be integrated with other circuitry and is off-chip, as a second and separate device which must be connected through a circuit board to any additional circuitry. For example, in accordance with the present invention, the system 150, including clock generator 100, may be fabricated with other, second circuitry using conventional CMOS (complementary metal oxide semiconductor), BJT (bipolar junction transistor), BiCMOS (bipolar and CMOS), or other fabrication technologies utilized in modern IC manufacturing.

Second, no separate reference oscillator is required. Rather, in accordance with the invention, the clock generator 100 is self-referring and free-running, such that it is not referenced to or locked to another signal, such as being synchronized in a phase-locked loop (“PLL”), delay locked loop (“DLL”), or via injection locking to a reference signal, which
is typical of the prior art. Instead, the exemplary embodiments may be utilized as such a reference oscillator which generates a frequency reference signal, which may then be locked to by one or more phase-locked or delay-locked loops, for example. Third, the clock generator 100 provides a plurality of output frequencies and a power conservation mode, such that frequencies may be switched with low latency and in a glitch-free manner. For example, second circuitry 180 may shift to a power conservation mode, such as a battery or lower frequency mode, and request (through selection signals) a lower clock frequency for minimizing power consumption, or request a low power clock signal to enter a sleep mode. As discussed in greater detail below, such frequency switching is provided with substantially negligible latency, with low latency introduced for glitch prevention (in proportion to the number of glitch prevention stages utilized), using a merely a handful of clock cycles, rather than the thousands of clock cycles required to change the output frequency from a PLL/DLL.

Additional embodiments also provide for generating a plurality of frequency reference signals, whether sinusoidal or square-wave, such as for use as one or more clock signals or reference frequency sources. In exemplary embodiments, the clock/frequency reference of the invention is coupled to one or more phase-locked loops (“PLLs”) or delay-locked loops (“DLLs”), to provide a corresponding plurality of output reference signals at selected frequencies. These exemplary embodiments are typically programmable, through control signals or stored coefficients, such as to adjust the divide ratios of the PLLs or DLLs for corresponding frequency selection.

In addition, given the significantly high available output frequencies of the clock generator and/or timing/frequency reference 100 discussed below, new operating modes are available. For example, clock start-up times are effectively or substantially negligible, allowing the clock generator and/or timing/frequency reference 100 to be repeatedly started and stopped, such as turned off entirely or to be pulsed for power conservation. For example, rather than running continuously as a clock, the clock generator and/or timing/frequency reference 100 can be operated in comparatively short, discrete intervals or bursts (i.e., pulsed), periodically or non-periodically, for instruction processing by a second circuit 180, such as a processor. As discussed in greater detail below, with the rapid start-up time, such pulsed operation provides a power savings, as more instructions (million instructions per second or MIPS) are processed per milliwatt (mW) of power consumption. In addition, such a pulsed mode may also be utilized to periodically synchronize a second clock or oscillator, in addition to other uses. As a consequence, the clock generator and/or timing/frequency reference 100 (and the other embodiments discussed below) has a plurality of operating modes, including a clock mode, a timing and/or frequency reference mode, a power conservation mode, and a pulsed mode.

Fourth, as discussed in greater detail below, the clock generator and/or timing/frequency reference 100 includes features for highly accurate frequency generation over fabrication process, voltage, temperature (“PVT”) and age variations. These features include frequency tuning and selection, and compensation for frequency variations which may be caused due to temperature and/or voltage fluctuations, fabrication process variations, and IC aging.

Fifth, the clock generator and/or timing/frequency reference 100 generates a significantly and comparatively high frequency, such as in the hundreds of MHz and GHz range, which is then divided to a plurality of lower frequencies. Each such division by “N” (a rational number, as a ratio of integers) results in a significant noise reduction, with phase noise reduced by N and phase noise power reduced by N². As a consequence, the clock generator of the present invention results in significantly less relative period jitter than available with other oscillators that generate their output directly or through frequency multiplication.

These features are illustrated in greater detail in FIG. 2, which is a block diagram illustrating a first exemplary apparatus 200 embodiment, including a frequency controller 215 in accordance with the teachings of the present invention. As illustrated in FIG. 2, the apparatus 200 is a clock generator and/or timing/frequency reference, providing one or more output signals, such as a clock or reference signal having any of a plurality of frequencies, selected using frequency selector 205. The apparatus (or clock generator) 200 includes an oscillator 210 (having a resonant element), a frequency controller 215, a frequency divider 220, a mode selector 225, and the frequency selector 205 mentioned above. In accordance with the invention, the oscillator 210 generates a signal having a comparatively high frequency, f₀. Due to PVT or age variations mentioned above, the frequency controller 215 is utilized to frequency select or tune the oscillator 210, such that the oscillation frequency f₀ is selectable from a plurality of potential oscillation frequencies, i.e., the frequency controller 215 provides for output signals having frequencies which are accurate over PVT and age variations.

For example, given these PVT variations, the output frequency from an oscillator, such as oscillator 210, may vary plus or minus 5%. For some applications, such as those utilizing ring oscillators, such frequency variability may be acceptable. In accordance with the present invention, however, greater accuracy for the clock generator 200 is desirable, particularly for more sensitive or complex applications, such as providing clock signals for integrated microprocessors, microcontrollers, digital signal processors, communication controllers, and so on. As a consequence, frequency controller 215 is utilized to adjust for these PVT variations, such that the output frequency from the oscillator is the selected or desired frequency f₀ with much less variance by several orders of magnitude, such as ±0.25% or less, and having a comparatively low-jitter.

Various exemplary embodiments of the frequency controller 215, in accordance with the teachings of the present invention, are illustrated in detail below. For example, referring to FIG. 21, which is a block diagram illustrating an exemplary frequency controller 1415 and apparatus 1400 in accordance with the teachings of the present invention, an oscillator (resonator 310 and sustaining amplifier 305) provides a first output signal having a resonant frequency f₀. The exemplary frequency controller 1415 is coupled to the oscillator and modifies the resonant frequency f₀, in response to a second signal, such as a second signal provided by one or more sensors 1440. The exemplary frequency controller 1415 comprises one of more of the following components: transconductance modulator 1420, variable parameter modulator (or controller) 1425 (such as one or more of the controlled capacitance or controlled reactance modules discussed below), process (or other parameter) modulator (or compensator) 1430, voltage compensator 1455, coefficient register(s) 1435, and potentially also an age variation compensator 1460. Depending upon the selected embodiment, the frequency controller 1415 may also include one or more sensor(s) 1440, analog-to-digital (A/D) converter (“ADC”) 1445, and control logic block 1450. For example, a temperature-dependent current source, I(T) (or, more generally, y(x)) generator 415 illustrated in FIG. 4 effectively functions as a temperature
sensor in accordance with the present invention, providing a corresponding output current which varies as a function of ambient or junction temperature. Such a temperature-dependent output current may be converted into a digital signal by an A/D converter (ADC) 1445, and utilized to provide corresponding coefficients (stored in registers 1435) utilized by the various modulators or compensators 1420, 1425, 1430, 1455 and 1460 of the frequency controller 1415, to control the resonant (or output) frequency $f_0$, in light of various parameters, such as a variable operating temperature or variable fabrication processes. In other illustrated embodiments, such a temperature-dependent output current is provided directly (as a second signal, without intervening A/D conversion) to the various modulators, such as to transconductance modulator 1420 and to variable parameter modulator (or controller) 1425. These modulators, in turn, modify the resonant frequency $f_0$, through, for example, modifying the current through the resonator 310 and sustaining amplifier 305, or modifying the effective reactance or impedance (e.g., capacitance, inductance or resistance) coupled to and effectively forming part of the resonator 310. For example, the effective reactance (or impedance) may be modified by coupling to or decoupling from the resonator 310 fixed or variable capacitances, or modifying the magnitudes of one or more reactances coupled to the resonator, such as by modifying a control voltage or other continuous control parameter.

In the various illustrated embodiments discussed below, the transconductance modulator 1420 and variable parameter modulator (or controller) 1425 are generally implemented to utilize a temperature parameter, such that a substantially stable resonant frequency $f_0$ is provided over variations in operating temperature. It will be understood by those of skill in the art that these modulators may be implemented to provide a substantially stable resonant frequency $f_0$ as a function or in response to other variable parameters, such as variations due to fabrication process, voltage variations, aging, and other frequency variations.

Referring again to FIG. 2, to improve performance and decrease jitter (noise) and other interference, instead of generating a low frequency output and multiplying it up to a higher frequency, as is typically done using PLLs and DLLs, the present invention generates a comparatively high frequency output, $f_o$, which is then divided to one or more lower frequencies ($f_i$ through $f_n$), using frequency divider 220. Clock signals having one or more of the plurality of frequencies from frequency divider 220 may then be selected, using frequency selector 205. As indicated above, such frequency selection is provided glitch-free and with low latency, providing comparably and significantly fast and glitch-free frequency switching. In addition, a plurality of operating modes are provided, using mode selector 225.

FIG. 3 is a block diagram illustrating in greater detail a second exemplary apparatus embodiment, as clock generator and/or timing/frequency reference 300, in accordance with the teachings of the present invention. Referring to FIG. 3, clock generator and/or timing/frequency reference 300 comprises a resonator 310 and a sustaining amplifier 305 (forming an oscillator 395), a temperature compensator (or modulator) 315, a process variation compensator (or modulator) 320, a frequency calibration module 325, a voltage variation compensator (or modulator) 380, an age (time) variation compensator (or modulator) 365, one or more coefficient registers 340, and depending on the selected embodiments, may also include a sensor(s) 385, an analog-to-digital converter (“ADC”) 390, frequency divider and square wave generator 330, a voltage isolator 355, a resonant frequency selector 360, an output frequency selector 335, a mode selector 345, and a low-latency start-up module 390. The sustaining amplifier 305, temperature compensator 315, process variation compensator 320, voltage variation compensator 380, age variation compensator 365, resonant frequency selector 360, and frequency calibration module 325 are often included within a frequency controller, such as frequency controller 340 (or 215 or 1415). Alternatively, the sustaining amplifier 305 and resonator 310 may be considered to comprise an oscillator 395, with one or more of the various controller elements (e.g., temperature compensator 315, process variation compensator 320, voltage isolator 355, voltage variation compensator 380, age variation compensator 365, resonant frequency selector 360, sensor(s) 385, ADC 390, and frequency calibration module 325) included within a frequency controller 340 (or 215 or 1415). It should also be noted that the square-wave generator (of 330) may not be needed in timing or frequency reference embodiments.

The resonator 310 may be any type of resonator which stores energy, such as an inductor (L) and a capacitor (C) coupled to form an LC-tank, where the LC-tank has a selected configuration of a plurality of LC-tank configurations, or is otherwise electrically or electromechanically equivalent to or otherwise typically represented in the art as an inductor coupled to a capacitor. Such an LC-resonator is illustrated as resonator 405 in FIG. 4. In addition to LC resonators, other resonators are considered equivalent and within the scope of the present invention; for example, the resonator 310 may be a ceramic resonator, a mechanical resonator (e.g., XTAL), a microelectromechanical (“MEMS”) resonator, or a film bulk acoustic resonator. In other cases, various resonators may be represented by electrical or electromechanical analogy as LC resonators, and are also within the scope of the present invention. In exemplary embodiments, an LC-tank has been utilized as a resonator, to provide for a high Q-value for a completely integrated solution.

The sustaining amplifier 305 provides for both start-up and sustaining amplification for the resonator 310. The temperature compensator 315 provides frequency control for the resonator 310, to adjust the oscillation frequency based on variations due to temperature. In selected embodiments, depending upon the degree of control desired or required, the temperature compensator 315 may include control over both current and frequency, as illustrated below for selected embodiments. For example, the temperature compensator 315 may comprise one or both of a transconductance modulator 1420 and a variable parameter modulator 1425. FIG. 21, with both modulators 1420 and 1425 embodied to be responsive to temperature fluctuations. Similarly, the process variation compensator 320 provides frequency control for the resonator 310, to adjust the oscillation frequency based on process variations inherent in semiconductor fabrication technologies, both process variations within a given foundry (e.g., batch or run variations, variations within a given wafer, and die-to-die variations within the same wafer) and process variations among different foundries and foundry processes (e.g., 130 nm and 90 nm processes). Voltage variation compensator 380 may be utilized to maintain a stable output frequency over supply voltage variations and other voltage variations. Age variation compensator 365 is utilized to maintain a stable output frequency as the IC ages, with corresponding variations in circuit elements occurring over time. Frequency calibration module 325 is utilized to fine-tune and select the desired output frequency, $f_o$, from among a plurality of oscillation frequencies which may occur in resonator 310, i.e., to select the output frequency $f_o$, from a plurality of available or potential frequencies. In selected embodiments, coefficient registers 340 are utilized to store coefficient values.
utilized in the various exemplary compensator and calibration embodiments, discussed in greater detail below.

As mentioned above, the frequency controller 349, in selected embodiments, may also include one of more sensors 385 and analog-to-digital converter (ADC) 390. In addition, many of the other compensators and modulators of the frequency controller include components which function as sensors, such as temperature-dependent current sources and other voltage variation detectors. In addition to being utilized to generate various pluralities of stored coefficients which provide control to various switching elements, to both switch controlled reactance modules (discussed below) to the resonator 310 (as a discrete form of control) and to vary the amount of effective reactance supplied by a coupled or switched reactance to the resonator 310 (a continuous form of control), the various sensors, compensators and modulators may also be utilized to provide other forms of continuous control over the resonant frequency of the resonator 310. The various continuous outputs from sensors, current generators, control voltages, etc., as illustrated and discussed below, function as control signals within the scope of the present invention. For example, the various control voltages, which may vary with a selected parameter (e.g., temperature) or which may be constant with respect to a selected parameter, function as control signals which are used to modify corresponding magnitudes of controlled capacitance modules implemented using varactors.

In addition to the temperature and process compensation, voltage isolator 355 provides isolation from variations in voltage, such as from a power supply, and may be implemented separately or as part of other components, such as part of temperature compensator 315. In addition to frequency adjustment for these PVT and age variations, the resonant frequency may also be selected independently through resonant frequency selection 360, for obtaining a selected frequency from a range of available frequencies.

For clock signal generation, clock generator 300 utilizes a frequency divider (in module 330) to convert the output oscillation frequency f0 to a plurality of lower frequencies (f1 through fN) and to convert a substantially sinusoidal oscillation signal to a substantially square wave signal for clock applications, using a square wave generator (also in module 330). Frequency selector 335 then provides for selection of one or more of the available output signals having the plurality of frequencies, and mode selector 345 may also provide for operating mode selection, such as providing a low power mode, a pulsed mode, a reference mode, and so on. Using these components, the clock generator 300 provides a plurality of highly accurate (over PVT), low jitter, and stable output frequencies f0, f1 through fN, with minimal to negligible frequency drift due to such PVT variations, thereby providing sufficient accuracy and stability for sensitive or complex applications, as mentioned above.

FIG. 4 is a high-level schematic and block diagram illustrating exemplary frequency controller, oscillator and frequency calibration embodiments in accordance with the teachings of the present invention. As illustrated in FIG. 4, the resonator is embodied as a resonant LC tank 405, and the frequency controller is embodied as several elements, a negative transconductance amplifier 410 (used to implement the sustaining amplifier), a temperature-responsive (or temperature-dependent) current generator I(T) (or, more generally, y(x), as responsive to any such parameter “x”) 415, a temperature-responsive (or temperature-dependent) frequency (f0(T)) compensation module 420, a process variation compensation module 425, and may also include a frequency calibration module 430. The various temperature-responsive or temperature-dependent modules 415 and 420 are sensitive to or responsive to temperature fluctuations, and provide corresponding adjustments, such that the resonant frequency is stable and accurate over these PVT and age variations.

The resonant LC tank 405 with a sustaining amplifier may be equally described as a harmonic oscillator or harmonic core, and all such variations are within the scope of the present invention. It should be noted that while the resonant LC tank 405 is an inductor 435 in parallel with a capacitor 440, other circuit topologies are also known and equivalent to that illustrated, such as an inductance in series with a capacitance. Another such equivalent topology is illustrated in FIG. 8. In addition, as indicated above, other types of resonators may be utilized and all are considered equivalent to the exemplary resonant LC tank illustrated herein. Moreover, as discussed in greater detail below, additional capacitances and/or inductances, both fixed and variable (and referred to more generally as impedances or reactances (or reactive elements)), are distributed in the various modules and effectively form part of the resonant LC tank 405 and are utilized as part of the frequency controller of the invention. In addition, corresponding resistances (resistive components of the various impedances) R1, 445 and R2, 450 are illustrated separately, but should be understood to be intrinsic to the inductor 435 and capacitor 440, respectively, occurring as part of fabrication, and are not additional or separate components from the respective inductor 435 and capacitor 440. Conversely, such additional or intrinsic (parasitic) resistances can also be included as part of compensation for PVT variations, as illustrated and discussed below with reference to FIG. 29.

The inductor 435 and capacitor 440 of the resonant LC tank or oscillator 405 are sized to substantially or approximately provide the selected oscillation frequency, f0, or range of oscillation frequencies around f0. In addition, inductor 435 and capacitor 440 may be sized to have or to meet IC layout area requirements, with higher frequencies requiring less area. Those of skill in the art will recognize that f0=√L/C, but only as first order approximation because, as discussed below, other factors such as the impedances R1 and R2, any additional resistors, along with temperature and process variations and other distortions, affect f0, and may be included in second and third order approximations. For example, the inductor 435 and capacitor 440 may be sized to generate a resonant frequency in the 1-5 GHz range; in other embodiments, higher or lower frequencies may be desirable, and all such frequencies are within the scope of the invention. In addition, the inductor 435 and capacitor 440 may be fabricated using any semiconductor or other circuitry process technology, and may be CMOS-compatible, bipolar-junction transistor-compatible, for example, while in other embodiments, the inductor 435 and capacitor 440 may be fabricated using silicon-on-insulator (SOI), metal-insulator-metal (MiM), polysilicon-insulator-polysilicon (PiP), GaAs, strained-silicon, semiconductor heterojunction technologies, or MEMS-based (microelectromechanical) technologies, also for example and without limitation. It should be understood that all such implementations and embodiments are within the scope of the invention. In addition, other resonator and/or oscillator embodiments, in addition to or instead of the resonant LC tank 405, may also be utilized and also within the scope of the present invention. As used herein, “LC tank” will mean and refer to any and all inductor and capacitor circuit layouts, configurations or topologies which may provide oscillation, however embodied. It should be noted that the capability of the oscillator 405 to be fabricated using a conventional process, such as CMOS technology, allows the clock generator to be fabricated integrally and monolithically
with other circuitry, such as the second circuitry 180, and provides a distinct advantage of the present invention.

In addition, the capacitance 440 illustrated in FIG. 4 is only a portion of the overall capacitance involved in the resonance and frequency determination of the resonant LC tank 405, and is a fixed capacitance. In selected embodiments, this fixed capacitance may represent approximately 10% to 90% of the total capacitance ultimately utilized in the oscillator, as an example. Alternatively, the capacitance 440 may also be implemented as a variable capacitance, if desired. As discussed in greater detail below, the overall capacitance is distributed, such that additional fixed and variable capacitance is selectively included within the clock generator and/or timing/frequency reference 300, and is provided, for example, by components of the frequency controller (215, 1415), such as temperature-responsive frequency (f(T)) compensation module 420 and process variation compensation module 425, to provide for both selecting the resonant frequency f0 and to allow the resonant frequency f0 to be substantially independent of both temperature and process variations.

In the selected embodiments, the inductance 435 has been fixed, but also could be implemented in a variable manner, or as a combination of fixed and variable inductances. As a consequence, those of skill in the art will recognize that the detailed discussions of fixed and variable capacitance, for both frequency tuning and temperature and process independence, pertain similarly to inductance choices. For example, different inductances could be switched in or out of the oscillator, to similarly provide tuning. In addition, a single inductor's inductance may also be modulated. As a consequence, all such inductance and capacitance variations are within the scope of the present invention, and are illustrated as switchable, variable and/or fixed reactive elements or components of the exemplary controlled impedance modules 1305 of FIG. 20 and the controlled reactance modules 1805 of FIGS. 25-27.

Also as illustrated in FIG. 4, the resonant LC tank 405 and resulting output signal, referred to as a first (output) signal at nodes or lines 470 and 475, is a differential signal and provides common-mode rejection. Other configurations, including non-differential or other single-ended configurations are also within the scope of the present invention. For example, in single-ended configurations, only one instantiation of the various modules (e.g., 485, 460) would be required, rather than the use of two for a balanced configuration as illustrated. Similarly, other components and features discussed below, such as frequency dividers, would also have a single-ended rather than differential configuration. Such additional exemplary I.C. oscillators, both differential and single-ended, are discussed below with reference to FIGS. 31-37, in addition to the differential I.C. oscillators illustrated in FIGS. 6 and 8. In addition, various embodiments illustrated utilize MOSFET transistors (metal oxide semiconductor field effect transistors) in various forms (such as CMOS, accumulation-mode MOSFET (“AMOS”), inversion-mode MOSFET (“IMOS”), and so on); other implementations are also available, such as using bipolar junction transistors (“BJTs”), BiCMOS, etc. All such embodiments are considered equivalent and are within the scope of the present invention.

The negative transconductance amplifier 410 is selected to provide temperature compensation through transconductance (g_m) modulation and the on-resistance of its resistors. Transconductance (g_m) modulation may also be utilized independently in frequency selection. Another significant advantage of the present invention is the selection of a negative transconductance amplifier 410 to provide start-up and sustaining amplification, because both oscillation amplitude and frequency are affected by the transconductance of the sustaining amplifier, providing both amplitude modulation and frequency trimming (or tuning), in addition to providing temperature compensation. The negative transconductance amplifier 410 will inject current into the resonant LC tank 405 (and specifically onto the capacitor 440) in response to a voltage "v" across the resonant LC tank 405, as illustrated (across nodes 470 and 475). That current injection, in turn, will change (and distort) the voltage waveform (as voltage is the integral of the current), resulting in a change in or variation in frequency, generally in inverse proportion to the magnitude of the transconductance, g_m, as illustrated in FIG. 5A. It should be noted that this transconductance is a negative value, as gain is provided to cancel the loss intrinsic to the resonant element. As a consequence, whenever "transconductance amplifier" is utilized herein, it should be understood to mean and to be merely an abbreviation for "negative transconductance amplifier". In turn, the transconductance is also a function of the bias current, substantially proportional (approximately) to the square root of the current (I(T)) through the amplifier 410 (for MOSFETs), and substantially proportional (approximately) to the current (I(T)) through the amplifier 410 (for BJTs), which is temperature-dependent, resulting in a wave form distortion which is both temperature and bias current dependent, as illustrated in FIG. 5B. In addition, as illustrated in FIG. 5C, the oscillation frequency is also related to and a function of the transconductance of the sustaining negative transconductance amplifier 410, providing for oscillation frequency selection. Moreover, in addition to temperature dependence (as I(T)), the current can also vary as a function of other parameters or variables (so is referred to more generally as current I(x)), such as voltage or external tuning, and may also be amplified such as by a factor of "y" (as illustrated below); as a consequence, the current is referred to as "y*I(x)".

As indicated above, more generally, such a variable current y*I(x) may be utilized as or as a part of a sensor, such as one or more sensors 1440 or transconductance modulator 1420 of FIG. 21 or sensors 1815 of FIG. 25. For example, when such as variable current is provided by I(T) generator 415, such that the current provided is a function of temperature (parameter or variable "T" of temperature parameter "T"), I(T) generator 415 thereby functions as a temperature sensor, and may be utilized as such in the exemplary embodiments, such as utilized by the frequency controller (215, 349, 1415) to adjust the resonant frequency f0 in response to temperature fluctuations. For example, transconductance modulator 1420 of FIG. 21 may comprise such a temperature (or other parameter) responsive current source 415 (which also functions as a sensor 1440), providing current to a sustaining amplifier 305. Significant inventive breakthroughs of the present invention include utilizing those potential distortions advantageously, to provide for frequency compensation in generating the selected I(T) value of the oscillator, and frequency modulation through modulation of the transconductance of the sustaining amplifier. As a consequence, and as discussed in greater detail below, the transconductance, first, may be modified or varied for frequency selection, and second, to compensate for such frequency variation due to temperature, voltage, fabrication process or aging, by modifying the current y*I(x), generally on a real-time or near real-time basis. The selected frequency f0 and its stability with respect to temperature variations, in accordance with the invention, may be determined through appropriate selection of the transconductance g_m and selection of I(T). Stated another way, in accordance with the present invention, the bias current is made temperature dependent, as I(T) (or, more generally, as
y(x)), which in turn affects the transconductance $g_m$, which in turn affects the oscillation frequency $f_o$. This methodology may also be utilized for other variables, such as voltage fluctuations, process variation, or aging variation.

FIG. 6 is a circuit diagram illustrating exemplary negative transconductance amplifier (410), temperature-responsive current generator (I(T) 415), and LC tank resonator (405) embodiments in accordance with the teachings of the present invention. As illustrated in FIG. 6, a resonant LC tank 500 is coupled to a negative transconductance amplifier implemented as a complementary cross-coupled pair amplifier 505 (comprised of transistors M1, M2, M3 and M4) in turn, is coupled through a voltage isolator 510 (implemented as a current mirror (transistors 525A and 525B) and referred to interchangeably herein) to a temperature-responsive current generator (I(T)) 515. The current mirror 510 (voltage isolator) may also be implemented in a cascode topology (520A and 520B), such as to provide improved stability with variations in power supply and isolate the oscillator from the power supply (voltage isolation). The temperature-responsive current generator 515 may be implemented utilizing topologies such as CTAT (complementary to absolute temperature), PTAT (proportional to absolute temperature), or PTAT2 (proportional to absolute temperature squared), as illustrated in FIGS. 7A, 7B, and 7C, respectively, and combinations of CTAT, PTAT, and PTAT2, as illustrated in FIG. 7D. In each case, the current I(T) (or y(x)) injected into the negative transconductance amplifier (complementary cross-coupled pair amplifier) 505 has a temperature dependence, such as increasing current (PTAT and PTAT2) or decreasing current (CTAT) as a function of increasing temperature, as illustrated. One or more combinations of these temperature-responsive current generators may also be implemented, as illustrated in FIG. 7D, such as CTAT in parallel with PTAT, for example.

The selection of a particular temperature-responsive or temperature-dependent current generator is also a function of the fabrication process utilized; for example, CTAT may be utilized for a Taiwan Semiconductor (TSMC) fabrication process. More generally, as different fabricators utilize different materials, such as aluminum or copper, $R_t$ typically varies, resulting in different temperature coefficients which, in turn, change the temperature coefficient of the oscillator, thereby requiring differences in (I(T)) compensation. Correspondingly, different ratios of CTAT, PTAT, and PTAT2 compensation may be required to provide an effectively flat frequency response as a function of temperature. Not separately illustrated, the various temperature-responsive current generators illustrated in FIGS. 7A, 7B, 7C, and 7D may include a start-up circuit. In addition, the transistors comprising the selected temperature-responsive current generator configuration may be biased differently, such as biased in strong inversion for CTAT (M7 and M8) and PTAT2 (M13 and M14), and in subthreshold for PTAT (M9 and M10) and PTAT2 (M11 and M12), for the exemplary topologies illustrated.

FIG. 8 is a circuit and block diagram illustrating additional exemplary negative transconductance amplifier, temperature-responsive (or temperature-dependent) current generator (I(T) or I(x)), and LC tank oscillator embodiments in accordance with the teachings of the present invention. As illustrated in FIG. 8, the resonant LC tank 500 has a different topology than previously illustrated, but also is coupled to a negative transconductance amplifier implemented as a complementary cross-coupled pair amplifier 505 (transistors M1, M2, M3 and M4) which, in turn, is coupled through a plurality of current mirrors 510 (or 520) and 530 to a temperature-responsive (or temperature-dependent) current generator (I(T)) or I(x) 515. As illustrated, the plurality of current mirrors are utilized to successively provide gain to and increase the current I(T) entering the negative transconductance amplifier 505 and resonant LC tank 550. Often, the tail device in the current mirror (e.g., transistor M6 in FIG. 6) providing current into node B and which drives the negative transconductance amplifier 505 is selected to be a PMOS device, and thus several stages of mirroring may be required (as shown) to provide a PMOS current mirror input to the $g_m$ amplifier. PMOS is often selected because in modern CMOS processes, PMOS devices are often buried channel devices which are known to exhibit less flicker noise than equally sized and similarly biased NMOS devices. Reduced flicker noise in the tail device reduces the phase noise and jitter of the oscillator because flicker noise is upconverted around the oscillation frequency by the nonlinear active devices in the circuit.

As indicated above, the portion of the current mirror 510 or 520 (or other circuitry) sourcing current into the negative transconductance amplifier 505 should have a high impedance at its output to reduce power supply frequency drift, such as by using long transistor geometries and cascode configurations to increase output impedance, and provide significant stability at node B. In addition, a shunt capacitor 570 also may be employed to filter and thereby reduce flicker noise from the various tail devices.

Depending upon the selected application, the use of the negative transconductance amplifier 505 with its I(T) (or y(x)) bias may provide sufficient frequency stability, such that the additional frequency controller components may not be necessary or desirable in that application. In other embodiments, however, additional accuracy and less frequency drift may be provided, using one or more of the components discussed in greater detail below.

In addition to providing a temperature-dependent current y(x) (or I(T)), the various transistors M1, M2, M3 and M4 each have an associated resistance during conduction, which may also tend to cause frequency distortion and frequency drift during oscillation. In each half-cycle, either M1 and M4 or M2 and M3 are on and conducting. Such resistance is also temperature dependent. As a consequence, the transistors M1, M2, M3 and M4 should be adjusted in size (width and length) to also compensate for such frequency effects. It should be noted that the current injected into the resonant LC tank 405 must be sufficient to sustain oscillation (as illustrated in FIG. 5C) and, as a consequence, will have a minimum value, which may limit the degree or capability of frequency control which can be readily implemented through the negative transconductance amplifier 410 (or 505) and temperature-dependent current generator 415 (or 515). As a consequence, I(T) and the transistor (M1, M2, M3 and M4) sizing should be jointly selected to provide for oscillation startup, to accommodate maximum currents for power consumption constraints, and to fit into the selected LC area and layout. For example, the transconductance $g_m$ may be selected to provide approximately sufficient current to ensure startup and sustain oscillation, with a frequency characteristic of decreasing frequency with increasing temperature, followed by sizing transistors M1, M2, M3 and M4 to be large enough to either make the frequency independent of temperature or increasing with increasing temperature, followed by fine-tuning the frequency-temperature relationship with appropriate selection of I(T). In selected modeled embodiments, this has resulted in frequency accuracy of approximately ±0.25% to 0.5% over PVT, which may be more than sufficient for many applications.

Referring again to FIG. 4, additional compensation modules are also utilized as part of frequency controller (215, 349,
to provide greater control and accuracy over the resonant frequency \( f_0 \), such as for applications in which greater accuracy and less variance (or frequency drift) may be required, or where technologies do not allow the previous techniques to provide sufficient accuracy over PVT or age variations, such as to provide a frequency accuracy of approximately \( \pm 0.25\% \) or better. In these circumstances, temperature-dependent (or temperature-responsive) frequency (\( f_0(T) \)) compensation module 420 may be utilized, such as the exemplary temperature-responsive frequency (\( f_0(T) \)) compensation module 420. This module 420 may be implemented, for example, utilizing controlled (or controllable) capacitance modules 485, with each coupled to a respective side or rail of the resonant LC tank 405 (lines 470 and 475), and with each under common control, provided by a first plurality (“w”) of switching coefficients (\( p_0 \) though \( p_{w(1)} \)) (register 495) and a voltage controller (\( V_{CTRL} \)) 480 providing a control voltage determined by a second plurality (“v”) of switching coefficients (\( q_0 \) though \( q_{v(1)} \)) (register 455), with representative examples illustrated in FIGS. 9 and 10. (The terms “controlled” and “controllable” are utilized interchangeably herein). Additional exemplary embodiments are illustrated in FIG. 20, which illustrates an exemplary controlled impedance module 1300 utilized in a frequency-temperature compensation module, such as in place of or in addition to controlled (or controllable) capacitance modules 485 in module 420; in FIG. 22, which illustrates another variation of controlled capacitance modules 485, as controlled capacitance modules 1500 with a plurality of temperature-dependent or other parameter-dependent control voltages (generated as illustrated FIG. 23 or 26); in FIG. 25, which illustrates a plurality of controlled reactance modules 1805 which are switched in or out (coupled to or uncoupled from the resonator) in response to control signals from control logic 1810 and sensor(s) 1815, including feedback from the oscillator; in FIG. 26, which illustrates a plurality of controlled reactance modules 1805 which are switched in or out and/or switched to a control voltage, in response to control signals (continuous) or coefficients (discrete); and in FIG. 27, which illustrates a plurality of controlled reactance modules 1805 which are switched in response to control signals, for voltage variation compensation. There are several different types of switching available, such as coupling or uncoupling a reactance or impedance to the resonator, or switching coupled reactances or impedances to selected control voltages or other control signals, for example.

FIG. 9 is a circuit diagram illustrating an exemplary first controllable capacitance module 635 in accordance with the teachings of the present invention, which may be utilized as the controlled (or controllable) capacitance modules 485 in the frequency-temperature compensation module 420 (and attached to each side of the resonant LC tank 405 (nodes or lines 470 and 475)). As illustrated, the controlled (or controllable) capacitance module 635 is comprised of a bank or array of a plurality (w) of switchable capacitive modules 640 of binary-weighted fixed capacitors (\( C_2 \)) 620 and binary- or other differentially-weighted variable capacitors (varactors) (\( C_v \)) 615. Any type of fixed capacitors 620 and variable capacitors (varactors) 615 may be utilized; in selected embodiments, the varactors 615 are AMOS (accumulation-mode MOSFET), IMOS (inversion-mode MOSFET), and/or junction/diode varactors. Each switchable capacitive module 640 has an identical circuit layout, and each differs by a binary weighted capacitance, with switchable capacitive module 640, having a capacitance of one unit, switchable capacitive module 640, having a capacitance of two units, and so on, with switchable capacitive module 640, having a capacitance of \( 2^{(w-1)} \) units, with each unit representing a particular capacitance magnitude or value (typically in femtofarads (fF) or picofarads (pF)). As mentioned above, other differential weighting schemes are equally applicable, such as linear or binary, and may also consist of providing such differential weighting by switching the reactance to a selected control voltage, thereby increasing or decreasing its effective reactance.

Within each switchable module 640, each fixed and variable capacitance is initially equal, with the variable capacitance allowed to vary in response to the control voltage provided at node 625. This control voltage, in turn, varies with temperature or another selected variable parameter, resulting in an overall or total capacitance provided by the controlled capacitance module 635 also varying as a function of temperature (or other parameter) and which, in turn, is utilized to vary the resonant frequency \( f_0 \). In other selected embodiments, any of a plurality of control voltages may be utilized, including static control voltages, to provide for other types of compensation, discussed below. Also within each switchable capacitive module 640, either the fixed capacitance \( C_f \) or the variable capacitance \( C_v \) is switched into the circuit, not both, using switching coefficients \( p_0 \) though \( p_{w(1)} \). For example, in the selected embodiment, for a given or selected module 640, when its corresponding “p” coefficient is a logic high (or high voltage), the corresponding fixed capacitance \( C_f \) is switched into the circuit and the corresponding variable capacitance \( C_v \) is switched out of the circuit (and coupled to a power rail voltage \( V_{DD} \) or ground (GND), depending whether the device is AMOS or IMOS, respectively, to avoid a floating node and to minimize the capacitance presented to the tank), and when its corresponding “p” coefficient is a logic low (or low voltage), the corresponding fixed capacitance \( C_f \) is switched out of the circuit and the corresponding variable capacitance \( C_v \) is switched into the circuit and coupled to the control voltage provided at node 625.

In an exemplary embodiment, a total of eight switchable capacitive modules 640 (and corresponding first plurality of eight switching coefficients \( p_0 \) through \( P_7 \)) have been implemented to provide 256 combinations of fixed and variable capacitances. As a result, significant control over oscillation frequency as a function of temperature variations is provided.

It should be noted, in this exemplary embodiment, by switching in or out the fixed capacitance \( C_f \) or the variable capacitance \( C_v \), the ratio of fixed to variable changes and, correspondingly, the amount or degree of temperature-responsiveness of the controllable capacitance module 635. For example, with increasing amounts of variable capacitance \( C_v \), the controllable capacitance module 635 provides greater variability of capacitance in response to temperature (or other parameter), thereby adjusting the frequency response of the tank or other oscillator.

FIG. 10 is a circuit diagram illustrating an exemplary temperature-dependent voltage control module 650 utilized to provide control voltage in the controllable capacitance module 635 (of the temperature-temperature compensation module 420) and as \( V_{CTRL} \) 480 (in FIG. 4), in accordance with the teachings of the present invention. As illustrated, voltage control module 650 creates a temperature-dependent current \( I(T) \) or more generally, a current \( I(x) \), using current generator 655, as previously discussed, using one or more combinations of PTAT, PTAT \(^2\) and/or CTAT current generators, and may share the \( I(T) \) generator 415 utilized with the negative transconductance amplifier 410, instead of providing a separate generator 655. The temperature-dependent current \( I(T) \) (or \( I(x) \)) is mirrored through current mirror 670 to an array or bank of a plurality of switchable resistive modules or
branches 675 and a fixed capacitive module or branch 680, all configured in parallel. In other exemplary embodiments, depending upon the parameter variation to be compensated, other control voltage generators discussed below may be utilized.

In other combinations, depending upon the selection and weighting of the PTAT, PTAT2 and/or CTAT current generators, a temperature-independent current may also be generated. For example, a PTAT generator and a CTAT generator, sized to have equal magnitudes and opposite slopes, can be combined to create a current generator which provides a constant current over temperature fluctuations. Such a current generator, for example, can be utilized to provide a constant current source in the aging variability compensator illustrated in FIG. 30. Those of skill in the art will recognize that other current sources may also be utilized, such as those which vary with power supply voltage, and may be utilized as corresponding voltage sensors.

The resistors 685 may be any type or combination of different types, such as diffusion resistors (p or n), polysilicon, metal resistors, salicide or unsalicide polysilicon resistors, or well resistors (p or n well), for example. Depending upon the type or combination of types of resistors selected, the resistors 685 generally will also have a corresponding temperature dependence (or responsiveness), providing a corresponding voltage variation across the selected resistor 685 as a function of temperature for a given current through the selected resistor 685. For example, a diffusion resistor will generally have a high temperature coefficient (providing more voltage variation with temperature), while a polysilicon resistor will generally have a low temperature coefficient (providing less voltage variation with temperature), while a mix of a plurality of these different resistor types in series for a selected module 675 will provide a corresponding response in between these high and low response levels. Alternatively, the resistors 685 may be sized or weighted to provide different voltage levels as a function of a given current, such as a temperature-dependent current (e.g., I(T)), thereby providing a corresponding voltage variation as a function of temperature for such a temperature-varying current.

Each switchable resistive module 675 is switched in or out of the voltage control module 650 by a corresponding "Q" coefficient of a second plurality ("x") of switching coefficients 901, 902, ..., 90n. When switchable resistive module 675 is switched into the circuit (such as when its corresponding coefficient is a logic high or high voltage), the resulting voltage across its corresponding resistor 685 is also temperature-dependent, due to the temperature-dependent current I(T). In a selected embodiment, three switchable resistive modules 675 were utilized, providing 8 branch combinations. As a result, the control voltage provided to node 625 is also a function of temperature (or other parameter), thereby providing a temperature or other parameter dependence sensitivity to the variable capacitors 615 in controllable capacitance module 635. Other resistive modules which are more generally parameter-dependent, or which are temperature-independent, are discussed below with reference to FIGS. 23 and 26, and FIG. 28, respectively.

The first plurality of switching coefficients 901, 902, ..., 90n may be determined post-fabrication by testing a representative IC having the clock generator of the present invention. Once a resonant frequency f0 has been selected and/or calibrated for a given fabrication process (discussed below with reference to FIGS. 11 and 12), the temperature (or other parameter) responsiveness of the oscillator is determined and adjusted, to provide a substantially constant selected resonant frequency f0 for such variation in ambient or operating temperature (or other variable parameter). In the exemplary embodiments, the first plurality of switching coefficients 901, 902, ..., 90n are determined first, by testing various combinations of coefficients, to provide a coarse level of adjustment, resulting in a substantially or mostly flat frequency response as a function of varying ambient temperature. As illustrated in FIG. 24, more or less fixed capacitance Cx or variable capacitance Cy is switched into or out of the oscillator.

For example, when the uncompensated frequency response of the oscillator to temperature variation is represented by lines 1705 or 1710, additional variable capacitance Cy may be switched in, providing a coarse adjustment for the frequency response of the oscillator to approximately line 1715. Conversely, also for example, when the uncompensated frequency response of the oscillator to temperature variation is represented by lines 1725 or 1730, additional fixed capacitance Cx may be switched in, providing a coarse adjustment for the frequency response of the oscillator to approximately line 1720.

The second plurality of switching coefficients 902, though 90n, are then determined, also by testing various combinations of coefficients, to provide a finer level of adjustment, resulting in a substantially and significantly flat frequency response as a function of varying ambient temperature, illustrated in FIG. 24 as adjusting a partially compensated frequency response (lines 1715 or 1720) to the substantially flat response of line 1700, through selection of the temperature responsiveness of the various resistors 685. The first and second pluralities of coefficients are then loaded into respective registers 405 and 455 in all of the ICs fabricated in the selected processing run (or batch). Depending on the fabrication processing, under other circumstances, it is possible that for higher accuracy, each IC may be separately calibrated. As result, in conjunction with the temperature compensation provided by the negative transconductance amplifier 410 and I(T) generator 415, the overall frequency response of the clock generator is substantially independent of temperature fluctuations.

In other exemplary embodiments, the first plurality of switching coefficients 901, 902, ..., 90n and the second plurality of switching coefficients 902, though 90n may also be determined and varied dynamically during operation of the oscillator, such as through sensor(s) 1440 and A/D converter 1445, as illustrated in FIG. 21, or through sensor(s) 1815 and control logic (or control loop) 1810 illustrated in FIG. 25. In these alternative embodiments, the stored first and second pluralities of coefficients may be eliminated or bypassed, with corresponding voltages applied directly as control signals to the respective switching components as illustrated in FIGS. 9 and 10 (and, similarly, extended to the other pluralities of coefficients discussed below).

For example, as illustrated in FIG. 26, as discussed in greater detail below, any of a plurality of current sources 1955 may be provided in various combinations to a plurality of resistive modules, to create a plurality of control voltages responsive to a selected parameter "P", which may be switched in any combinations to each of the plurality of controlled reactance modules 1805, which may be embodied, for example, as controlled capacitance modules 1505 (FIG. 22), to control the effective reactance of the resonator. In addition, any of a plurality of constant (temperature independent) control voltages may also be created, as illustrated in FIG. 28. Moreover, other or additional types of current sources may be utilized, either to generate the control voltage or to provide sensor 385, 1440 capability, such as those which may vary with the supply voltage VDD, or which are inde-
dependent of both supply voltage, temperature, and other parameters. Any of these control voltages may be utilized to provide continuous control in real time, in addition to discrete control, over parameter variations, such as temperature variations.

As a consequence, the overall capacitance provided to the resonant LC tank 405 is distributed into a combination of fixed and variable portions, with the variable portions responsive to provide temperature compensation and, therefore, control over the resonant frequency f₀. The more variable capacitance Cᵣ, which is switched into the circuit (controlled capacitor module 635), the greater the frequency response to fluctuations in ambient temperature. As indicated above, both fixed and variable capacitors may be implemented using variable capacitors (varactors) coupled or switched, respectively, to substantially constant or variable voltages.

In addition to providing temperature compensation, it should be noted that a switched or controlled (or controllable) capacitance module 635 may also be utilized to select or tune the resonant frequency f₀. It will also be apparent to those of skill in the art that a switched or controllable capacitance module 635 may also be utilized to provide a frequency response to other parameter variations, such as fabrication process variations, frequency, and voltage fluctuations. In addition, as discussed below with reference to FIGS. 20 and 25-27, a capacitance, an inductance, a resistance, or any other reactance or impedance element may be utilized in these various exemplary embodiments, providing a controlled reactance or impedance module to provide a selected frequency response to any of a plurality of variable parameters, such as temperature, voltage, fabrication process, or frequency.

FIG. 22 is a circuit diagram illustrating an exemplary second controlled capacitor module 1500 utilized (with module 1600 of FIG. 23) (in lieu of or in addition to modules 485 and 480) in a frequency-temperature compensation module 420, or more generally, in a frequency controller 215, 349, 1415, in accordance with the teachings of the present invention. The second controlled capacitance module 1500 operates similarly to the first controlled capacitance module 635, but utilizes variable capacitances, instead of both fixed and variable, and utilizes a plurality of different control voltages, instead of a single control voltage. In addition, such variable capacitances are not coupled to or decoupled from the resonator (i.e., the variable capacitances are always coupled to the resonator), and instead are switched to different control voltages to control the frequency response as a function of a selected parameter such as temperature. Selected embodiments, moreover, may utilize as few as one module, and the differential weighting may be accomplished by switching to a selected control voltage of a plurality of control voltages.

Referring to FIG. 22, the second controlled capacitor module 1500 utilizes at least one of a plurality (“q”) of variable capacitance modules 1505, each of which contains a variable capacitance (Cᵣ) 1515ₜ through 1515ₜₚₑₙₙ, (illustrated in pairs A and B, corresponding to balanced coupling to node 475 or 470, and illustrated with binary-weighting) which are switchable (through pluralities of transistors or other switches 1520, through 1520ₜₚₑₙₙ) to a selected control voltage of a plurality of control voltages V₀, V₁(x), through Vₚₑₙₙ₋₁(x), where control voltage V₀ is substantially static (substantially non-responsive to the selected parameter “x”, such as temperature), while the remaining control voltages V₁(x) through Vₚₑₙₙ₋₁(x) are generally responsive or sensitive to the selected parameter “x”, such as temperature. As illustrated, the backplates of each corresponding pair of variable capacitances 1515 (A and B) are coupled to each other (shorted together), and then connected via a switch to a selected control voltage. Each such pair of variable capacitances 1515 is switchable, through corresponding coefficients (illustrated as a fourth plurality of coefficients d₀, d₁, . . . , dₚₑₙₙ₋₁) through h₀, h₁, . . . , hₚₑₙₙ₋₁ₚₑₙₙ such that each module 1505 may be switched separately and independently to any of the plurality of control voltages V₀, V₁(x), through Vₚₑₙₙ₋₁(x). As a consequence, these switchable modules may remain coupled to the resonator with the effective impedance (e.g., reactance) varied through switching to one or more control voltages.

FIG. 23 is a circuit diagram illustrating an exemplary second voltage control module 1600 utilized in a frequency-temperature compensation module in accordance with the teachings of the present invention. As illustrated in FIG. 23, a parameter-sensitive or reactive current source 655 (such as any of the various CTAT, PTAT, or PTAT² temperature sensitive current sources, and their combinations, previously discussed and illustrated in FIGS. 7A-7D) is provided (through one or more current mirrors (e.g., 670, 510, 520) to an array or bank of a plurality “k−1” of resistive modules 1605 (illustrated as modules 1605ₚₑₙₙ₋₁, 1605ₚₑₙₙ₋₂, . . . , 1605₂, 1605₁, 1605₀), each of which provides a separate or independent control voltage, V₀(x), V₁(x), through Vₚₑₙₙ₋₁(x) which are provided to modules 1505 (of FIG. 22). The various corresponding resistors 1620₀, 1620₁, . . . , 1620ₚₑₙₙ₋₁ₚₑₙₙ may be any of the types, sizes or weights previously discussed with reference to FIG. 10, to provide any selected voltage response to a selected parameter, such as temperature. A static control voltage, V₀, as illustrated, may be generated utilizing any voltage divider coupled between the voltage supply rail V_SUPPLY and ground, with corresponding resistance magnitudes or values 1605₀, and 1605ₚₑₙₙ₋₁, selected to provide the desired static voltage level. In addition, generation of a plurality of different static or constant (i.e., temperature independent) voltages is illustrated in FIG. 28, by combining different current sources having differently shaped currents in response to temperature (or another parameter) with different temperature-dependent resistors having complementary or opposing temperature responses, resulting in a plurality of control voltages having different magnitudes and substantially constant over temperature variations. Any of these various voltages may be utilized, as needed, as any of the various control voltages.

In the exemplary embodiments, each such control voltage of the plurality of control voltages is different, to provide a plurality of control voltages, each of which are differently responsive or shaped (i.e., provide different responses (response curves) as a function of variations in the selected parameter such as temperature), may respond to different parameters, and others which may be substantially constant with respect to a selected parameter. Depending upon the selected embodiment, the array or bank of resistive modules 1605 may be switchable (through corresponding transistors 1610 (illustrated as transistors 1610₀, 1610₁, through 1610ₚₑₙₙ₋₁ₚₑₙₙ), and thereby switched into or out of the array 1600, or may be statically included (fixed connections 1615, illustrated as dashed lines in FIG. 23) to automatically generate a predetermined number of control voltages V₀, V₁(x), through Vₚₑₙₙ₋₁(x). Depending upon the selection of resistors 1620 (and/or transistors 1610, if included), each of the various control voltages V₀, V₁(x), through Vₚₑₙₙ₋₁(x) will be different or otherwise provide a different response to the selected parameter or variable, such as a different temperature response.

Similarly, FIG. 26 is a circuit and block diagram illustrating an exemplary third voltage control module 1900 which may be utilized to provide control voltages to any of the various modules in accordance with the teachings of the
As illustrated in FIG. 26, a plurality of parameter-sensitive or responsive current sources 1955 (such as any of the various CTIA, PTAT and PTAT² temperature sensitive sources, and their combinations, previously discussed in FIGS. 7A-7D) is provided (through one or more current mirrors (e.g., 670, 510, 520)) to an array or bank of a plurality of test parameters 1895 (illustrated as modules 1905, 1905, through 1905, respectively). Each of the resistive modules 1905 provides a separate or independent control voltage, Vg(P), Vg(P), or Vg(P), through Vg(P), creating a plurality of control voltages which are responsive or independent upon the selected parameter “P”, and which are provided to control resistance modules 1805, controlled capacitance modules 1505 (of FIG. 22), or any of the other modules utilizing one or more control voltages. The various corresponding resistors 1920, 1920, through 1920, may be any of the types, sizes or types previously discussed, to provide any selected voltage response to a selected parameter. The selection of current source (or combination of current sources) and resistor size and type allows the shaping of the response of any desired control voltage to the selected parameter. In addition, any of the plurality of different static or constant (i.e., temperature independent) voltages illustrated in FIG. 28 also may be utilized, as needed, as any of the various control voltages for any of the modules discussed.

Depending upon the selected embodiment, the array or bank of resistive modules 1905 may be switchable (through corresponding transistors 1915, illustrated as transistors 1915, 1915, through 1915, respectively), and thereby switched into or out of the array, dynamically or statically, to automatically generate a plurality of control voltages Vg(P), Vg(P), or Vg(P), through Vg(P). Each of these different control voltages may then be switched (using switches 1930, such as a full cross-bar switch), in any combination, statically or dynamically, under the switching control of control signals and/or coefficients 1950, to control resistance modules 1805, which may be coupled to the resonator or which also may be switched into or out of the tank. As a consequence, any of these control voltages may be utilized to control the effective reactance of the resonator (oscillator), providing both discrete and continuous control of the resulting resonant frequency. For example, any of these parameter-dependent control voltages Vg(P), Vg(P), or Vg(P), through Vg(P), or any of the substantially parameter-independent control voltages (FIG. 28), may be provided to the controlled impedance modules 1305 or the controlled capacitance modules 1505 or 1805 to vary the effective capacitance provided to the resonator, providing frequency control over variations from any of a plurality of parameters.

Referring again to FIG. 22, when each of these different control voltages Vg(P), or Vg(P), or Vg(P), or more generally, Vg(P), Vg(P), or Vg(P), through Vg(P), and any of the substantially constant control voltages, is available switchable to the variable capacitances C, 1515 in the variable capacitance modules 1505 through the fourth plurality of coefficients d, d, . . . , d, through h, h, . . . , h, a highly flexible, fine-tuned and highly controllable frequency response to the selected parameter (such as temperature) is provided to the resonator 405, maintaining highly accurate frequency control over the resonant frequency f. For example, variable capacitances 1515, 1515, and 1515, in module 1505, may be switched to control voltage Vg(x) through parameter h, or a corresponding dynamically applied voltage, as a control signal) being set to a logical high or high voltage with the remaining parameters of the fourth plurality of parameters set to a logical low or low voltage, providing a first frequency response as a function of temperature or another selected parameter, while variable capacitances 1515, and 1515, in module 1505, may be switched to control voltage Vg(x) through parameter d, or a corresponding dynamically applied voltage, as another control signal) being set to a logic high or high voltage with the remaining d parameters of the fourth plurality of parameters set to a logic low or low voltage, providing a second frequency response as a function of temperature or another selected parameter, and so on. As discussed above, the fourth plurality of coefficients d, . . . , d, through h, h, . . . , h, also may be determined post-fabrication through testing one or more ICs, or may also be determined and varied dynamically during operation of the oscillator, such as through sensor(s) 1440 and A/D converter 1445, as illustrated in FIG. 21, or through sensor(s) 1815 and control logic (or control loop) 1810, illustrated in FIG. 25. More generally, such control through either coefficients or control signals is illustrated in FIG. 26, and can be utilized to provide either or both discrete or continuous frequency control as a function of any selected parameter, such as temperature, voltage, fabrication process, age, or frequency.

In addition, in lieu of stored coefficients for the first, second or fourth pluralities of coefficients, particularly when the corresponding values would be determined dynamically as discussed above, corresponding voltages may be directly applied to the various switches (e.g., transistors 1520 or the switching transistors of modules 640 and 650), as control signals, as mentioned above.

Referring again to FIG. 4, another compensation module is also utilized to provide greater control and accuracy over the resonant frequency f, also for applications in which greater accuracy and less variance (or frequency drift) may be required, such as to provide a frequency accuracy of approximately ±0.25% or better over PVT. In these circumstances, a process variation compensation module 425 may be utilized, to provide control over the resonant frequency f, independently of fabrication process variations, such as the exemplary modules illustrated in FIGS. 11 and 12. As indicated above, any of these various modules may include any impedance, reactance, or resistance, and be made responsive to any selected parameter, such as temperature, process variation, voltage variation, and frequency variation.

FIG. 11 is a circuit diagram illustrating an exemplary first process variation compensation module 760 in accordance with the teachings of the present invention. The first process variation compensation module 760 may be utilized as the process compensation modules 460 in FIG. 4, with each module attached to a rail or side of the resonant LC tank 405 (lines or nodes 470 and 475). In addition, each first process variation compensation module 760 is controlled by a third plurality (“y”) of switching coefficients r, through r, stored in register 465. The first process variation compensation module 760 provides an array of switchable capacitive modules having differentially-weighted (e.g., binary-weighted), first fixed capacitances 750, for adjustment and selection of the resonant frequency f, by switching in or out a plurality of fixed capacitances 750, through a corresponding plurality of switching transistors 740 (controlled by a corresponding “y” coefficient). Again, as each capacitance branch is switched in or out of the array or circuit 760, the corresponding first fixed capacitance is added or subtracted from the total capacitance available for oscillation in the resonant LC tank, thereby changing the effective reactance and modulating the resonant frequency. The third plurality of switching coefficients r, through r, is also determined post-fabrication using test ICs, generally as an iterative process with the determinations of the first and second (or fourth) pluralities of
switching coefficients. This calibration is accomplished using the frequency calibration module (325 or 430) and a reference oscillator known to have a predetermined frequency. The determined \( r \) coefficients are then stored in the corresponding registers 465 of the ICs of that production or process batch. Alternatively, each IC may be calibrated separately, for example.

In addition to such calibration methods, the third plurality of switching coefficients \( r \) though \( r_{(n-1)} \) may also be determined using other methods, discussed below, such as using various voltage and current sensors to measure parameters or variables which reflect fabrication process parameters, such as transistor threshold voltages, resistance magnitudes or values of the tank, or absolute current levels produced by the various current sources. Such measured values may then be utilized to provide corresponding coefficients (the third plurality of switching coefficients \( r \) though \( r_{(n-1)} \)) and/or control signals for corresponding frequency adjustment. For example, such measured or sensed values may be converted to digital values, which are then indexed to a lookup table in memory, which then provides stored values based on known values, or other calibrations or modeling.

To avoid additional frequency distortions, several additional features may be implemented with this first process variation compensation module 760. First, to avoid additional frequency distortion, the on resistance of the MOS transistors 740 should be small, and therefore the transistors' width/length ratio is large. Second, large capacitances may be split into two branches, with two corresponding transistors 740 controlled by the same \( \omega \) coefficient. Third, to provide for the resonant LC tank to have a similar load under all conditions, when a first fixed capacitance 750 is switched in or out of the circuit 760, a corresponding second fixed capacitance 720, as a “dummy” capacitor (having a significantly smaller capacitance or the smallest size allowed by the design rules for the fabrication process), is correspondingly switched out or into the circuit, based on the inverse of the corresponding \( \omega \) coefficient. As a consequence, approximately or substantially the same on resistance of the transistors 740 is always present, with only the amount of capacitance varied.

As an alternative to the use of the “dummy” capacitances, metal fuses or the like could be utilized instead of the transistors 740. Metal fuses would be left intact to include the corresponding fixed capacitor 750, and could be “blown” (open-circuited) to remove the corresponding fixed capacitance 750 from the resonant LC tank 405.

FIG. 12 is a circuit diagram illustrating an exemplary second process variation compensation module 860 in accordance with the teachings of the present invention. The second process variation compensation module 860 may be utilized as the process compensation modules 460 in FIG. 4, with each module attached to a rail or side (lines 470 and 475) of the resonant LC tank 405, instead of modules 760. More generally, the second process variation compensation module 860 is utilized as part of frequency controller (215, 349 or 1415), such as process (or other parameter) modulator or compensator 1430 (FIG. 21). In addition, each second process variation compensation module 760 would also be controlled by a third plurality of switching coefficients \( r \) through \( r_{(n-1)} \) stored in register 465. (Because of the different circuitry employed in each exemplary process variation compensation module 760 or 860, however, the corresponding third pluralities of switching coefficients \( r \) through \( r_{(n-1)} \) generally would, of course, be different from each other.) In addition, such switching may be controlled through use of any control signals, discussed above.

It should be noted that FIG. 12 provides a varactor illustration different from those utilized in other Figures, in which a varactor 850 is represented by a MOS transistor, rather than as a capacitor with an arrow through it. Those of skill in the art will recognize that varactors are often AMOS or IMOS transistors, or more generally MOS transistors, such as those illustrated in FIG. 12, and configured by shorting the transistor’s source and drain. As a consequence, the other illustrated varactors may be considered to include, as potential embodiments, the AMOS or IMOS transistors as configured as in FIG. 12. In addition, the varactors 850 may also be binary-weighted with respect to each other, or may use another differential weighting scheme.

The second process variation compensation module 860 has a similar structural concept, but additional notable differences from the first process variation compensation module 760. The second process variation compensation module 860 provides an array or bank of a plurality of switchable variable capacitive modules 865, without MOS switches/transistors, and hence the losses or loading through the MOS transistors are eliminated. Instead, the load appears as a low loss capacitance; such low loss also implies that the oscillator start-up power is less. In the second process variation compensation module 860, a MOS varactor 850 is switched either to \( V_{in} \), which may be any of the various pluralities of control voltages discussed above, to provide a corresponding capacitance level to the resonant LC tank 405, or may be switched to ground or the power rail (voltage \( V_{pp} \)), thereby providing either the minimum capacitance or the maximum capacitance to the resonant LC tank 405 based upon the varactor 850 geometry. For AMOS, switched to voltage \( V_{dd} \) would provide minimum capacitance and switched to ground would provide maximum capacitance, while the opposite is the case for IMOS. Again, the second process variation compensation module 860 is comprised of an array of variable capacitances, as varactors 850, for adjustment and selection of the resonant frequency \( f \), by coupling or switching a selected varactor 850 to any of a plurality of control voltages (\( V_{in} \)), to ground or \( V_{dd} \), such as switching between a first voltage and a second voltage, through a corresponding \( \omega \) coefficient or through application of a corresponding control signal. In another alternative, instead of a plurality or an array, one varactor 850 may be utilized, with its effective reactance provided to the tank controlled by a selected control voltage.

As each capacitance branch is switched to a corresponding control voltage, ground or \( V_{dd} \), the corresponding variable capacitance is added to or not included in the total capacitance available for oscillation in the resonant LC tank, thereby changing its effective reactance and modulating the resonant frequency. More particularly, for an AMOS implementation, coupling to \( V_{dd} \) (as \( V_{in} \)) provides lesser capacitance and coupling to ground (\( V_{in} = 0 \)) provides greater capacitance, with the opposite holding for an IMOS implementation, in which coupling to \( V_{dd} \) (as \( V_{in} \)) provides greater capacitance and coupling to ground (\( V_{in} = 0 \)) provides lesser capacitance, where it is assumed that the voltage on the rails of the LC tank (nodes or lines 470 and 475 of FIG. 4) is between zero \( V \) and voltage \( V_{dd} \), and significantly or substantially far from either voltage level. Coupling to voltages between \( V_{dd} \) and ground, such as many of the various control voltages, as \( V_{in} \), will provide a corresponding, intermediate level of capacitance to the tank. The third plurality of switching coefficients \( r \), though \( r_{(n-1)} \) also determined post-fabrication using test ICs, also generally as an iterative process with the determinations of the first and second pluralities of switching coefficients. The determined \( \omega \) coefficients are then stored in the corresponding registers 465 of the ICs of that production or
process batch. Again, individual ICs may also be calibrated and tested separately. In addition, any selected number of modules 850 may be controlled dynamically, to provide continuous frequency control during oscillator operation.

As indicated above, depending upon the type (AMOS or IMOS) of varactor, switching any of the variable capacitive modules 865 to \( V_{VAR} \), or ground, as first and second voltage levels, results in the corresponding maximum capacitance or no (negligible) capacitance being included as effective capacitance for the resonator (LC tank). As mentioned above, however, other capacitance levels intermediate between such maxima and minima may also be generated, by switching the variable capacitive modules 865 to a corresponding control voltage. Utilizing a plurality of control voltages having different magnitudes, results in a corresponding capacitance of the variable capacitive modules 865 being added to (or subtracted from) the LC tank, thus changing its effective reactance and modulating the resonant frequency.

FIG. 28 is a circuit diagram illustrating an exemplary fourth voltage control module 2850 utilized in frequency, process and other parameter control. Resonance modules in accordance with the teachings of the present invention. Referring to FIG. 28, a plurality of substantially constant voltage modules 2600 (illustrated as 2606, 2606, 2606, through 2606) are utilized to create a corresponding plurality of control voltages which are substantially constant with respect to a selected parameter, such as temperature, and which have a corresponding plurality of different magnitudes, creating a plurality of control voltages \( V_{A}, V_{B}, V_{C} \) through \( V_{D} \), which have different magnitudes. As illustrated, the plurality of different, substantially static or constant (i.e., temperature independent) voltages is created by combining different current sources 2055 (illustrated as current sources 2055, 2055, 2055, through 2055) each having different responses to temperature or another parameter (i.e., differently shaped currents in response to temperature or another parameter)), with a corresponding plurality of resistors 2040 (illustrated as corresponding resistors 2040, 2040, 2040, through 2040), each of which have a temperature or other parameter-dependent response which is opposing or complementary to the corresponding current source 2055 of the particular module 2600. Each corresponding current source 2055 and resistor 2040 is selected to have such opposing or complementary responses with the other, to effectively cancel the other’s response to the selected parameter. For example, a current source 2055 is selected to have a particular combination of PFA, CFA or CTA current sources of appropriate magnitude, and a resistor 2040 is selected based on size, type, and so on, such that the resulting voltage is substantially constant over the parameter variations, e.g., temperature variations. Any of these various voltages may be utilized, as needed, as any of the various control voltages, such as to provide a corresponding \( V \) or the variable capacitive modules 865 illustrated in FIG. 12, to adjust the effective capacitance (reactance) of the resonator and the resulting resonant frequency.

It should also be noted that the illustrated embodiments for modules such as temperature compensator 315 (or 410, 415 and/or 420) and process variation compensator 320 (or 425 and 460), such as those illustrated in FIGS. 6-12, may be utilized for other purposes. For example, the various illustrated embodiments for the compensator 315 (or 410, 415 and/or 420) may be made dependent upon process variation, rather than temperature. Similarly, the various illustrated embodiments for the compensator 320 (or 425 and 460) may be made dependent upon temperature, rather than process variation. As a consequence, the embodiments for these and other modules should not be considered limited to the exemplary circuits and structures illustrated, as those of skill in the art will recognize additional and equivalent circuits and applications, all of which are within the scope of the invention.

As indicated above, the various illustrated controlled capacitance modules 485, 635, 460, 750, 860, 1501 may be generically generalized to any reactance or impedance element, whether a capacitance, inductance, resistance, or combination of capacitance, inductance or resistance. An array or bank 1300 of such a plurality (“n”) of switchable, controlled impedance (or reactance) modules 1305 are illustrated in FIG. 20, and may be utilized within the frequency controller (215, 349, 1400) of the present invention, as any of the various modulators or compensators (315, 320, 355, 1420, 1425, 1430). Each differently weighted, controlled reactance or impedance module 1305 (illustrated as 1305, 1305, 1305, through 1305) is comprised of one or more fixed reactances \( Z_{1}, Z_{2}, \) variable reactances \( Z_{1}, Z_{2}, \) or “dummy” reactances \( Z_{1}, Z_{2} \), which are switchable in response to a corresponding coefficient “s” of a plurality of coefficients \( s_{1}, s_{2}, \) through \( s_{(n+1)} \). The array of controlled reactance or impedance modules 1305 generally may be implemented to operate as discussed above with respect to any of the various controlled capacitance modules, in any of the various embodiments. The plurality of coefficients may be determined post-fabrication, or dynamically, as discussed above for the other sets of coefficients. In addition, depending upon the implementation, the various reactances or impedances may be switched in or out of the array 1300 or switched to various control voltages or ground, as previously illustrated, and may be utilized to provide a selected frequency response of the oscillator in response to any of a plurality of parameters, such as temperature variations, voltage fluctuations, fabrication process, or frequency.

Similarly, referring to FIG. 25, an array or bank of a plurality “n” of switchable, controlled reactance modules 1805 are illustrated (as controlled reactance modules 1805, through 1805, \( \ldots \)), and also may be utilized within the frequency controller (215, 1415) of the present invention, as any of the various modulators or compensators (315, 320, 355, 1420, 1425, 1430). These controlled reactance modules 1805 may also be binary, linearly, or otherwise differently weighted, and switched in or out of the various circuits, switched to one or more control voltages, or any combination thereof, and may be responsive to any selected parameter. The array of controlled reactance modules 1805 generally may be implemented to operate as discussed above with respect to any of the various controlled capacitance modules, in any of the various embodiments. Rather than being switched to the oscillator through a plurality of coefficients, in this exemplary embodiment, the controlled reactance modules 1805 are switched dynamically, through voltages or currents provided directly by sensors 1815 and control logic 1810, with feedback provided (line or node 1820), which may be implemented as known in the art, or as illustrated above, with all such variations considered within the scope of the present invention. In addition, the reactance modules may be more considered more broadly, as impedance modules, with both a resistive and/or reactance aspect, such as utilizing the various resistors illustrated in FIG. 29.

For example, such variations in the selected parameter may be determined in any of a plurality of ways previously discussed, such as through a temperature-sensitive current source, other temperature sensors, or any other type of sensor which is responsive to the selected parameter. For example, a sensor may comprise a circuit across a diode, providing a voltage output responsive to temperature. Referring to FIG. 21, the output of such a sensor 1440 may be provided to A/D
converter 1445, which provides a digital output indicative of the level of the sensed parameter, which may then be utilized as the corresponding coefficients (any of the pluralities of coefficients discussed above), or utilized to dynamically switch any of the various controlled reactance or impedance modules (e.g., 1305, 1805) or the various second controlled capacitance modules. Similarly, sensor 1815 output may be provided to control logic 1810, which may also adjust the various reactances, either statically or dynamically, and with or without feedback from the resonator.

FIG. 27 is a circuit and block diagram illustrating an exemplary voltage variation compensation module 2000 in accordance with the teachings of the present invention, and may be utilized as a voltage variation compensator 380, 1455 illustrated in FIGS. 3 and 21. Referring to FIG. 27, a switchable resistive module 1650 forms a voltage divider, using resistors 1620, and 1620, providing voltage Vp. In the event of fluctuations in the supply voltage (power rail) VPP, voltage Vp is correspondingly changed. As voltage Vp can be switched (switches 1930) (as discussed above) to any of the controlled reactance modules 1805, under the control of control signals or coefficients 1950, the effective capacitance to the tank is also varied, thereby modulating the resonant frequency. As a result, the resonant frequency may be controlled over such voltage fluctuations. Other implementations will be apparent based upon the other illustrated embodiments, and are also within the scope of the invention.

As indicated above, the resonant frequency of the tank may also be modified by varying the resistance to the tank, in addition to the intrinsic or parasitic resistances R, 445 and R, 450 of FIG. 4. FIG. 29 is a circuit diagram illustrating an exemplary resistive control module 2100 which may be utilized as or as part of any of the various frequency control modules and the various frequency controllers in accordance with the teachings of the present invention. Such a resistive control module 2100 may be inserted into node Q in resonator 405 of FIG. 4, in series with inductor 435 and R, 445, or in series with capacitor 440 and R, 450, or both. Each switchable resistive module 2115 (illustrated as the plurality of switchable resistive modules 2115, 2115, 2115, through 2115,) has a differently weighted (such as a binary-weighted), resistor 2105 (illustrated as corresponding resistors 2105, 2105, 2105, through 2105,), and is switchable in or out of the array or module 2100 through corresponding transistors or switches 2110 (illustrated as transistors 2110, 2110, 2110, through 2110,) under the control of control signals and/or coefficients 1950. As indicated above, such switching also provides another mechanism to control or modulate the resonant frequency of the resonator 405, and may be a function of any selected parameter, or may be parameter independent, such as for resonant frequency selection.

FIG. 30 is a block diagram illustrating an exemplary age variation compensator 2200 in accordance with the teachings of the present invention. As illustrated in FIG. 30, various sensors are utilized to measure a relevant parameter which is or may be affected by the passage of time, or which otherwise changes over the lifetime of an IC, such as a voltage sensor 2205 to measure a threshold voltage of a transistor, a resistance sensor 2210 to measure one or more resistance magnitudes or values of the tank, and/or a current sensor to measure absolute current levels produced by the various current sources. A selected measurement, at a given point in time is provided (via multiplexer 2220) to ADC 2225, for conversion into a digital value, which is stored in a register or other non-volatile memory 2230. When the IC is first powered on or otherwise initialized, an initial measurement is stored in the register 2230, to provide a basis for comparison for subsequent measurements. Subsequently, additional measurements may be performed, with the resulting values stored as corresponding current values in register 2230, illustrated as current and initial values for voltage, resistance and current. For a given parameter, such as voltage, current and initial values may be read and compared, comparator 2235, which then provides a corresponding age compensation signal proportional to any difference between the two values. Such difference values provided by the age compensation signal may then be utilized to provide corresponding coefficients and/or control signals for corresponding frequency adjustment. For example, such age compensation signals may be indexed to a lookup table in memory 2240, which then provides stored values based on known values, or other calibrations or modeling of age affects, and provides for corresponding frequency adjustments using any of the various modulators and compensators discussed above.

As mentioned above, the clock generator and timing/frequency reference (100, 200, 300) of the present invention may utilize a wide variety of oscillators. In exemplary embodiments, resonant LC oscillators are utilized to provide an output signal, as a first reference signal, having a comparatively higher Q, lower jitter, and decreased phase noise. Exemplary first and second differential LC oscillators have been discussed above with reference to FIGS. 4, 6 and 8. Additional types of resonant oscillators are also within the scope of the present invention, and exemplary LC oscillators are illustrated in and discussed below with reference to FIGS. 31-37, with an active inductor illustrated in FIG. 38. These additional exemplary LC oscillators and inductor types (passive or active) may be utilized equivalently to the LC oscillators previously discussed, and to illustrate their equivalent operation, are also illustrated in conjunction with exemplary frequency controller components previously described and illustrated in FIG. 4, namely, compensation modules 420 and 425. It should be understood that any of the other controller reactance modules, control voltage generators, frequency control, calibration, frequency selection, frequency division, and other components may also be utilized equivalently, in addition to those specifically illustrated in FIGS. 31-37. It should also be noted that the exemplary active inductor illustrated in FIG. 38, or any other active inductor, may be substituted for any of the passive inductors illustrated in any of the topologies of any of the FIGS. 1-37. Similarly, various topologies are illustrated using n-MOS or p-MOS transistors; any types of transistors may be utilized equivalently. Accordingly, use of any passive or active inductor, or any type of transistor, is considered equivalent and within the scope of the present invention.

The various LC oscillators illustrated below may provide either a differential or a single-ended first reference signal. The various compensation modules 420 and 425, which may be implemented in a wide variety of ways as discussed above, as controlled reactance modules, may be combined with the various oscillators in a plurality of ways. First, the controlled reactance modules (illustrated as compensation modules 420 and 425) may be coupled in parallel with any of the one or more illustrated capacitors. In many instances, multiple instances of the controlled reactance modules can be coupled to the illustrated LC oscillators. Consequently, the corresponding nodes for coupling are labeled as node “A” and node “B”, to indicate the corresponding nodes for coupling to the given LC oscillator topology, with additional instances available for coupling illustrated as a corresponding node “A” (A-prime) and node “B” (B-prime) and/or corresponding node “A” (A-double-prime) and node “B” (B-double-
prime). Second, not separately illustrated in the various FIGS. 31-37, the controlled reactance modules (illustrated as compensation modules 420 and 425) may be utilized in lieu of and substitute for any of the one or more illustrated capacitors. Those of skill in the art will recognize innumerable other variations, all of which are considered equivalent and within the scope of the invention.

FIG. 31 is a circuit diagram illustrating a third exemplary LC oscillator 2260, implemented with a differential n-MOS cross-coupled topology, which may be utilized in accordance with the teachings of the present invention, and is a variation of the LC oscillator illustrated in FIG. 8. As illustrated, the apparatus 2250 comprises the third exemplary LC oscillator 2260, having a differential n-MOS cross-coupled topology, and the frequency controller and frequency calibration modules (compensation modules 420 and 425) previously discussed in the double-balanced configuration of FIG. 4. The output frequency $f_0$ is obtained between nodes 470 and 475, which are equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

The cross-coupled n-MOS transistors 2251 and 2251 are coupled through a current mirror 530A (or 530B), to a bias current, such as using the parameter-responsive current $I(x)$ generator 515 (or 415), also previously discussed or, alternatively, another fixed or variable current source. The frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) are coupled to the oscillator across nodes A and B as illustrated, and also operate as previously discussed. The inductors 2253 and 2254 (with illustrated resistances) may be replaced equivalently by the center-tap inductor 2257 (center-tap coupled to $V_{dc}$) and inserted between nodes A and B as illustrated, and may be fixed or variable. In addition, the various capacitances may be implemented to be either fixed or variable, also as previously discussed, and are illustrated with both fixed and variable capacitances. In exemplary embodiments, the resistances may also be fixed or varying.

It will be apparent to those of skill in the art that a similar cross-coupled n-MOS version of the oscillator illustrated in FIG. 6 may be implemented similarly (by removing (replacing with short-circuits) the illustrated cross-coupled n-MOS transistors M1 and M2).

FIG. 32 is a circuit diagram illustrating a fourth exemplary LC oscillator 2280, implemented with a differential n-MOS cross-coupled topology, which may be utilized in accordance with the teachings of the present invention, and is also a variation of the LC oscillator illustrated in FIG. 8. As illustrated, the apparatus 2270 comprises the fourth exemplary LC oscillator 2280, having a differential n-MOS cross-coupled topology, and the frequency controller and frequency calibration modules (compensation modules 420 and 425) previously discussed in the double-balanced configuration of FIG. 4. The output frequency $f_0$ is obtained between nodes 470 and 475, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

The cross-coupled n-MOS transistors 2271 and 2271 are coupled through a current mirror 510 (or 520) to a bias current, such as using the parameter-responsive current $I(x)$ generator 515 (or 415), also previously discussed or, alternatively, another fixed or variable current source. The frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) are coupled to the oscillator across nodes A and B as illustrated, and also operate as previously discussed. The inductors 2273 and 2274 (with illustrated resistances) may be replaced equivalently by the center-tap inductor 2277 (center-tap coupled to ground) and inserted between nodes A and B, as illustrated, and may be fixed or variable. In addition, the various capacitances may be implemented to be either fixed or variable, also as previously discussed, and are illustrated with both fixed and variable capacitances. In exemplary embodiments, the resistances may also be fixed or varying.

Also, it will be apparent to those of skill in the art that a similar cross-coupled p-MOS version of the oscillator illustrated in FIG. 6 may be implemented similarly (by removing (replacing with short-circuits) the illustrated cross-coupled n-MOS transistors M3 and M4).

FIG. 33 is a circuit diagram illustrating a fifth exemplary LC oscillator 2305, having a single-ended Colpitts configuration (or topology), which may be utilized in accordance with the teachings of the present invention. As illustrated, the apparatus 2300 comprises the third exemplary LC oscillator 2305, having a single-ended Colpitts configuration (or topology), and portions of the frequency controller and frequency calibration modules previously discussed (single-ended versions of compensation modules 420 and 425). The frequency controller and frequency calibration modules (485, 460) are coupled in parallel to either capacitor 2310 across nodes A and B as illustrated, or to capacitor 2315 across nodes A' and B' as illustrated, or both (separately in parallel to capacitor 2310 across nodes A and B and to capacitor 2315 across nodes A' and B'). The output frequency $f_0$ is obtained between nodes 470 and 475, which are equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

The transistor 2325 may be coupled to a fixed or varying bias voltage or to another circuit node (not separately illustrated). In addition, a bias current is also provided, such as using the parameter-responsive current $I(x)$ generator 515, also previously discussed or, alternatively, another fixed or variable current source. The frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) also operate as previously discussed. In addition, the various reactances (inductor 2320, capacitors 2310 and 2315) may be implemented to be either fixed or variable, also as previously discussed. In exemplary embodiments, the resistance 2330 may also be fixed or varying.

FIG. 34 is a circuit diagram illustrating a sixth exemplary LC oscillator, having a differential, common base Colpitts configuration (or topology), which may be utilized in accordance with the teachings of the present invention. As illustrated, the apparatus 2400 comprises the sixth exemplary LC oscillator 2405, having a differential, common base Colpitts configuration (or topology), and the frequency controller and frequency calibration modules previously discussed in the double-balanced configuration of FIG. 4. The output frequency $f_0$ is obtained between nodes 470 and 475, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

The transistors 2425 and 2426 may be coupled to a fixed or varying bias voltage. While illustrated using n-MOS transistors, transistors 2425 and 2426 also provide an example of equivalent use of bipolar junction transistors in the present invention. In addition, one or more bias currents are also provided, such as using the parameter-responsive current $I(x)$ generator 515, also previously discussed or, alternatively, one or more other fixed or variable current sources. The frequency controller modules (480, 485 with coefficient registers 455
and 495) and frequency calibration modules (460 with coefficient register 465) are coupled in parallel to capacitor 2415 across nodes A and B as illustrated, or in parallel to capacitor 2410 across nodes A' and B' as illustrated, or in parallel to capacitor 2430 across nodes A'' and B'' as illustrated, or in any combination of these three configurations, and also operate as previously discussed. In addition, the various reactances (inductor 2420, capacitors 2410, 2415 and 2430) may be implemented to be either fixed or variable, also as previously discussed.

FIG. 35 is a circuit diagram illustrating a seventh exemplary LC oscillator 2405, having a differential, common collector Colpitts configuration (or topology), which may be utilized in accordance with the teachings of the present invention. As illustrated, the apparatus 2400 comprises the seventh exemplary LC oscillator 2405, having a differential, common collector Colpitts configuration (or topology), and the frequency controller and frequency calibration modules previously discussed in the double-balanced configuration of FIG. 4. The output frequency f<sub>o</sub> is obtained between nodes 470<sub>c</sub> and 475<sub>c</sub>, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

One or more bias currents are provided, such as using the parameter-responsive current I<sub>x</sub>(x) generator 515, also previously discussed or, alternatively, one or more other fixed or variable current sources. The frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) are coupled in parallel to capacitor 2515 across nodes A and B as illustrated, or in parallel to capacitor 2510 across nodes A' and B' as illustrated, or in parallel to capacitor 2530 across nodes A'' and B'' as illustrated, or in any combination of these three configurations, and also operate as previously discussed. In addition, the various reactances (inductor 2520, capacitors 2510, 2515 and 2530) may be implemented to be either fixed or variable, also as previously discussed.

FIG. 36 is a circuit diagram illustrating an eighth exemplary LC oscillator 2605, having a single-ended Hartley configuration (or topology), which may be utilized in accordance with the teachings of the present invention. As illustrated, the apparatus 2600 comprises the eighth exemplary LC oscillator 2605, having a single-ended Hartley configuration (or topology), and portions of the frequency controller and frequency calibration modules previously discussed. Also because the oscillator 2605 is single-ended rather than differential, the frequency controller and frequency calibration modules (485, 460) are coupled to one rail (node 470<sub>c</sub>) only, rather than having the double-balanced configuration of FIG. 4. As illustrated, the output frequency f<sub>o</sub> is obtained between nodes 470<sub>c</sub> and 475<sub>c</sub>, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification. In addition, the frequency controller and frequency calibration modules (485, 460) are coupled to one rail (node 470<sub>c</sub>) only, rather than having the double-balanced configuration of FIG. 4. As illustrated, the output frequency f<sub>o</sub> is obtained between nodes 470<sub>c</sub> and 475<sub>c</sub>, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification. In addition, the frequency controller and frequency calibration modules (485, 460) are coupled to one rail (node 470<sub>c</sub>) only, rather than having the double-balanced configuration of FIG. 4. As illustrated, the output frequency f<sub>o</sub> is obtained between nodes 470<sub>c</sub> and 475<sub>c</sub>, which are also equivalent to the nodes 470 and 475 previously discussed, and may be substituted as such for all references in the Figures and this specification.

The oscillator 2705 includes an inductive load 2720 which may be, for example, an inductor or an inductor in parallel with a capacitor (presenting an overall inductance), and may be implemented to be either fixed or variable, also as previously discussed. The inductive load 2705 is in parallel with an inverter 2725 and resistance 2730. The frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) and also operate as previously discussed. In addition, the various capacitances 2710 and 2715 may be implemented to be either fixed or variable, also as previously discussed. In exemplary embodiments, the resistance 2730 may also be fixed or varying.

It should be noted that any of the various LC oscillator topologies may be implemented to provide a quadrametric configuration (or topology), which may be utilized with the frequency compensation (for temperature, process variation, and other parameter variation) in accordance with the teachings of the present invention. For example, two LC oscillators may be cross-coupled with each other (and appropriately configured with the frequency controller modules (480, 485 with coefficient registers 455 and 495) and frequency calibration modules (460 with coefficient register 465) to provide a plurality of first reference signals having 90° phase relationships (at 0°, 90°, 180° and/or 270°).

FIG. 38 is a circuit diagram illustrating an exemplary active inductor 2910 configuration, which may be utilized in accordance with the teachings of the present invention. While the active inductor 2910 is illustrated using bipolar junction transistors, an equivalent circuit may be obtained using any type
of CMOS transistors. An active inductor 2910 may be utilized for any of the inductors or inductive loads of any of the LC oscillators described herein or their equivalents, and may provide a savings in IC area. The illustrated active inductor 2910 would generally be coupled to the other portions of an oscillator at node D. A bias current is also provided, such as using the parameter-responsive current I(x) generator 515, also previously discussed or, alternatively, another fixed or variable current source. In addition, the active inductor 2910 is illustrated as an example and without limitation—other active inductor circuits may also be utilized equivalently, including with other types of transistors and circuit configurations.

Those of skill in the art will recognize that innumerable variations are available for the various exemplary LC oscillator embodiments illustrated above. For example, the various amplifiers may be implemented in a wide variety of ways, such as with p channel transistors only, n channel transistors only, or a combination of both p and n channel transistors as illustrated. In addition, the various amplifiers and current mirrors may have various circuit locations and configurations with respect to the various resonators. Singular or multiple inductor or capacitor variations may be utilized equivalently. The various topologies may be symmetrical or asymmetrical, complementary or non-complementary, or cross-coupled or non-cross-coupled, for example. All such variations are considered equivalent and within the scope of the present invention.

Referring again to FIG. 21, the frequency controller 215, 349, 1415 of the present invention may comprise one or more of the following: (1) a transconductance modulator 1410 (e.g., 410, 415 and the embodiments illustrated in FIGS. 6-8), which in the exemplary embodiments, may also include or be coupled to sustaining amplifier 305; (2) a variable parameter modulator 1425 to modulate the resonant frequency f1 in response to any selected parameter, such as temperature, fabrication process variation, voltage variation, or frequency, such as the various controlled capacitance modules 485, 635, 1505 or controlled reactance modules 1305, 1805; (3) a process (or other parameter) modulator or compensator 1430, such as process variation compensator 425, 760, 860, or controlled reactance modules 1305, 1805; (4) a voltage variation compensator 380, 1455, and/or (5) an age (time) variation compensator (or modulator) 365, 1460. It will be observed by those of skill in the art that the various divisions between transconductance modulator 1410, variable parameter modulator 1425, or process (or other parameter) modulator or compensator 1430 or the other compensators and modulators are arbitrary and do not limit the scope of the present invention, as each may be made responsive to any of the parameters discussed above, and each may be utilized for any of the purposes discussed above (e.g., the variable parameter modulator 1425 may be utilized to compensate for fabrication process variations, etc., rather than temperature variations, for example). In addition, depending upon the selected implementation, one or more coefficient registers 1435 (e.g., 455, 465, 495) may be utilized to store any of the pluralities of coefficients discussed above. In alternative embodiments, such coefficients may not be needed, with switching voltages or currents applied directly, either statically or dynamically, as control signals.

Also in the exemplary embodiments, these various components may include a sensor 1440, 1815 (e.g., y(x) or I(T) generator 415, 515), or such as sensor may be provided as a separate component, such as a current source coupled to a diode as discussed above. Also, depending on the selected embodiment, and A/D converter 1445 and control logic 1450, 1810, to provide the selected frequency control.

In summary, the exemplary embodiments of the present invention provide an apparatus for frequency control of a resonator, with the resonator adapted to provide a first signal having a resonant frequency. The apparatus comprises a sensor (1440, 1815) adapted to provide a second signal, such as a control voltage, in response to at least one parameter of a plurality of parameters; and a frequency controller (215, 1415) coupled to the sensor and couplable to the resonator, with the frequency controller adapted to modify the resonant frequency in response to the second signal. The pluralities of parameters are variable and comprise at least one of the following parameters: temperature, fabrication process, voltage, frequency, and age.

In the exemplary embodiments, the frequency controller is further adapted to modify a reactance or impedance element coupled to the resonator in response to the second signal, such as modifying a total capacitance of the resonator in response to the second signal (FIG. 9), coupling to the resonator or decoupling from the resonator a fixed or variable capacitance (635), modifying the effective reactance of a varactor coupled to the resonator by switching the varactor to a selected control voltage, or equivalently, modifying an inductance of the resonator in response to the second signal, such as by coupling to the resonator or decoupling from the resonator a fixed or variable inductance, or modifying a resistance (or other impedance) of the resonator in response to the second signal, such as by coupling to the resonator or decoupling from the resonator a resistance.

In the exemplary embodiments, the frequency controller may further comprise a coefficient register adapted to store a first plurality of coefficients; and a first array (635) having a plurality of switchable capacitive modules coupled to the coefficient register and couplable to the resonator, each switchable capacitive module having a fixed capacitance 615 and a variable capacitance 620, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch between the fixed capacitance and the variable capacitance and to switch each variable capacitance to a control voltage. The plurality of switchable capacitive modules may be binary-weighted. The frequency controller may further comprise a second array 650 having a plurality of switchable resistive modules coupled to the coefficient register and further having a capacitive module, the capacitive module and the plurality of switchable resistive modules further coupled to a node 625 to provide the control voltage, with each switchable resistive module responsive to a corresponding coefficient of a second plurality of coefficients stored in the coefficient register to switch the switchable resistive module to the control voltage node 625. In selected embodiments, the sensor further comprises a current source 655 responsive to temperature, wherein the current source is coupled through a current mirror 670 to the second array to generate the control voltage across at least one switchable resistive module of the plurality of switchable resistive modules. Also in selected embodiments, the current source has at least one CTAT, PTAT, or PTAT" configuration (FIGS. 7A-7D). In addition, each switchable resistive module of the plurality of switchable resistive modules has a different temperature response for a selected current.

In other exemplary embodiments, the sensor is a temperature sensor and varies the second signal in response to temperature variation. The selected embodiments may also include an analog-to-digital converter 1445 coupled to the temperature sensor to provide a digital output signal in
response to the second signal, and a control logic block 1450 to convert the digital output signal to the first plurality of coefficients.

In other exemplary embodiments, the frequency controller further comprises a process variation compensator 320, 425, 760 or 860, the process variation compensator coupleable to the resonator and adapted to modify the resonant frequency in response to a fabrication process parameter of the plurality of parameters. The process variation compensator may further comprise a coefficient register adapted to store a plurality of coefficients; and an array 760 having a plurality of switchable capacitive modules coupled to the coefficient register and to the resonator, each switchable capacitive module having a first fixed capacitance 750 and a second fixed capacitance 720, each switchable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between the first fixed capacitance and the second fixed capacitance. In other exemplary embodiments, the process variation compensator may further comprise a coefficient register adapted to store a plurality of coefficients; and an array 860 having a plurality of binary-weighted switchable variable capacitive modules 865 coupled to the coefficient register and to the resonator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between a first voltage and a second voltage.

In other exemplary embodiments, a frequency controller further comprises a coefficient register adapted to store a first plurality of coefficients; and a first array 1500 having a plurality of switchable, binary-weighted capacitive modules 1505 coupled to the coefficient register and coupleable to the resonator, each switchable capacitive module having a variable capacitance 1515, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch (1520) the variable capacitance to a selected control voltage of a plurality of control voltages. The sensor may comprise a current source responsive to temperature, and the frequency controller may also include a second array 1600 having a plurality of resistive modules 1605 coupled through a current mirror (670, 510, 520) to the current source (655), the plurality of resistive modules adapted to provide the plurality of control voltages, and wherein each resistive module of the plurality of resistive modules has a different response to temperature and is adapted to provide a corresponding control voltage, of the plurality of control voltages, in response to a current from the current source.

In other exemplary embodiments, an apparatus for frequency control of a resonator comprises a coefficient register adapted to store a first plurality of coefficients; and a first array (1300, 1800) having a plurality of switchable reactance modules (1305, 1805) coupled to the coefficient register and to the resonator, each switchable reactance module responsive to a corresponding coefficient of the first plurality of coefficients to switch a corresponding reactance to the resonator to modify the resonant frequency. The corresponding reactance may be a fixed or variable inductance, a fixed or variable capacitance, or any combination thereof. The corresponding reactance may be switched between the resonator and a control voltage or a ground potential, and the control voltage may be determined by a current source responsive to temperature. For example, the corresponding reactance is variable and is switched between the resonator and a selected control voltage of a plurality of control voltages. In selected embodiments, the first plurality of coefficients are calibrated or are determined by a sensor responsive to at least one parameter of a plurality of variable parameters, such as temperature, fabrication process, voltage, and frequency.

In the exemplary embodiments, the plurality of switchable reactance modules may further comprise a plurality (635) of binary-weighted switchable capacitive modules 640, each switchable capacitive module having a fixed capacitance and a variable capacitance, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch between the fixed capacitance and the variable capacitance and to switch each variable capacitance to a control voltage. The apparatus may also include a current source 655 responsive to temperature; and a second array having a plurality of switchable resistive modules 675 coupled to the coefficient register and selectively coupleable to the current source, the second array further having a capacitive module 680, the capacitive module and the plurality of switchable resistive modules further coupled to a node 625 to provide the control voltage, each switchable resistive module responsive to a corresponding coefficient of a second plurality of coefficients stored in the coefficient register to switch the switchable resistive module to the control voltage node, and wherein each switchable resistive module of the plurality of switchable resistive modules has a different temperature response for a selected current from the current source.

In other exemplary embodiments, the plurality of switchable reactance modules further comprise a plurality 1500 of binary-weighted switchable capacitive modules 1505, each switchable capacitive module having a variable capacitance 1515, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch (1520) the variable capacitance to a selected control voltage of a plurality of control voltages. The apparatus may also include a current source 655 responsive to temperature; and a second array having a plurality of resistive modules 1605 coupled through a current mirror (670, 510, 520) to the current source, the plurality of resistive modules adapted to provide the plurality of control voltages, and wherein each resistive module of the plurality of resistive modules has a different response to temperature and is adapted to provide a corresponding control voltage, of the plurality of control voltages, in response to a current from the current source.

In other exemplary embodiments, the plurality of switchable reactance modules may further comprise a plurality 760 of binary-weighted switchable capacitive modules coupled to the coefficient register and to the resonator, each switchable capacitive module having a first fixed capacitance 750 and a second fixed capacitance 720, each switchable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between the first fixed capacitance and the second fixed capacitance. In other exemplary embodiments, the plurality of switchable reactance modules may further comprise a plurality 860 of binary-weighted switchable variable capacitive modules 865 coupled to the coefficient register and to the resonator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between a first voltage and a second voltage.

In the exemplary embodiments, an apparatus in accordance with the teachings of the invention comprises a resonator 310, 405 adapted to provide a first signal having a resonant frequency; and a temperature compensator 315 coupled to the resonator and adapted to modify the resonant frequency in response to temperature variation. The resonator is at least one of the following resonators: an inductor (L) and a capacitor (C) configured to form an L-C tank resonator; a ceramic resonator; a mechanical resonator, a microelectromechanical resonator, or a film bulk acoustic resonator. The apparatus may further comprise a negative transconductance amplifier 410 coupled to the resonator and to the temperature compen-
sator, wherein the temperature compensator is further adapted to modify a current through the negative transconductance amplifier in response to temperature variation. The temperature compensator may further comprise a current source 415, 515, 655 responsive to temperature variation.

In other exemplary embodiments, the temperature compensator further comprises: a current source 415, 515, 655 adapted to provide a current responsive to temperature variation; a coefficient register adapted to store a first plurality of coefficients; a plurality of resistive modules 675, 1605 coupled to the resonator and the current source, at least one resistive module of the plurality of resistive modules adapted to provide a control voltage or a plurality of control voltages; and a plurality of switchable reactance modules (1305, 1805, 635, 1505), coupled to the resonator and to the current source and selectively coupleable to at least one resistive module of the plurality of resistive modules.

In other exemplary embodiments, the invention provides a frequency controller for frequency control of a resonator, comprising: a coefficient register adapted to store a first plurality of coefficients and a second plurality of coefficients; a current source 415, 515, 655 adapted to provide a current corresponding to a temperature; a first array having a plurality of switchable resistive modules 675, 1605 coupled to the coefficient register and further having a capacitive module, the first array further coupled through a current mirror to the current source to create at least one control voltage across at least one switchable resistive module of the plurality of switchable resistive modules, each switchable resistive module responsive to a corresponding coefficient of the second plurality of coefficients to switch the switchable resistive module to provide the control voltage to a control voltage node; and a second array having a plurality of binary-weighted switchable capacitive modules 640 coupled to the coefficient register and to the resonator, each switchable capacitive module having a fixed capacitance and a variable capacitance, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch between the fixed capacitance and the variable capacitance and to switch each variable capacitance to the control voltage node.

Referring again to FIGS. 3 and 4, the clock generator and/or timing/frequency reference (100, 200, or 300) may also include a frequency calibration module (325 or 430). This frequency calibration module is the subject of a separate patent application, but its high-level functionality is described briefly below. FIG. 13 is a high-level block diagram illustrating an exemplary frequency calibration module 900 (which may be utilized as module 325 or 430) in accordance with the teachings of the present invention. The frequency calibration module 900 includes a digital frequency divider 910, a counter-based frequency detector 915, a digital pulse counter 905, and a calibration register 930 (which also may be utilized as register 465). Using a test IC, the output signal from the clock generator (100, 200 or 300) is frequency divided (910) and compared with a known reference frequency 920 in frequency detector 915. Depending upon whether the clock generator (100, 200 or 300) is fast or slow with respect to the reference, down or up pulses are provided to the pulse counter 905. Based upon those results, the third plurality of switching coefficients $r_n$ though $r_{n-1}$ is determined, and the clock generator (100, 200 or 300) is calibrated to a selected reference frequency. Again, individual ICs may also be calibrated and tested separately.

Referring again to FIGS. 2, 3 and 4, it will be appreciated by those of skill in the art that a highly accurate over PVT, low jitter, free-running and self-referenced oscillator has been described, providing a differential, substantially sinusoidal signal having a selectable and tunable resonant frequency, $f_m$, available at nodes 470 and 475. For many applications, this signal is sufficient, and may be utilized directly (and may be output on bus 125 or 135 of FIG. 1, on line 250 of FIG. 2, or on line 350 of FIG. 3, or between the rails or lines 470 and 475 of FIG. 4). For example, this signal may be utilized as a timing or frequency reference. In accordance with the present invention, additional applications are available, including clock generation (substantially square wave), frequency division, low-latency frequency switching, and mode selection, as described below.

FIG. 14 is a block diagram illustrating an exemplary first frequency divider and square wave generator 1000, and an exemplary asynchronous frequency selector 1050, with exemplary glitch suppression module 1080 in accordance with the teachings of the present invention. As indicated above, a first frequency divider and square wave generator 1000 may be included in or comprise modules 220 and/or 330, and frequency selector 1050 (with or without glitch suppression module 1080) may be included in or comprise modules 205 and/or 335.

Referring to FIG. 14, the output signal from the oscillator, namely, a differential and substantially sinusoidal signal having a frequency $f_m$ such as output on line 250 of FIG. 2, or line 350 of FIG. 3, or between the rails or lines 470 and 475 of FIG. 4, is input into frequency divider and square wave generator 1000. The frequency of this substantially sinusoidal signal is divided by an one or more arbitrary values “$N$” into “$m$” different frequencies (including $f_m$, where appropriate), and converted to substantially square wave signals, resulting in a plurality of substantially square wave signals having $m+1$ different available frequencies, output on lines or bus 1020 as frequencies $f_0$, $f_1$, $f_2$, through $f_m$. Any of these substantially square wave signals having $m+1$ different available frequencies are selectable asynchronously through exemplary asynchronous frequency selector 1050 which, as illustrated, may be embodied as a multiplexer. The selection of any of these substantially square wave signals having $m+1$ different available frequencies may be accomplished through the plurality of selection lines ($S_m$ through $S_0$) 1055, providing a substantially square wave signal having the selected frequency, output on line 1060.

As part of asynchronous frequency selection, glitch suppression is also provided by glitch suppression module 1080, which may be embodied in a plurality of ways, including through the use of one or more exemplary D flip-flops ("DFFs") illustrated in FIG. 14. A glitch could occur in an asynchronous frequency transition in which either a low state or a high state is not maintained for a sufficient period of time and may cause metastability in circuitry which is driven by the output clock signal. For example, an asynchronous frequency transition could result in a low state at a first frequency transitioning into a high state at a second frequency, at a point where the high state is about to transition back to a low state at the second frequency, resulting in a voltage spike or glitch. To avoid potential glitches from being provided as part of an output clock signal, the selected substantially square wave signal (having the selected frequency) is provided on line 1060 to a first DFF 1065 which provides a holding state; if a glitch should occur, it will be held until a clock edge triggering the DFF. To avoid the glitch occurring at the clock edge, the DFFs may be clocked at least at the maximum available frequency, or one or more additional DFFs (such as DFF 1070) may be employed, as, during the wait for another clock signal, the Q output from the DFF 1065 will have stabilized to either a first state (high or low) or a second state (low or high).
such as to either the power or ground rail. It has been shown by the inventors that two DFFs are sufficient, with additional DFFs potentially being added as may be desired, but with additional DFFs causing increased switching latency. While illustrated utilizing exemplary DFFs, other flip-flops or counters may be utilized, and those of skill in the art will recognize myriad other equivalent implementations which will achieve this result, and all such variations are within the scope of the invention.

Such exemplary low latency frequency switching in accordance with the teachings of the present invention is illustrated in FIG. 15. FIG. 15 is also illustrative of “substantially” square waves of the present invention, which are typical of actual square waves utilized in various technologies, exhibiting reasonable variation, undershoots and overshoots at their respective high and low states (and not the perfect “flatness” of textbook examples). FIG. 15, part A, illustrates asynchronous glitch-free switching from 1 MHz to 33 MHz, while part B illustrates measured glitch-free switching from 4 MHz to 8 MHz, then to 16 MHz, and then to 33 MHz.

Referring again to FIG. 14, the frequency divider and square wave generator 1000 may be implemented in innumerable ways, such as differential or single-ended, with the illustrated divider being merely exemplary. As the output from the oscillator illustrated in FIG. 4 is differential (across lines or rails and), the first divider 1005 is also differential and provides complementary outputs, to present a substantially constant load to the oscillator and to maintain phase alignment, and is fast, to support high frequencies such as in the GHz range. In addition, it may be necessary or advisable to reject any relaxation mode oscillation of the first divider 1005. The second divider 1010 may also be differential and provide any arbitrary frequency division (divide by “M”), such as dividing by an integer, a multiple of two, a rational number, or any other amount or number, etc. Topologies or configuration for such dividers are known in the art, and any such divider may be utilized. Such dividers, for example and without limitation, may be a sequence (multiple stages) of counters or flip-flops 1075, such as those flip-flops illustrated in FIG. 16, as a second, differential frequency divider 1074, which provide frequency division in powers or multiples of 2, with the output of each stage providing a different frequency and further providing a clock signal for the next stage and also fed back to its own input, as illustrated. As illustrated, a plurality of frequencies are then available for output on lines or bus 1020, such as 1/2, 1/4, and so on, through 1/2^n. In addition, as illustrated, buffers 1085 may also be utilized, from the oscillator to the first divider 1005, to provide sufficient voltage to drive the first divider 1005, and also between second divider 1010 stages, to isolate state-dependent load variation which could also affect signal rise and fall times.

It should also be noted that the use of the various flip-flops has also provided a substantially square wave, as any substantially sinusoidal signal has been provided to clock a flip flop, whose output is then pulsed to a high or low voltage. Other square wave generators may also be utilized, as known or becomes known in the art. In the illustrated embodiments, to maintain phase alignment, differential signals are maintained through the last division. Following the last frequency division, the plurality of signals (each having a different frequency) are then squared (in module 1015) to provide substantially an evenly divided (e.g., 50:50) duty cycle, such that the time in which the signal is in a first (high) state is substantially equal to the time in which the signal is in a second (low) state.

FIG. 17 is a block diagram illustrating an exemplary mode selection module in accordance with the teachings of the present invention. There are circumstances in which a highly accurate, high performance reference, such as a clock generator (100, 200 or 300) of the invention, is unnecessary, such as in a low power, standby mode. In these circumstances, in accordance with the invention, either no clock output is provided, or a low power, reduced performance clock 1105 output is provided. For example, at comparatively low frequencies, a low performance ring oscillator may provide suitable performance with low power consumption. As illustrated in FIG. 17, for these conditions, the output of the low power oscillator 1105 may be selected (through multiplexer 1100), and provided as a clock output to other circuitry. At higher frequencies, however, such low performance oscillators consume considerably more power, typically significantly more than the oscillator of the present invention. There is typically a “break-even” point as a function of frequency, after which the clock generator (100, 200 or 300) provides both higher performance and lower power consumption, and may be selected (through multiplexer 1100), and provided as a clock output to other circuitry. As a consequence, the clock generator (100, 200 or 300) may also be utilized to provide a low power mode.

In addition, using mode selector 1110, other modes may be selected, such as a no power mode, rather than merely a low-frequency or sleep mode, as the clock generator (100, 200 or 300) may be restarted comparatively rapidly, or a pulsed mode, in which the clock generator (100, 200 or 300) is repeatedly stopped and restarted, periodically or non-periodically, in bursts or intervals. Various reference modes are discussed below.

In sharp contrast to the prior art, this pulsed clocking using the clock generator and/or timing/frequency reference (100, 200 or 300) of the present invention provides power savings or conservation. While more power may be consumed during a given burst, as the clock has a comparatively high frequency, more instructions are processed in that interval, followed by no or limited power dissipation during the non-pulse or off interval, resulting in higher MIPS/mW compared to a continuously running clock. In contrast, due to the comparatively long start-up time and locking of prior art clocks, such pulsed clocking results in more power consumption and less efficiency in the prior art.

FIG. 18 is a block diagram illustrating an exemplary synchronization module 1200 for a second oscillator in accordance with the teachings of the present invention. As mentioned above, the clock generator and/or timing/frequency reference (100, 200 or 300) may provide a reference mode to synchronize other oscillators or clocks, which may or may not be low power, such as second oscillator 1210 (e.g., ring, relaxation, or phase shift oscillators). An output signal from the clock generator and/or timing/frequency reference (100, 200 or 300) is further frequency divided as needed to form a plurality of available reference frequencies, with a reference frequency selected from this plurality of frequencies. This may be accomplished using the modules discussed above, such as by using the existing frequency dividers (220, 330, 1000, for example), and then providing the reference signal from the frequency selector 1050 (or 205 or 335). For example, referring to FIG. 3, mode selector 345 may select a reference mode and provide the output reference signal from frequency selector 335 to a second oscillator (with synchronization module) 375. A synchronization module, such as PLL or DLL 1205, is then utilized to synchronize the output signal from the second oscillator 1210 to the reference signal provided by clock generator and/or timing/frequency reference (100, 200 or 300). In addition to a mode of continuous synchronization, a pulsed-synchronization may also be pro-
vided, in which the clock generator and/or timing/frequency reference (100, 200 or 300) provides a pulsed output, and synchronization occurs during the interval of these pulses, as a synchronization interval.

FIG. 19 is a flow diagram illustrating an exemplary method in accordance with the teachings of the present invention, and provides a useful summary. The method begins with start step 1220, such as through clock generator and/or timing/frequency reference (100, 200 or 300) start-up. It should be noted that while illustrated in FIG. 19 as consecutive steps, these steps may occur in any order, and generally may occur concurrently as the clock generator and/or timing/frequency reference (100, 200 or 300) operates. Referring to FIG. 19, a resonant signal having a resonant frequency is generated, step 1225, such as through LC tank 405 or resonator 310. The resonant frequency is adjusted in response to temperature, step 1230, such as through a temperature compensator 315, which adjusts current and frequency. The resonant frequency is adjusted in response to fabrication process variation, step 1235, such as through process variation compensator 320. As indicated above, step 1235 may be performed as a first calibration step, followed by the temperature adjustment of step 1230. The resonant signal having the resonant frequency is divided into a plurality of secondary signals having a corresponding plurality of frequencies, in which the plurality of frequencies are substantially equal to or lower than the resonant frequency, step 1240, such as through frequency divider 330 or 1000). An output signal is selected from the plurality of secondary signals, step 1245, such as through frequency selector 335 or 1050, for example. Depending upon the selected embodiment or mode, the selected output signal may be provided directly, for example, as a reference signal.

In other embodiments, such as when the output signal is a differential rather than single-ended signal, and when the resonant signal is a substantially sinusoidal signal, the method continues with converting the differential, substantially sinusoidal signal to a single-ended, substantially square wave signal having a substantially equal high and low duty cycle, as needed, step 1250, such as to generate a clock output signal using modules 330 or 1000, for example. An operating mode is also selected from a plurality of operating modes, step 1255, where the plurality of operating modes can be selected from a group comprising a clock mode, a timing and frequency reference mode, a power conservation mode, and a pulsed mode, for example, such as using mode selector 225 or 345. When a reference mode is selected in step 1255, in step 1260, the method proceeds to step 1265, to synchronize a third signal (e.g., from a second oscillator) in response to the output signal, such as illustrated in FIG. 18. Following steps 1260 or 1265, the method may end or repeat (continue) (such as with the clock generator and/or timing/frequency reference (100, 200 or 300) running continuously), return step 1270.

FIG. 19 is a block diagram illustrating a second exemplary system 1195 embodiment in accordance with the teachings of the present invention. As illustrated, the second exemplary system 1195 comprises a clock generator (timing/frequency reference (100, 200, 300), as discussed above, and second circuitry 180, of any type or kind, for any function, application, or purpose, such as a "processor" 1275 as illustrated and as defined below. The second circuitry 180 may also further comprise a memory 1280, an interface 1285 for input and output ("I/O"), and other circuitry components for any selected application or function. The second exemplary system 1195 is typically embodied as a single integrated circuit, providing one or more first reference signals, as one or more system clocks or references, which is integrated with other components and which does not require any external reference or clock, such as a crystal oscillator reference. For example, the clock/reference (100, 200, 300) is free-running and is not and does not lock to any reference clock or signal, and instead provides a reference clock or signal to other, second circuitry 180.

The second exemplary system 1195 also may be embodied as a plurality of integrated circuits, coupled through bonding wires within the same IC package. For example, the clock generator (timing/frequency reference) (100, 200, 300) may be embodied on a first IC, and the second circuitry 180 on a second IC, which are coupled to each other through one or more bonding wires, for the first IC (clock) to provide one or more first reference signals, as one or more system clocks or references, to the second IC (second circuitry 180), providing a clock or reference as part of a single, packaged component which does not require any external reference or clock, such as a crystal oscillator reference.

As illustrated in FIG. 19, in addition to the clock generator (timing/frequency reference) (100, 200, 300), the second exemplary system 1195 further comprises one or more types of second circuitry, such as one or more processors 1275, and potentially also an I/O interface (or other I/O means) 1285 and a memory 1280. Each of these components receives the one or more first reference signals, typically for use as one or more clocking signals. In the second exemplary system 1195, the I/O interface 1285 may be implemented as known or may become known in the art, to provide data communication between, first, the processor 1275, memory 1280, and second, any channel, busses, input and output devices, mechanisms and media discussed herein (not separately illustrated), including wireless, optical or wireline, using any applicable standard, technology, or media, without limitation. For example, when the second exemplary system 1195 is utilized as a computer processor, the I/O interface 1285 is adapted to provide data communication to and from one or more busses, such as a PCI bus, a PCI-Express bus, a universal serial bus (USB1 or USB2), and so on. In addition, the I/O interface 1285 may provide an interface to any CD or disk drives, or an interface to a communication channel for communication via a network, to provide communication with any form of media or communication device, such as providing an Ethernet port, for example. Also for example, the I/O interface 1285 may provide all signaling and physical interface functions, such as impedance matching, data input and data output between external communication lines or channels (e.g., Ethernet, T1 or ISDN lines) coupled to a network, and internal server or computer communication busses (e.g., one of the various PCI or USB busses), for example and without limitation. In addition, depending upon the selected embodiment, the I/O interface 1285 (or the processor 1275) may also be utilized to provide data link layer and media access control functionality.

The memory 1280 may be embodied in any number of forms, including within any computer or other machine-readable data storage medium, memory device or other storage or communication device for storage or communication of information such as computer-readable instructions, data structures, program modules or other data, currently known or which becomes available in the future, including, but not limited to, a magnetic hard drive, an optical drive, a magnetic disk or tape drive, a hard disk drive, other machine-readable storage or memory media such as a floppy disk, a CDROM, a CD-RW, digital versatile disk (DVD) or other optical memory, a memory integrated circuit ("IC"), or memory portion of an integrated circuit (such as the resident memory within a processor IC), whether volatile or non-volatile, whether removable or non-removable, including without
limitation RAM, FLASH, DRAM, SDRAM, SRAM, MRAM, FRAM, ROM, EPROM or EEPROM, or any other type of memory, storage medium, or data storage apparatus or circuit, which is known or which becomes known, depending upon the selected embodiment. In addition, such computer readable media includes any form of communication media which embodies computer readable instructions, data structures, program modules or other data in a data signal or modulated signal, such as an electromagnetic or optical carrier wave or other transport mechanism, including any information delivery media, which may encode data or other information in a signal, wired or wirelessly, including electromagnetic, optical, acoustic, RF or infrared signals, and so on.

The second exemplary system 1195 further comprises one or more types of processing circuitry, such as one or more processors 1275, which may be single- or multiple-core, may be general purpose or specialized, and which may be adapted to perform any type of functionality. As the term “processor” is used and defined herein, a processor 1275 may be any type or kind of circuitry, adapted to perform a function, an application, or other purpose, of any type or kind, and may include use of a single integrated circuit (“IC”), or may include use of a plurality of integrated circuits or other components connected, arranged or grouped together, such as microprocessors, digital signal processors (“DSPs”), controllers or micro-controllers, parallel processors, multiple core processors, custom ICs, application specific integrated circuits (“ASICs”), field programmable gate arrays (“FPGAs”), adaptive computing ICs, associated memory (such as RAM, DRAM and ROM), and other ICs and components. As a consequence, as used herein, the term processor should be understood to equivalently mean and include a single IC, or arrangement of custom ICs, ASICs, processors, microprocessors, controllers, FPGAs, adaptive computing ICs, or some other grouping of integrated circuits which perform(s) any applicable function(s), with associated memory, such as microprocessor memory or additional RAM, DRAM, SDRAM, SRAM, MRAM, ROM, FLASH, EPROM or EEPROM. A processor (such as processor 1275), with its associated memory, may be adapted or configured (via programming, microcode, FPGA interconnection, or hard-wiring) to perform any functionality, as discussed below, associated with any selected application of the second exemplary system 1195 (or third, fourth or fifth exemplary systems discussed below). For example, any function or methodology may be programmed and stored, in a processor 1275 with its associated memory (and/or memory 1280) and other equivalent components, as a set of program instructions or other code (or equivalent configuration or other program) for subsequent execution when the processor is operative (i.e., powered on and functioning). Equivalently, when the processor 1275 may be implemented in whole or part as FPGAs, custom ICs and/or ASICs, the FPGAs, custom ICs or ASICs also may be designed, configured and/or hard-wired to implement any selected functionality or methodology. For example, the processor 1275 may be implemented as an arrangement of microprocessors, DSPs and/or ASICs, collectively referred to as a “processor”, which are respectively programmed, designed, adapted or configured to implement a selected function, such as a communication function, a data processing function, etc.

The processor 1275 may be implemented as, for example and without limitation, a microprocessor; a digital signal processor; a controller; a microcontroller; a universal serial bus (USB) controller; a Peripheral Component Interconnect (PCI) controller; a Peripheral Component Interconnect Express (PCI-e) controller; a Firewire controller; an AT Attachment (ATA) interface controller, an Integrated Drive Electronics (IDE) controller; a Small Computer Systems Interface (SCSI) controller. In other embodiments, the processor 1275 may be implemented to provide other forms of control functionality, such as a television controller; a local area network (LAN) or Ethernet controller; a video controller; an audio controller; a modem processor or controller; a cable modem controller or processor; a multimedia controller; an MPEG controller, e.g., MPEG-1, (Video CD, MP3), MPEG-2 (digital television, DVD), MPEG-4 (multimedia for fixed and mobile web applications), MPEG-7 (description and search of audio and visual content), MPEG-21 (multimedia framework). In other embodiments, when the clock/reference has been implemented to provide significant and stable frequency accuracy, the processor 1275 may be implemented to provide communications functionality, such as one or more communication controllers for mobile communication (a mobile communication controller, an IEEE 802.11 controller; a GSM controller, a GPRS controller; a PCS controller; an AMPs controller; a CDMA controller; a WCDMA controller; a spread spectrum controller; a wireless LAN controller; an IEEE 802.11 controller in its various forms, etc.), or non-mobile communication (e.g., a DSL controller; a T1 controller; an ISDN controller; or other multimedia or other communication controller.

Continuing with the above-example, selected frequencies may include 12, 30, 48 or 480 MHz for a USB controller (USB1 or USB2); 33 or 66 MHz for a PCI controller, or 6 MHz for a PCI-e controller, a Firewire controller, an AT controller, or an SCI controller; 10.7 MHz for a television controller; 50 MHz for a local area network (LAN) or Ethernet controller; 27 MHz or 54 MHz for a video controller; 24.576 MHz for an audio controller; 56.448 MHz for a modem processor; and other frequencies suitable for any of the various MPEG controllers or communications controllers mentioned above. Other frequencies are also selected based upon the application, such as appropriate GHz frequencies when the processor 1275 is utilized in a computer, for example.

The various frequencies, such as those illustrated above, may be determined in any of a plurality of ways, whether provided directly by the clock generator (timing/frequency reference) 100, 200, 300 as first frequency f0 of the first reference signal, or as one or more second frequencies of one or more second reference signals (via the one or more dividers 1000, 1010, 1074, 1218, 1219 or locking circuits 1204 and other components discussed below). For example, the various frequencies may be determined as part of design and fabrication, or post-fabrication (such as through calibration and programming), or both. More particularly, the frequency selection may occur as part of design and fabrication, such as through selection of the number and size of inductors and capacitors utilized in the LC oscillator of the clock/reference 100, 200, 300. For example, the size(s) and/or shape(s) of the one or more inductors (e.g., 445) may be selected through a suitable metal layer mask. As discussed above, frequency selection also may occur post-fabrication, through the use of the various calibration and control coefficients or signals discussed above. In addition, as discussed below, frequency selection may be performed through the configuration of the one or more locking circuits 1204 or dividers, such as through selection of the divide ratio(s) through programmable counters, which may be as part of the design and fabrication of the IC, or may be programmed post-fabrication, also through use of calibration and control coefficients or signals, or by switching dividers in or out of the divide chain.
In addition to the illustrated one or more processors 1275, I/O interface 1285, and memory 1280, those of skill in the art will appreciate that the various exemplary systems may also include additional or different components, and generally will vary with the selected application. For example, different application may require additional circuits, such as different physical layer implementations in addition to that described for I/O interface 1285, for example.

FIG. 40 is a block diagram illustrating a third exemplary system 1201 embodiment in accordance with the teachings of the present invention. As illustrated in FIG. 40, the first reference signal having a first frequency (f1) is provided either directly to a processor 1275 (as an example of second circuitry 180) or to additional second circuitry illustrated as inverter 1196, dividers (1000, 1074, 1218 and/or 1219 discussed below), locking circuits 1204 (illustrated as locking circuit 12041, locking circuit 12042, through locking circuit 1204n), and combinations or permutations of such dividers, locking circuits, etc. This additional second circuitry is adapted to receive the first reference signal having a first frequency (f1) and to provide one or more corresponding second reference signals at selected frequencies, illustrated as frequencies f2, f3 through fn and having any selected phase relationship (e.g., inverted, 90 degrees, quadrature, etc.).

The third exemplary system 1201 (and the various other exemplary embodiments discussed below) provide for generating a plurality of reference signals, whether sinusoidal or square-wave, such as for use as one or more clock signals or frequency references. The clock/frequency reference (100, 200, 300) provides a first reference signal (having a first frequency f1), and is coupled to one or more locking circuits 1204 such as phase-locked loops, delay-locked loops, injection locking circuits (illustrated as locking circuit 12041, locking circuit 12042, through locking circuit 1204n), to provide a corresponding plurality of output signals at selected frequencies, illustrated as frequencies f1c1, f1c2 through f1cn. Each locking circuit 1204 of the plurality of locking circuits 1204 has a corresponding divide ratio of a plurality of different divide ratios. In operation, each locking circuit 1204 is adapted to phase, delay or otherwise lock to the first reference signal provided by the clock/frequency reference (100, 200, 300), and to provide an output, second reference signal having an output frequency determined from the first frequency and the corresponding divide ratio. Each locking circuit 1204, such as a PLL or DLL, may be implemented as known in the art, as the illustrated PLL 1204, in FIG. 43 and discussed below.

In an exemplary embodiment, the frequencies of the second reference signals may be fixed, such as fixed at fabrication through wired or configured dividers or divide ratios, or variable, such as selected or programmed post-fabrication through control circuitry (or logic) or stored coefficients (1215) (block 1215, which may be a register storing coefficients or other circuitry providing control signals), such as to adjust the divide ratios of the locking circuits 1204 for corresponding frequency selection, and as further discussed below. Any stored coefficients (1215) may also be part of the various frequency calibration and frequency control coefficients stored in registers 455, 465 and 495, as discussed above. As an option, a user input, such as for frequency selection, also may be provided through a user interface (not separately illustrated).

As discussed above with reference to FIGS. 14 (dividers 1000, 1010) and 16 (divider 1074 for a differential signal), the output signal from the oscillator of clock/frequency reference (100, 200, 300), as a first reference signal typically at a first frequency, also may be frequency divided to provide one or more second reference (or clock) signals having one or more selected, second frequencies. FIG. 41 is a block diagram illustrating a third exemplary frequency divider 1218 embodiment in accordance with the teachings of the present invention, for asynchronous frequency division. FIG. 42 is a block diagram illustrating a fourth exemplary frequency divider 1219 embodiment in accordance with the teachings of the present invention, for synchronous frequency division. As previously discussed, for these embodiments, each flip-flop (or counter) 1214 (illustrated as flip-flops 1214a, 1214b, through 1214n) provides a frequency division by a factor of two or, when implemented as a counter, by whatever number maximum (terminal or ultimate) number to which the counter is adapted to count. FIG. 41 illustrates a configuration of the flip-flops (or counters) 1214 to provide asynchronous frequency division. FIG. 42 illustrates a configuration of the flip-flops (or counters) 1214, with other gate logic (AND gates) 1217 to provide synchronous frequency division. In addition to the illustrated gate logic (AND gates) 1217, any configuration of combinational logic, for example, may be utilized to provide the selected synchronization, with the gate logic (AND gates) 1217 being one example for the illustrated divide by 8 of FIG. 42, and all such variations are within the scope of the invention.

Frequency dividers, such as the third exemplary frequency divider 1218 and the fourth exemplary frequency divider 1219, may be coupled to the oscillator of the various clock generator (timing/frequency reference) (100, 200, 300) embodiments, providing one or more second reference signals having a corresponding plurality of second frequencies, illustrated as frequencies f2, f3 through fn. Alternatively, frequency dividers such as the third exemplary frequency divider 1218 and the fourth exemplary frequency divider 1219, may be part of a locking circuit 1204 (e.g., one or more phase-locked loops ("PLLs"), delay-locked loops ("DLLs"), or injection locking circuits) which is coupled to the oscillator of the various clock generator (timing/frequency reference) (100, 200, 300) embodiments. An exemplary locking circuit was illustrated as PLL 1205 in FIG. 18. Such locking circuit embodiments are discussed below with reference to FIGS. 43 and 44. In addition, the various dividers (1000, 1010, 1074, 1218, 1219) may also be coupled to one or more locking circuits 1204, as illustrated in FIG. 40.

Both asynchronous frequency division and synchronous frequency division, for providing one or more output signals having a selected frequency, are within the scope of the present invention. In addition, the frequency division may be switched between or among synchronous or asynchronous frequency division, at any point in the divide chain (i.e., the succession of coupled flip-flops (or counters) 1214 as illustrated). Such frequency division may be division by any number. The frequency division may be of either a single-ended or a differential clock or reference signal (e.g., as illustrated in FIGS. 14, 16, 41 and 42). Innumerable other circuit topologies for frequency division will be apparent to those of skill in the art, and are considered equivalent, with all such variations are within the scope of the invention.

Continuing to refer to FIG. 40, the third exemplary system 1201 may comprise the clock generator (timing/frequency reference) (100, 200, 300) and any one or more of the illustrated second circuitry, such as inverter 1196, square-wave generator 1015, a divider (1000, 1010, 1074, 1218, 1219), a locking circuit 1204, or any of the various other types of second circuitry previously mentioned, such as one or more processors 1275, memory 1280, or I/O interface 1285. For example, the third exemplary system 1201 may be implemented to include the direct provision (on line 1197) of the
first reference signal having a first frequency (f₁) to additional second circuitry 1198 such as a processor 1275, along with one or more dividers (1000, 1010, 1074, 1218, 1219) adapted to provide a plurality of second reference signals at lower frequencies, such as for power saving. Also for example, the third exemplary system 1201 may be implemented to include one or more locking circuits 1204 and/or one or more dividers (1000, 1010, 1074, 1218, 1219) coupled to locking circuits 1204, to provide a plurality of second reference signals at any corresponding frequencies, such as based upon corresponding divide ratios (providing any rational multiple of the first frequency (f₁)).

FIG. 43 is a block diagram illustrating a fourth exemplary system 1202 embodiment in accordance with the teachings of the present invention. The clock/frequency reference (100, 200, 300) provides a first reference signal (having a first frequency f₁), and is coupled to at least one locking circuit 1204 such as a phase-locked loop (PLL), a delay-locked loop (DLL), or an injection locking circuit, to provide a corresponding, second reference signal, such as a clock output signal at a selected frequency, illustrated as frequency f₂. (A fifth embodiment with multiple locking circuit 1204 is discussed below with reference to FIG. 44.) In operation, each locking circuit (such as PLL or DLL) 1204 is adapted to phase, delay or otherwise lock to the first reference signal provided by the clock/frequency reference (100, 200, 300), and to provide an output signal (as the second reference signal) having an output, second frequency determined from the first frequency and a corresponding divide ratio. Illustrated as a phase-locked loop embodiment for purposes of example and not limitation, a phase-locked loop 1204, (as a type of locking circuit 1204) comprises a divider (or multiplier) 1206 (e.g., ×N) and a second divider (or multiplier) 1207 (e.g., ×M), forming a corresponding divide ratio, to provide the second frequency f₂ which is a rational multiple (M/N) of first frequency f₁. In the illustrated embodiment, the second divider 1207 effectively functions as a multiplier (dividing the output frequency f₁ to a lower frequency to match and phase lock with f₂/N). Depending upon the selected embodiment, the output frequency of the second reference signal (e.g., f₂) may be any rational multiple of the first frequency f₁, whether higher or lower.

The locking circuit 1204, when implemented as a phase-locked loop embodiment 1204, further comprises a phase detector 1208, a charge pump 1209, optionally filter 1211, and a voltage-controlled oscillator (“VCO”) 1212 (such as a second oscillator 1210 illustrated in FIG. 18). The VCO 1212 provides the second reference signal having a second frequency f₂ which is utilized as a clock or other reference by the processor 1275, memory 1280, and I/O interface 1285 in an integrated third system 1202 embodiment.

The clock/reference (100, 200, 300) is adapted to provide, as output, a first reference signal at a first frequency f₁, or in conjunction with divider or locking circuit 1204, a second reference signal at a second frequency, illustrated as frequency f₂ in FIG. 43, or with a plurality of locking circuits 1204 or dividers, to provide output of a corresponding plurality of second reference signals having corresponding frequencies f₁, f₂, through fₙ, illustrated in FIG. 44. As mentioned above, the frequency selection may occur as part of design and fabrication, such as through selection of the number and size of inductors and capacitors utilized in the LC oscillator of the clock/reference (100, 200, 300). For example, the size(s) and/or shape(s) of the one or more inductors (e.g., 445) may be selected through a suitable metal layer mask. Frequency selection also may occur post-fabrication, through the use of the various calibration and control coefficients or signals discussed above. In addition, frequency selection may be performed through the configuration of the one or more locking circuits 1204 (PLL/DLLs), such as through selection of the divide ratio(s) through programmable counters, which may be as part of the design and fabrication of the IC, or may be programmed post-fabrication, also through use of calibration and control coefficients or signals, or by switching dividers in or out of the divide chain.

FIG. 44 is a block diagram illustrating a fifth exemplary system 1203 embodiment in accordance with the teachings of the present invention. The fifth exemplary system 1203 comprises the components previously discussed for the third system 1202 embodiment, namely, a clock/frequency reference (100, 200, 300), control logic or stored coefficients (1215), one or more processors 1275, an I/O interface (or other I/O means) 1285, and a memory 1280. The fifth exemplary system 1203 further comprises a plurality of locking circuits 1204 and dividers (1000, 1010, 1074, 1218, 1219), such as phase-locked loops or delay-locked loops (or injection locking circuits) and synchronous or asynchronous dividers, respectively, to provide a corresponding plurality of second reference signals (clock or other reference signals) having a corresponding plurality of second frequencies, including any type or shape (single-ended, differential, square-wave, sinusoidal, spread spectrum), illustrated as plurality of second reference signals having corresponding second frequencies f₁, f₂, f₃, through fₙ, the plurality of second reference signals having corresponding frequencies f₁, f₂, f₃, through fₙ, and potentially also the first reference signal having first frequency f₀, are provided to switching circuitry 1290, for selection of one or more second reference signals to be provided to the one or more processors 1275, I/O interface 1285, and memory 1280.

The switching circuitry 1290 may be controlled by the frequency selection and control logic circuitry 1295 and/or control logic or stored coefficients register (1215) (discussed above). For example, the control logic circuitry 1295 may provide one or more control signals to the switching circuitry 1290 which, in turn, is adapted to respond to the one or more control signals to switch a selected second reference signal, of the plurality of second reference signals, to the processor 1275 and the other components. Similarly, one or more stored coefficients (e.g., stored in a coefficient register 1215) may be utilized to control the switching of a selected second reference signal, of the plurality of second reference signals, to the processor 1275 and the other components, by controlling a gate voltage of a switching or pass-transistor, for example. In addition, the frequency selection and control logic circuitry 1295 may also be utilized to control the plurality of locking circuits 1204, such as by programming the corresponding divide ratios. In exemplary embodiments, the switching circuitry 1290 is implemented to provide substantially glitch-free switching, and may be implemented through any type of switching fabric or matrix, such as through one or more multiplexers, pass-transistors, cross-bar switch, or other switching or configurable circuitry. Alternatively, the switching circuitry 1290 may be omitted, with a plurality of clock or reference signals, having different frequency or phase relationships, types or shapes (e.g., single-ended, differential, square-wave, sinusoidal, spread spectrum) provided directly to the one or more processors 1275, I/O interface 1285, and memory 1280. In addition, the switching circuitry 1290 may be implemented through non-reconfigurable circuitry, such as through various fuse or other electrically programmable connections, ROM connections, or other one-time configurable linkages, for example. Innumerable variations on the
control of the selection of the one or more second reference signals, of the plurality of second reference signals, which are provided to the second processing circuitry such as the processor 1275, memory 1280, I/O interface 1285, will be apparent to those of skill in the art, are considered equivalent and are within the scope of the present invention.

For example, the fifth exemplary system 1203 may be utilized to provide a plurality of clock or reference signals having any selected frequency and/or phase relationships, single-ended or differential, and square-wave or sinusoidal. Continuing with the example, a first, comparatively higher frequency signal may be provided to the one or more processors 1275, an I/O interface 1285, and memory 1280 for high performance when ample power is available. A second, comparatively lower frequency signal may be provided to the one or more processors 1275, an I/O interface 1285, and memory 1280 for power-saving performance when a power source may be limited, such as for a power reduction when the power supply is a battery. A third, comparatively lower frequency signal may be provided to the one or more processors 1275, an I/O interface 1285, and memory 1280 for power-saving, such as for a sleep or hibernation mode. In addition to frequency determination through the selection of the number and size of inductors and capacitors utilized in the LC oscillator of the clock/reference (100, 200, 300), the frequency selection and control logic circuitry 1295 and/or control logic or stored coefficients (1215) may be programmed or calibrated to control the switching circuitry 1290 to provide any such corresponding clock or other second reference signals having frequencies f1, f2, through fN.

Four exemplary discrete apparatus embodiments are illustrated in FIGS. 45-48. Similarly to the other illustrated embodiments, these discrete apparatus embodiments are also adapted to operate without locking to an external reference signal, such as without locking to any type of crystal (XTAL) reference. In addition, any of these discrete apparatus embodiments may be provided in configurable or programmable forms, such as to provide selectable frequencies and output pins for the one or more second reference signals, or in non-configurable or non-programmable forms, such as to provide predetermined or otherwise fixed frequencies and output pins for the one or more second reference signals. For example, the discrete apparatus embodiments may be provided as a “standard” IC providing one or more clock signals at predetermined frequencies, or may be provided as a configurable IC for user selection of output frequencies, signal types, signal levels, etc. Such configuration and/or selection may occur as part of design and fabrication, such as through mask-programming of reactance sizes, amounts, and interconnections, or post-fabrication, such as through configuration and selection of interconnections, reactance switching, divide ratios, etc., as discussed in greater detail below. In addition, such configurability may be combined with the exemplary integrated embodiments discussed above.

FIG. 45 is a block diagram illustrating an exemplary first discrete apparatus 3000 embodiment in accordance with the teachings of the present invention, typically implemented as a discrete (i.e., single) integrated circuit. As illustrated in FIG. 45, the first discrete apparatus 3000 comprises a clock/frequency reference (100, 200, 300), one or more dividers (1000, 1010, 1074, 1218, or 1219) and/or one or more locking circuits 1204, which operate as previously discussed, and one or more input/output (I/O) interface circuits 3010. In addition, as an option, the first discrete apparatus 3000 may further comprise control logic and/or stored coefficients register (1215) and a user interface 3025. Not separately illustrated, the first discrete apparatus 3000 typically includes input for power and control signals, and may also include a voltage regulator.

The one or more locking circuits 1204 may be phase-locked loops or delay-locked loops (or injection locking circuits), and the one or more dividers (1000, 1010, 1074, 1218, 1219) (including any within the locking circuits 1204) may be synchronous or asynchronous, single-ended or differential, as discussed above. The locking circuits 1204 and/or dividers (1000, 1010, 1074, 1218, 1219) may also be implemented to be configurable or non-configurable. In this exemplary first discrete apparatus 3000 and the other exemplary discrete embodiments discussed below, the one or more dividers (1000, 1010, 1074, 1218, or 1219) and/or one or more locking circuits 1204 provide a corresponding plurality of second reference signals (clock or other reference signals) having a corresponding plurality of second frequencies, including of any type or shape (single-ended, differential, square-wave, sinusoidal, spread spectrum, etc.), illustrated as plurality of plurality of second reference signals having corresponding second frequencies f1, f2, through fN. The plurality of second reference signals having corresponding frequencies f1, f2, through fN, and potentially also the first reference signal having first frequency f0, are provided directly to the corresponding plurality of I/O interfaces 3010. (In addition, depending upon the number of divider and/or locking circuits which are successively “chained”, such as illustrated in FIGS. 45 and 48, with one or more second reference signals occurring between the successive circuits, the resulting output (from the last of the successive divider or locking circuits) may be referred to as plurality of third reference signals having a corresponding plurality of third frequencies f1, f2, through fN).

Similarly to the I/O interface 1285, the I/O interface 3010 may be implemented as known or may become known in the art, to provide (output) communication of the first and/or second reference signals from the clock/frequency reference (100, 200, 300) and any of the various dividers (1000, 1010, 1074, 1218, 1219) and locking circuits 1204, to any other device or structure (e.g., an off-chip device), such as, for example and without limitation, one or more IC input/output pins, or channels, busses, input and output devices, other circuitry, other I/O PADS, mechanisms and media discussed herein, including wireless, optical or wireline, using any applicable standard, technology, or media. For example, when first discrete apparatus 3000 is utilized to provide a clocking IC for a computer or communication system, the I/O interface 3010 is adapted to provide reference signal communication to (and potentially from) one or more conductive lines or wires on a printed circuit board (PCB), one or more busses, such as a PCI bus, a PCI Express bus, a universal serial bus (USB1 or USB2), or one or more other ICs, such as when connected via IC bonding wires to another IC, and so on. In addition, the I/O interface 3010 may provide an interface to any other device or structure previously discussed.

For purposes of the present invention, while referred to as an I/O interface 3010, the I/O interface 3010 is only required to provide output of the various first and/or second reference signals. Depending upon the selected embodiment, the I/O interface 3010 may also be implemented to accept various types of input. Similarly, in exemplary embodiments utilizing switchable or configurable connections (discussed below), the I/O interface 3010 may be implemented for both output and input functionality, with input signals correspondingly switched or routed to other parts of the IC, as part of I/O pin configuration, for example.
The I/O interface 3010 is utilized to provide any and/or all signaling and physical interface functions, such as impedance matching, signal transmission or other data output from the first discrete apparatus 3000 to any other device, and any other communication functionality suitable for any selected application. In the exemplary embodiment, the I/O interface 3010 may be implemented to be configurable or programmable, such as for selection of output signal levels (e.g., full voltage rail-to-full voltage rail, or fractional voltage rail-to-fractional voltage rail), selection of output signal types (e.g., single-ended or differential), and for changing or matching a load to be driven. In other exemplary embodiments, the I/O interface 3010 also may be implemented to be non-configurable, such as to provide the one or second reference signals at fixed or predetermined levels, types, and loads.

Such configurability or programmability is also applicable to other configurable or programmable components of the other illustrated, discrete embodiments, and such configurability and/or programmability may be provided through either or both the control circuit or logic and/or stored coefficients register (1215) and a user interface 3025, and implemented as part of design and manufacture, or implemented post-fabrication by a manufacturer, distributor, or end user. (Implementation through control circuit or logic and/or stored coefficients register (1215) is illustrated using the dashed lines of FIG. 45.) In addition, such configurability and/or programmability may be implemented utilizing any type of configurable, programmable, selection, switching or routing circuitry, discussed in detail below with respect to configurable switching or routing circuitry 3040 of FIGS. 46-48. For example, such configuration and/or programming may be implemented using switches, fuses, laser trimming, pass-transistors, multiplexers, demultiplexers, FPGAs, other configurable logic, etc. The various configurations or programs may be one-time configurations, such as when implemented through fuse connections, mask programming, or static coefficients stored in ROM, or may be reconfigurable, such as through storing variable coefficients in non-volatile memory, such as FLASH or EPROM, for control of corresponding switches or multiplexers, for example.

In addition, configurability or programmability may be provided as part of the design and fabrication of the various embodiments. For example, as discussed above, various pluralities of coefficients or control signals are determined post-fabrication for selection of the first frequency of the first reference signal by calibration to another reference frequency signal, such as an external frequency reference. The first frequency also may be mask programmable through selection of a size (and/or amounts or numbers) of the reactances (inductor(s) and/or capacitors), through selection of a plurality of connections and/or interconnections of the plurality of switchable, controlled reactance modules, to connect or disconnect the various reactances for control of the first frequency, or selection of a plurality of sizes of the plurality of switchable, controlled reactance modules, through selection of the type of signal (such as single-ended or differential), for example. The first frequency is also configurable post-fabrication through selection of a plurality of connections or interconnections of the plurality of switchable, controlled reactance modules and the interconnections of the other various components.

Other configurations are also mask programmable or otherwise configurable or selectable as part of the IC fabrication process. For example, any of the various connections and interconnections between and among components may be programmed in any of the conductive layer masks. For example, a selection of the output location of one or more second reference signals may occur at any point in a divide or locking chain, and may be selected through corresponding selection of interconnections provided in a conductive mask layer. Continuing with the example, for design and fabrication configurability, the I/O interface 3010 may be configured through providing various interconnections (through conductive layer masks), such as to a selected driver or amplifier of a plurality of drivers or amplifiers, to provide a corresponding signal level, or through bonding to a selected potential or floating potential. In addition, any of the various process parameters and sizes may also be modified for programmability and/or configurability, such as through any of the various etches, doping, ion implantation, deposition, layer thicknesses, conductive choices (e.g., metal versus polysilicon), use of stressed or strained substrates such as strained silicon, and so on. Other methods and types of configurability and programmability will be apparent to those of skill in the art, are considered equivalent, and within the scope of the present invention.

Continuing to refer to FIG. 45, spread-spectrum functionality may also be implemented in accordance with the present invention. For example and without limitation, spread-spectrum functionality may be implemented within the a clock/frequency reference (100, 200, 300), to vary the frequency of the first reference signal over time, or within any of the various dividers (1000, 1010, 1074, 1218, 1219) or locking circuits 1204 to vary any of the second frequencies of the corresponding second reference signals over time. For example, a control circuit of (control logic and/or stored coefficients register (1215)) may be coupled to the plurality of switchable, controlled reactance modules, and adapted to provide a time-dependent switching of the plurality of switchable, controlled reactance modules to modify the first frequency and provide a spread-spectrum first reference signal having a plurality of different first frequencies over time. Also for example, a control circuit of (control logic and/or stored coefficients register (1215)) may be coupled to one or more of the locking circuits 1204, with the control circuit adapted to provide a time-dependent variance of the divide ratio to provide a spread-spectrum second reference signal having a plurality of different, second frequencies over time. Continuing with the example, the various first and second dividers (1206 and 1207) (of a locking circuit 1204), or any of the other divide circuits (1000, 1010, 1074, 1218, 1219), may be implemented as counters, with the control circuit adapted to modify the terminal or ultimate count upon which the counter provides an output signal, also to vary the one or more second reference signals to provide a spread-spectrum second reference signal having a plurality of different, second frequencies over time.

The various calibrations and configurations may be provided post-fabrication through a user interface 3025. Such a user interface 3025 may be implemented to provide input to the various types of control circuitry (e.g., 3015, 1810) and/or coefficient registers (e.g., 455, 465, 495, 1215, 1950, 3020) for input of any selections or configurations. For example, the user interface 3025 may be coupled to a test bench or other computer interface, for automated input of such selections and configurations, as may be known or become known in the art, such as coupled to the various types of workstations or other equipment utilized for programming FPGAs, non-volatile memory, or other configurable logic.

FIG. 46 is a block diagram illustrating an exemplary second discrete apparatus 3030 embodiment in accordance with the teachings of the present invention. FIG. 47 is a block diagram illustrating an exemplary third discrete apparatus 3050 embodiment in accordance with the teachings of the
present invention. FIG. 48 is a block diagram illustrating an exemplary fourth discrete apparatus 3070 embodiment in accordance with the teachings of the present invention. The second discrete apparatus 3030 is implemented utilizing one or more dividers (1000, 1010, 1074, 1218, 1219), such as configurable counters. The third discrete apparatus 3050 is implemented utilizing one or more locking circuits 1204 (with configurable divide ratios, typically also implemented using configurable counters for incorporated first and second divide circuits). The fourth discrete apparatus 3070 is implemented utilizing both one or more dividers (1000, 1010, 1074, 1218, 1219), such as configurable counters, and one or more locking circuits 1204 (also with configurable divide ratios). In addition, the control circuit 3015 and coefficient register 3020 of the control circuit or logic and/or stored coefficients register (1215) are illustrated separately.

Instead of providing the various first reference signal and/or plurality of second reference signals directly to the corresponding I/O interfaces 3010 of the plurality of I/O interfaces 3010, for these exemplary second, third and fourth discrete apparatus embodiments, the first reference signal and plurality of second reference signals are provided to configurable switching (or routing) circuitry 3040. More particularly, the one or more dividers (1000, 1010, 1074, 1218, or 1219) and/or one or more locking circuits 1204 provide a corresponding plurality of second (or third) reference signals (clock or other reference signals) having a corresponding plurality of second (or third) frequencies, including of any type or shape (single-ended, differential, square-wave, sinusoidal, spread spectrum) (illustrated as plurality of plurality of second or third reference signals having corresponding second or third frequencies \( f_1, f_2, \ldots, f_n \) to the configurable switching (or routing) circuitry 3040, also with the first reference signal having first frequency \( f_0 \). In turn, the configurable switching (or routing) circuitry 3040 selectively switches or routes the first reference signal and plurality of second reference signals to selected I/O interfaces 3010 of the plurality of I/O interfaces 3010. Such selective switching or routing also may be controlled through the control circuitry 3015 and/or coefficient register 3020 (of a control circuit/ coefficient register 1215), and also configured or programmed through the user interface 3025.

The configurable switching (or routing) circuitry 3040 may be implemented utilizing any type of configurable, programmable, switching or routing circuitry. For example, such configuration and/or programming may be implemented using multiplexers, demultiplexers, switches, fuses, laser trimming, pass-transistors, FPGAs, or any other types of configurable logic or switching, etc. The various configurations or programs may be one-time configurations which provide a direct routing (direct interconnection) of signals, such as when implemented through mask connections, fuse connections or fixed coefficients stored in ROM, or may be reconfigurable, such as through storing variable coefficients in non-volatile memory, through state machines implemented in control circuitry and other types of control circuitry, for control of corresponding switches or multiplexers, for example. The selected switching or routing provided by the configurable switching (or routing) circuitry 3040 may be programmable or configurable as part of the fabrication process discussed above, such as through mask programmable connections, or may be determined post fabrication, such as through the control circuit or logic and/or stored coefficients register (1215) and user interface 3025.

For example, a generic, flexible and/or adaptive integrated circuit containing the various exemplary embodiments may be designed (and fabricated) to support a wide range of first and second frequencies, as discussed above, such as through mask programmability. Post-fabrication, typically through the user interface 3025 or other mechanisms previously discussed, the selected apparatus (IC) may be calibrated to have a first reference signal at one or more first frequencies, such as through the determination of the various coefficients previously discussed (and stored in a coefficient register, such as one of the registers previously discussed or coefficient register 3020). In addition, depending upon the selected embodiment, such calibration may provide one or more control signals.

Continuing with the example, also through the user interface 3025, any of the various second and/or third frequencies may be selected, along with their output locations, levels, and types, for providing specific output frequencies and signal types from the otherwise generic or flexible IC. Also post-fabrication, any of the various configurations or programming discussed above may be implemented, through either the use of control signals (from control circuit 3015) or coefficients (such as switching or control coefficients) (stored in coefficient register 3020) and utilized, for example, control switching or routing of the various first and second reference signals. In addition, through the user interface 3025, the manufacturer, distributor or end user may also configure any of the switching (or routing) circuitry 3040 and other parameters previously discussed, such as the various divide ratios or terminal (ultimate) counts utilized by the various locking circuits 1204 or dividers (1000, 1010, 1074, 1218, 1219) for frequency selection of the one or more second (or third) reference signals, the selected configuration of the I/O interfaces 3010 (e.g., signal level, signal type), and with the configurable switching (or routing) circuitry 3040, may provide for switching or routing of any selected first or second reference signal, having a corresponding, selected (and configurable) frequency, to any of the I/O interfaces 3010 of the plurality of I/O interfaces 3010. This selection feature can be utilized, for example, for customized IC pin programming, to provide one or more selected clock signals at selected IC pins.

In summary, the present invention provides an integrated circuit comprising: an oscillator comprising an inductor and a capacitor, the oscillator adapted to provide a first reference signal having a first frequency, the oscillator further adapted to operate without locking to an external reference signal; a voltage controller adapted to provide a plurality of voltage control signals; a plurality of switchable, controlled reactance modules coupled to the oscillator and to the voltage controller, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a corresponding voltage control signal of the plurality of voltage control signals to modify the first frequency; and an output circuit adapted to provide an interface for external signal communication.

The exemplary integrated circuit may further comprise a divider circuit coupled to the oscillator, the divider circuit adapted to provide a second reference signal at a second frequency. A locking circuit may be coupled to the divider circuit and adapted to lock to the second reference signal and provide a third reference signal having a third frequency, with the third frequency determined from the second frequency and a divide ratio of the locking circuit. In addition, a control circuit may be coupled to the locking circuit, with the control circuit adapted to provide a time-dependent variance of the divide ratio to provide a spread-spectrum third reference signal having a plurality of different third frequencies over time. Alternatively, a control circuit may be coupled to the plurality of switchable, controlled reactance modules, with the control circuit adapted to provide a time-dependent switching of the
plurality of switchable, controlled reactance modules to provide a spread-spectrum first reference signal having a plurality of different first frequencies over time.

The output circuit may be configurable for selection of a signal type of a plurality of signal types of the second reference signal, the plurality of signal types comprising at least one of the following signal types: differential, single-ended, full voltage rail-to-full voltage rail, or fractional voltage rail-to-fractional voltage rail.

The exemplary integrated circuit may further comprise a plurality of locking circuits coupled to the divider circuit, the plurality of locking circuits adapted to lock to the second reference signal and provide a corresponding plurality of third reference signals having a plurality of corresponding third frequencies, each third frequency of the plurality of corresponding third frequencies determined from the second frequency and a divide ratio of the corresponding locking circuit of the plurality of locking circuits. Each locking circuit of the plurality of locking circuits may be one of the following locking circuits: a phase-locked loop, a delay-locked loop, or an injection locking circuit. In addition, each locking circuit of the plurality of locking circuits may be configurable for selection of the divide ratio.

The exemplary integrated circuit may further comprise a plurality of output circuits adapted to provide a corresponding plurality of output interfaces for signal communication; and first switching circuitry coupled to the plurality of locking circuits and to the plurality of output circuits, the first switching circuitry adapted to selectively switch a selected second reference signal of the plurality of third reference signals to a selected output circuit of the plurality of output circuits. Control circuitry may be coupled to the plurality of output circuits and adapted to provide a control signal to a selected output circuit of the plurality of output circuits for selection of a signal type of a plurality of signal types of a corresponding third reference signal. Control circuitry may be coupled to the first switching circuitry and adapted to provide a control signal to the first switching circuitry to switch the selected third reference signal to the selected output circuit.

Similarly, a coefficient register may be coupled to the first switching circuitry and adapted to provide a first control coefficient of a first plurality of control coefficients to the first switching circuitry to switch the selected third reference signal to the selected output circuit. The coefficient register may be further coupled to the plurality of switchable, controlled reactance modules, the coefficient register adapted to store a second plurality of coefficients and to provide a corresponding coefficient of the second plurality of coefficients to control switching of a corresponding controlled reactance module to the oscillator. The second plurality of coefficients may be determined post-fabrication by calibration to an external signal providing a reference frequency. The exemplary integrated circuit may further comprise a user interface coupled to the coefficient register and adapted to provide a coefficient of the first plurality of coefficients or second plurality of coefficients to the coefficient register in response to user input.

The first switching circuitry may comprise, for example, a plurality of multiplexers and demultiplexers, or a plurality of pass-transistors, or a cross-bar switch.

The first frequency may be mask programmable through selection of a size of the inductor, or through selection of a plurality of connections of the plurality of switchable, controlled reactance modules, or through selection of a plurality of sizes of the plurality of switchable, controlled reactance modules. The first frequency may be configurable post-fab-

ication through selection of a plurality of connections of the plurality of switchable, controlled reactance modules.

Another exemplary integrated circuit embodiment may comprise: a harmonic oscillator comprising an inductor and a capacitor, the harmonic oscillator adapted to provide a first reference signal having a first frequency; a plurality of controlled reactance modules coupled to the harmonic oscillator, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a control voltage of a plurality of control voltages to modify the first frequency; a first coefficient register adapted to store a first plurality of switching coefficients; a plurality of switches coupled to the plurality of controlled reactance modules, each switch of the first plurality of switches responsive to a corresponding switching coefficient of the first plurality of switching coefficients to couple a selected control voltage of the plurality of control voltages to a corresponding controlled reactance module; a first divider coupled to the harmonic oscillator, the first divider adapted to provide a second reference signal at a second frequency; and a plurality of locking circuits coupled to the first divider, the plurality of locking circuits adapted to lock to the second reference signal and provide a corresponding plurality of third reference signals having a plurality of corresponding third frequencies, each third frequency of the plurality of corresponding third frequencies determined from the second frequency and a divide ratio of the corresponding locking circuit of the plurality of locking circuits. The harmonic oscillator may be further adapted to operate without locking to an external reference signal.

Also in summary, another exemplary configurable integrated circuit embodiment may comprise: an oscillator comprising an inductor, a capacitor, and a transconductance amplifier, the oscillator adapted to provide a first reference signal having a first frequency; the oscillator further adapted to operate without locking to an external reference signal, the transconductance amplifier further comprising a variable current source adapted to provide a corresponding current in response to operating temperature; a voltage controller adapted to provide a plurality of voltage control signals; a plurality of switchable, controlled reactance modules coupled to the oscillator and to the voltage controller, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a corresponding voltage control signal of the plurality of voltage control signals to modify the first frequency; a first divider coupled to the harmonic oscillator, the first divider adapted to provide a second reference signal at a second frequency; and a plurality of configurable locking circuits coupled to the first divider, the plurality of locking circuits adapted to lock to the second reference signal and provide a corresponding plurality of third reference signals having a plurality of corresponding third frequencies, each third frequency of the plurality of corresponding third frequencies determined from the second frequency and a configurable divide ratio of the corresponding locking circuit of the plurality of locking circuits.

Also in summary, the present invention provides an integrated circuit, comprising: a resonator comprising an inductor and a capacitor, the resonator adapted to provide a first reference signal having a first frequency; a voltage controller adapted to provide a plurality of voltage control signals; a plurality of switchable, controlled reactance modules coupled to the resonator and to the voltage controller, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a corresponding voltage control signal of the plurality of voltage control signals to modify the first frequency; and a processor
coupled to the resonator. The IC may further comprise a locking circuit coupled to the resonator, the locking circuit adapted to lock to the first reference signal and provide a second reference signal having a second frequency which is a rational multiple of the first frequency; and wherein the processor is coupled through the locking circuit to the resonator, and is adapted to receive the second reference signal.

The first or second reference signals may be, for example, a square-wave clock signal. The processor may be any type of circuitry adapted to perform a function, for example, any one of the following types of processors: a microprocessor; a digital signal processor; a controller; a microcontroller; a universal serial bus (USB) controller; a Peripheral Component Interconnect (PCI) controller; a Peripheral Component Interconnect Express (PCI-e) controller; a Firewire controller; an AT Attachment (ATA) interface controller, an Integrated Drive Electronics (IDE) controller; a Small Computer Systems Interface (SCSI) controller; a television controller; a local area network (LAN) controller; an Ethernet controller; a video controller; an audio controller; a modem processor; an MPEG controller; a multimedia controller; a communication controller; a mobile communication controller; an Ethernet 802.11 controller; a GSM controller; a GPRS controller, a PCS controller; an AMPS controller; a CDMA controller; a WCDMA controller; a spread spectrum controller; a wireless LAN controller; an IEEE 802.11 controller; a DSL controller; a T1 controller; an ISDN controller; or a cable modem controller. The integrated circuit may also further comprise: a memory coupled to the processor and further coupled to the locking circuit to receive the second reference signal; and an input/output interface coupled to the processor and further coupled to the locking circuit to receive the second reference signal. The locking circuit may be one of the following locking circuits, for example: a phase-locked loop, a delay-locked loop, or an injection locking circuit.

In other exemplary embodiments, the integrated circuit further comprises a plurality of locking circuits coupled to the resonator, the plurality of locking circuits adapted to lock to the first reference signal and provide a corresponding plurality of second reference signals having a plurality of corresponding frequencies; and may also include switching circuitry coupled to the plurality of locking circuits and to the processor, the switching circuitry adapted to selectively couple the processor to the plurality of locking circuits by switching a selected, second reference signal of the corresponding plurality of second reference signals to the processor. The integrated circuit may further comprise: control circuitry coupled to the switching circuitry, the control circuitry adapted to provide a control signal to the switching circuitry to switch the selected, second reference signal to the processor; and/or a coefficient register coupled to the switching circuitry, the coefficient register adapted to provide a control coefficient to the switching circuitry to switch the selected, second reference signal to the processor. Each locking circuit of the plurality of locking circuits may further comprise a plurality of asynchronous or synchronous divider circuits, and the plurality of corresponding frequencies are determined by corresponding divide ratios of the plurality of divider circuits. The integrated circuit may further comprise a spread-spectrum generator coupled to the resonator or the locking circuit, the spread-spectrum generator adapted to provide time-varying modulation of the first reference signal or the second reference signal.

In other exemplary embodiments, the integrated circuit may comprise: a harmonic oscillator comprising an inductor and a capacitor, the harmonic oscillator adapted to provide a first reference signal having a first frequency; a plurality of resistive modules adapted to generate a plurality of voltage control signals; a plurality of controlled reactance modules coupled to the harmonic oscillator and to the plurality of resistive modules, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a corresponding voltage control signal of the plurality of voltage control signals to modify the first frequency; a first coefficient register coupled to the plurality of switches, the first coefficient register adapted to store a first plurality of switching coefficients; a first plurality of switches coupled to the plurality of resistive modules and to the plurality of controlled reactance modules, each switch of the first plurality of switches responsive to a corresponding switching coefficient of the first plurality of switching coefficients to couple a selected control voltage of the plurality of control voltages to a corresponding controlled reactance module; a locking circuit operatively coupled to the harmonic oscillator, the locking circuit adapted to lock to the first reference signal and provide a second reference signal having a second frequency; and a processor operatively coupled to the locking circuit to receive the second reference signal.

This integrated circuit may further comprise: a plurality of locking circuits operatively coupled to the harmonic oscillator, the plurality of locking circuits adapted to lock to the first reference signal and provide a corresponding plurality of second reference signals having a plurality of corresponding frequencies; and a second plurality of switches coupled to the plurality of locking circuits and to the processor, the second plurality of switches adapted to switch a selected, second reference signal of the corresponding plurality of second reference signals to the processor. In addition, control circuitry may be coupled to the second plurality of switches, the control circuitry adapted to provide a control signal to the second plurality of switches to switch the selected, second reference signal to the processor. Alternatively, a second coefficient register may be coupled to the second plurality of switches, the second coefficient register adapted to provide a control coefficient to the second plurality of switches to switch the selected, second reference signal to the processor.

In other exemplary embodiments, the integrated circuit comprises: a resonator comprising an inductor and a capacitor, the resonator adapted to provide a first reference signal having a first frequency; a sensor adapted to provide a second signal in response to operating temperature or fabrication process variation; a voltage controller adapted to provide a plurality of voltage control signals; a plurality of switchable, controlled reactance modules coupled to the resonator and to the voltage controller, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a corresponding voltage control signal of the plurality of voltage control signals to modify the first frequency; a plurality of locking circuits operatively coupled to the resonator, the plurality of locking circuits adapted to lock to the first reference signal and provide a corresponding plurality of second reference signals having a plurality of corresponding frequencies; a processor adapted to receive a selected, second reference signal of the plurality of second reference signals and switching circuitry coupled to the plurality of locking circuits and to the processor, the switching circuitry adapted to switch the selected, second reference signal to the processor.

Also in summary, the present invention provides an apparatus comprising a resonator adapted to provide a first signal having a resonant frequency; an amplifier coupled to the resonator; and a frequency controller (coupled to the resonator) which is adapted to select a resonant frequency having a first frequency of a plurality of frequencies. The apparatus
also includes a frequency divider (coupled to the resonator) which is adapted to divide the first signal having the first frequency into a plurality of second signals having a corresponding plurality of frequencies, the plurality of frequencies substantially equal to or lower than the first frequency, such as by division by a rational number.

The first signal may be a differential signal or a single-ended signal. When the first signal is a differential signal, the frequency divider is further adapted to convert the differential signal to a single-ended signal. Similarly, when the first signal is a substantially sinusoidal signal, the frequency divider is further adapted to convert the substantially sinusoidal signal to a substantially square wave signal.

In various embodiments, the frequency divider may comprise a plurality of flip-flops or counters coupled successively in series, wherein an output of a selected flip-flop or counter is a frequency of a previous flip-flop or counter divided by two, or more generally, a plurality of dividers coupled successively in series, wherein an output of a successive divider is a lower frequency than the output of a previous divider. The plurality of dividers may be differential, single-ended, or differential and single-ended, such as differential followed by a final single-ended stage. The frequency divider may also include a square-wave generator adapted to convert the first signal into a substantially square-wave signal having a substantially equal high and low duty cycle.

The present invention may also include a frequency selector coupled to the frequency divider, and adapted to provide an output signal from the plurality of second signals. The frequency selector may further comprise a multiplexer and a glitch-suppressor.

The present invention may also include a mode selector coupled to the frequency selector, wherein the mode selector is adapted to provide a plurality of operating modes, which may be selected from a group comprising a clock mode, a timing and frequency reference mode, a power conservation mode, and a pulsed mode.

For a reference mode, the invention may also include a synchronization circuit coupled to the mode selector; and a controlled oscillator coupled to the synchronization circuit and adapted to provide a third signal; wherein in the timing and reference mode, the mode selector is further adapted to couple the output signal to the synchronization circuit to control timing and frequency of the third signal. Such a synchronization circuit may be a delay-locked loop, a phase-locked loop, or an injection locking circuit.

In selected embodiments, the amplifier may be a negative transconductance amplifier. The frequency controller may be further adapted to modify a current through the negative transconductance amplifier in response to temperature, and may comprise a current source responsive to temperature. Such a current source may have one or more configurations selected from a plurality of configurations, such as the plurality of configurations comprising CTAT, PTAT, and PTAT² configurations.

In addition, the frequency controller may be further adapted to modify a current through the negative transconductance amplifier to select the resonant frequency, modify a transconductance of the negative transconductance amplifier to select the resonant frequency, or modify a current through the negative transconductance amplifier in response to a voltage. The frequency controller may also include a voltage isolator coupled to the resonator and adapted to substantially isolate the resonator from a voltage variation, and may comprises a current mirror, which may further have a cascode configuration. The frequency controller may be further adapted to modify a capacitance or an inductance of the resonator in response to fabrication process variation, temperature variation, or voltage variation.

The frequency controller may have various embodiments for these various functions, and may further comprise: a coefficient register adapted to store a first plurality of coefficients; and a first array having a plurality of switchable capacitive modules coupled to the coefficient register and to the resonator, each switchable capacitive module having a fixed capacitance and a variable capacitance, each switchable capacitive module responsive to a corresponding coefficient of the first plurality of coefficients to switch between the fixed capacitance and the variable capacitance and to switch each variable capacitance to a control voltage. The plurality of switchable capacitive modules may be binary-weighted, or have another weighting scheme. The frequency controller may also include a second array having a plurality of switchable resistive modules coupled to the coefficient register and further having a capacitive module, the capacitive module and the plurality of switchable resistive modules further coupled to a node to provide the control voltage, each switchable resistive module responsive to a corresponding coefficient of a second plurality of coefficients stored in the coefficient register to switch the switchable resistive module to the control voltage node; and a temperature-dependent current source coupled through a current mirror to the second array.

The frequency controller may also include a process variation compensator coupled to the resonator and adapted to modify the resonant frequency in response to fabrication process variation. In an exemplary embodiment, the process variation compensator may comprise: a coefficient register adapted to store a plurality of coefficients; and an array having a plurality of switchable capacitive modules coupled to the coefficient register and to the resonator, each switchable capacitive module having a first fixed capacitance and a second fixed capacitance, each switchable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between the first fixed capacitance and the second fixed capacitance. The plurality of switchable capacitive modules may be binary-weighted, or have another weighting scheme.

In another exemplary embodiment the process variation compensator may comprise: a coefficient register adapted to store a plurality of coefficients; and an array having a plurality of switchable variable capacitive modules coupled to the coefficient register and to the resonator, each switchable variable capacitive module responsive to a corresponding coefficient of the plurality of coefficients to switch between a first voltage and a second voltage. The plurality of switchable variable capacitive modules also may be binary-weighted, or have another weighting scheme.

The present invention may also include a frequency calibration module coupled to the frequency controller and adapted to modify the resonant frequency in response to a reference signal. For example, the frequency calibration module may include a frequency divider coupled to the frequency controller, the frequency divider adapted to convert an output signal derived from the first signal having the first frequency to a lower frequency to provide a divided signal; a frequency detector coupled to the frequency divider, the frequency detector adapted to compare the reference signal to the divided signal and provide one or more up signals or down signals; and a pulse counter coupled to the frequency detector, the pulse counter adapted to determine a difference between the one or more up signals or down signals as an indicator of a difference between the output signal and the reference signal.
The resonator used with the invention may comprise an inductor (L) and a capacitor (C) coupled to form an LC-tank, having a selected configuration of a plurality of LC-tank configurations, such as series, parallel and so on, and may include other components. In other embodiments, the resonator may be selected from a group comprising: a ceramic resonator, a mechanical resonator, a microelectromechanical resonator, and a film bulk acoustic resonator, or any other resonator which is electrically equivalent to an inductor (L) coupled to a capacitor (C).

For example, the resonator typically comprises one or more inductors and capacitors, forming one or more LC-tanks or LC resonators. In a first embodiment, a double-balanced, differential LC oscillator topology is utilized. In other exemplary embodiments, differential or single-ended LC oscillator topologies may be utilized, for example, a single-ended Colpitts LC oscillator, a single-ended Hartley LC oscillator, a differential Colpitts LC oscillator (both common base and common collector versions), a differential Hartley LC oscillator (also both common base and common collector versions), a single-ended Pierce LC oscillator, a quadrature oscillator (e.g., formed from at least two double-balanced, differential LC oscillators), or an active inductor LC oscillator (which may be implemented to be either differential or single-ended). Additional LC oscillator topologies, now known or which become known, are considered equivalent and within the scope of the present invention.

The apparatus of the invention may be utilized as a timing and frequency reference, or as a clock generator. In addition, the invention may also include a second oscillator (such as a ring, relaxation, or phase shift oscillator) providing a second oscillator output signal; and a mode selector coupled to the frequency controller and to the second oscillator, the mode selector adapted to switch to the second oscillator output signal to provide a power conservation mode. Additional operating modes may be provided by a mode selector coupled to the frequency controller, which may be adapted to periodically start and stop the resonator to provide a pulsed output signal, or adapted to selectively start and stop the resonator to provide a power conservation mode.

In another selected embodiment, the apparatus of the invention, comprises: a resonator adapted to provide a first signal having a resonant frequency; an amplifier coupled to the resonator; a temperature compensator coupled to the amplifier and to the resonator, the temperature compensator adapted to modify the resonant frequency in response to temperature; a process variation compensator coupled to the resonator, the process variation compensator adapted to modify the resonant frequency in response to fabrication process variation; a frequency divider coupled to the resonator, the frequency divider adapted to divide the first signal having the resonant frequency into a plurality of single-ended, substantially square-wave second signals having a corresponding plurality of frequencies, the plurality of frequencies substantially equal to or lower than the resonant frequency, and each second signal having a substantially equal high and low duty cycle; and a frequency selector coupled to the frequency divider, the frequency selector adapted to provide an output signal from the plurality of second signals.

From the foregoing, it will be observed that numerous variations and modifications may be effected without departing from the spirit and scope of the novel concept of the invention. It is to be understood that no limitation with respect to the specific methods and apparatus illustrated herein is intended or should be inferred. It is, of course, intended to cover by the appended claims all such modifications as fall within the scope of the claims.

It is claimed:
1. An integrated circuit comprising: a reference oscillator comprising an inductor and a capacitor, the reference oscillator adapted to provide a first reference signal having a first frequency; a plurality of controlled reactance modules coupled to the reference oscillator, each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to a control voltage to maintain the first frequency substantially constant in a first operating mode; and an output circuit adapted to provide an output interface for signal communication.
2. The integrated circuit of claim 1, further comprising: a voltage controller coupled to the plurality of controlled reactance modules, the voltage controller adapted to provide the control voltage.
3. The integrated circuit of claim 1, further comprising: a control circuit coupled to the plurality of controlled reactance modules, the control circuit adapted to provide a time-dependent switching of the plurality of controlled reactance modules, in a second operating mode, to provide a spread-spectrum first reference signal having a plurality of different first frequencies over time.
4. The integrated circuit of claim 1, further comprising: a divider circuit coupled to the reference oscillator, the divider circuit adapted to provide a second reference signal at a second frequency.
5. The integrated circuit of claim 4, further comprising: a locking circuit coupled to the divider circuit and adapted to lock to the second reference signal and provide a third reference signal having a third frequency, the third frequency determined from the second frequency and a divide ratio of the locking circuit.
6. The integrated circuit of claim 5, further comprising: a control circuit coupled to the locking circuit, the control circuit adapted to provide a time-dependent variance of the divide ratio to provide a spread-spectrum third reference signal having a plurality of different third frequencies over time.
7. The integrated circuit of claim 4, wherein the output circuit is configurable for selection of a signal type of a plurality of signal types of the second reference signal, the plurality of signal types comprising at least one of the follow-
8. The integrated circuit of claim 4, further comprising: a plurality of locking circuits coupled to the divider circuit, the plurality of locking circuits adapted to lock to the second reference signal and provide a corresponding plurality of third reference signals having a plurality of corresponding third frequencies, each third frequency of the plurality of corresponding third frequencies determined from the second frequency and a divide ratio of the corresponding locking circuit of the plurality of locking circuits.

9. The integrated circuit of claim 8, wherein each locking circuit of the plurality of locking circuits is at least one of the following locking circuits: a phase-locked loop, a delay-locked loop, or an injection locking circuit.

10. The integrated circuit of claim 8, wherein each locking circuit of the plurality of locking circuits is configurable for selection of the divide ratio.

11. The integrated circuit of claim 8, further comprising: a plurality of output circuits adapted to provide a corresponding plurality of output interfaces for signal communication; and first switching circuitry coupled to the plurality of locking circuits and to the plurality of output circuits, the first switching circuitry adapted to selectively switch a selected, third reference signal of the plurality of third reference signals to a selected output circuit of the plurality of output circuits.

12. The integrated circuit of claim 11, further comprising: control circuitry coupled to the plurality of output circuits, the control circuitry adapted to provide a control signal to a selected output circuit of the plurality of output circuits for selection of a signal type of a plurality of signal types of a corresponding third reference signal, the plurality of signal types comprising at least one of the following signal types: differential, single-ended, full voltage rail-to-full voltage rail, or fractional voltage rail-to-fractional voltage rail.

13. The integrated circuit of claim 11, further comprising: control circuitry coupled to the first switching circuitry, the control circuitry adapted to provide a control signal to the first switching circuitry to switch the selected, third reference signal to the selected output circuit.

14. The integrated circuit of claim 11, further comprising: a coefficient register coupled to the first switching circuitry, the coefficient register adapted to provide a first control coefficient of a first plurality of control coefficients to the first switching circuitry to switch the selected, third reference signal to the selected output circuit.

15. The integrated circuit of claim 14, wherein the coefficient register is further coupled to the plurality of controlled reactance modules, the coefficient register adapted to store a second plurality of coefficients and to provide a corresponding coefficient of the second plurality of coefficients to control a switching of a corresponding controlled reactance module to the oscillator.

16. The integrated circuit of claim 15, further comprising: a voltage controller coupled to the plurality of controlled reactance modules, the voltage controller adapted to provide the control voltage; and wherein the plurality of controlled reactance modules further comprise: a second plurality of switches coupled to the coefficient register, and a plurality of variable capacitors correspondingly coupled to the second plurality of switches and to the voltage controller, the plurality of variable capacitors adapted to provide a selected capacitance in response to the control voltage.

17. The integrated circuit of claim 16, wherein the plurality of controlled reactance modules further comprise: a plurality of fixed capacitors correspondingly coupled to the second plurality of switches, the plurality of fixed capacitors adapted to provide a selected capacitance in response to a corresponding coefficient.

18. The integrated circuit of claim 15, wherein the second plurality of coefficients is determined post-fabrication by calibration to an external signal providing a reference frequency.

19. The integrated circuit of claim 15, further comprising: a user interface coupled to the coefficient register, the user interface adapted to provide a coefficient of the first plurality of coefficients or second plurality of coefficients to the coefficient register in response to user input.

20. The integrated circuit of claim 11, wherein the first switching circuitry comprises a plurality of multiplexers and demultiplexers, or a plurality of pass-transistors, or a crossbar switch.

21. The integrated circuit of claim 1, wherein the first frequency is programmable through selection of a size of the inductor, or through selection of a plurality of connections of the plurality of controlled reactance modules, or through selection of a plurality of sizes of the plurality of controlled reactance modules.

22. The integrated circuit of claim 1, wherein the first frequency is configurable post-fabrication through selection of a plurality of connections of the plurality of controlled reactance modules.

23. The integrated circuit of claim 1, wherein the oscillator has at least one configuration of the following configurations: a double-balanced, differential LC configuration; a differential n-MOS cross-coupled topology; a differential p-MOS cross-coupled topology; a single-ended Colpitts LC configuration; a single-ended Hartley LC configuration; a differential, common base Colpitts LC configuration; a differential, common base Hartley LC configuration; a differential, common collector Colpitts LC configuration; a differential, common collector Hartley LC configuration; a single-ended Pierce LC oscillator, or a quadrature LC oscillator configuration.

24. The integrated circuit of claim 1, further comprising a variable current source, the variable current source adapted to provide a corresponding current to a variable current source or ambient or operating temperature.

25. An integrated circuit comprising: a reference harmonic oscillator comprising an inductor and a capacitor, the harmonic oscillator adapted to provide a first reference signal having a first frequency; a first plurality of controlled oscillation modules coupled to the reference harmonic oscillator, each reactance module of the first plurality of oscillation modules adapted to provide a selected reactance in response to a control voltage to maintain the first frequency substantially constant in a first operating mode; a first coefficient register adapted to store a first plurality of switching coefficients; a first plurality of switches coupled to the first plurality of controlled reactance modules, each switch of the first plurality of switches responsive to a corresponding switching coefficient of the first plurality of switching
coefficients to couple a control voltage to a corresponding controlled reactance module; and
a first divider coupled to the reference harmonic oscillator, the first divider adapted to provide a second reference signal at a second frequency.

26. The integrated circuit of claim 25, wherein the reference harmonic oscillator is further adapted to provide the first reference signal without locking to an external reference signal.

27. The integrated circuit of claim 25, further comprising: a control circuit coupled to the first plurality of controlled reactance modules, the control circuit adapted to provide, in a second operating mode, a time-dependent switching of the plurality of control voltages to provide a spread-spectrum first reference signal having a plurality of different frequencies over time.

28. The integrated circuit of claim 25, further comprising: a second plurality of switches coupled to the first plurality of controlled reactance modules, each switch of the second plurality of switches responsive to a control signal to couple a selected controlled reactance module to a ground or power voltage.

29. The integrated circuit of claim 25, further comprising: a second plurality of controlled reactance modules; and a control circuit coupled to the second plurality of controlled reactance modules, the control circuit adapted to provide, in a second operating mode, a time-dependent switching of the second plurality of controlled reactance modules to the harmonic oscillator to provide a spread-spectrum first reference signal having a plurality of different frequencies over time.

30. The integrated circuit of claim 25, wherein the divider circuit is configurable for selection of a signal type of a plurality of signal types of the second reference signal, the plurality of signal types comprising at least one of the following signal types: differential, single-ended, full voltage rail-to-full voltage rail, or fractional voltage rail-to-fractional voltage rail.

31. The integrated circuit of claim 25, further comprising: a plurality of locking circuits coupled to the first divider, the plurality of locking circuits adapted to lock to the second reference signal and provide a corresponding plurality of third reference signals having a plurality of corresponding third frequencies, each third frequency of the plurality of corresponding third frequencies determined from the second frequency and a divide ratio of the corresponding locking circuit of the plurality of locking circuits.

32. The integrated circuit of claim 31, further comprising: a control circuit coupled to the plurality of locking circuits, the control circuit adapted to provide a time-dependent variance of the divide ratio of a first locking circuit of the plurality of locking circuits to provide a spread-spectrum third reference signal having a plurality of different third frequencies over time.

33. The integrated circuit of claim 31, wherein each locking circuit of the plurality of locking circuits is at least one of the following locking circuits: a phase-locked loop, a delay-locked loop, or an injection locking circuit.

34. The integrated circuit of claim 31, wherein each locking circuit of the plurality of locking circuits is configurable for selection of the divide ratio.

35. The integrated circuit of claim 31, further comprising: a plurality of output circuits; and second switching circuitry coupled to the plurality of locking circuits and to the plurality of output circuits, the second switching circuitry adapted to selectively switch a selected, third reference signal of the plurality of third reference signals to a selected output circuit of the plurality of output circuits.

36. The integrated circuit of claim 35, wherein each output circuit of the plurality of output circuits is configurable for selection of a signal level of a plurality of signal levels for output of a corresponding third reference signal of the plurality of third reference signals.

37. The integrated circuit of claim 35, further comprising: control circuitry coupled to the second switching circuitry, the control circuitry adapted to provide a control signal to the second switching circuitry to switch the selected, third reference signal to the selected output circuit.

38. The integrated circuit of claim 35, further comprising: a second coefficient register coupled to the second switching circuitry, the second coefficient register adapted to provide a control coefficient of a second plurality of control coefficients to the second switching circuitry to switch the selected, third reference signal to the selected output circuit.

39. The integrated circuit of claim 35, wherein the second switching circuitry comprises a plurality of multiplexers and demultiplexers, or a plurality of pass-transistors, or a crossbar switch.

40. The integrated circuit of claim 25, wherein the first plurality of controlled reactance modules further comprise: a plurality of variable capacitors, each variable capacitor of the plurality of variable capacitors adapted to provide a corresponding capacitance in response to the control voltage.

41. The integrated circuit of claim 40, further comprising: a second plurality of controlled reactance modules comprising a plurality of fixed capacitors, each fixed capacitor of the plurality of fixed capacitors adapted to provide a selected capacitance; and a second plurality of switches coupled to the second plurality of controlled reactance modules, each switch of the second plurality of switches responsive to a corresponding switching coefficient of a second plurality of switching coefficients to couple a corresponding controlled reactance module of the second plurality of controlled reactance modules to the reference harmonic oscillator.

42. The integrated circuit of claim 41, wherein the second plurality of switching coefficients is determined post-fabrication by calibration to a second reference frequency signal.

43. The integrated circuit of claim 41, further comprising: a user interface coupled to the first coefficient register, the user interface adapted to provide a coefficient of the first plurality of switching coefficients or second plurality of control coefficients to the first coefficient registers in response to user input.

44. The integrated circuit of claim 41, wherein the first frequency is mask programmable through selection of a size of the inductor, through selection of a plurality of connections of the first and second pluralities of controlled reactance modules, or through selection of a plurality of sizes of the first and second pluralities of controlled reactance modules.

45. The integrated circuit of claim 41, wherein the first frequency is configurable post-fabrication through selection of a plurality of connections of the first and second pluralities of controlled reactance modules.

46. The integrated circuit of claim 25, wherein the reference harmonic oscillator has at least one configuration of the following configurations: a double-balanced, differential LC configuration; a differential n-MOS cross-coupled topology; a differential p-MOS cross-coupled topology; a single-ended Colpitts LC configuration; a single-ended Hartley LC configuration; a differential, common base Colpitts LC configuration; a differential, common collector Colpitts LC configuration; a differential, common base Hartley LC configuration;
a differential, common collector Hartley LC configuration; a single-ended Pierce LC oscillator, or a quadrature LC oscillator configuration.

47. The integrated circuit of claim 25, further comprising:
a variable current source adapted to provide a corresponding current in response to ambient or operating temperature.

48. The integrated circuit of claim 47, wherein the variable current source has at least one complementary to absolute temperature (CTAT) configuration, proportional to absolute temperature (PTAT) configuration, or proportional to absolute temperature squared (PTAT²) configuration.

49. A configurable integrated circuit comprising:
a reference oscillator comprising an inductor, a capacitor, and an amplifier, the reference oscillator adapted to provide a first reference signal having a first frequency without locking to an external reference signal;
a voltage controller adapted to provide a control voltage;
a first plurality of controlled reactance modules coupled to the reference oscillator and to the voltage controller;
each reactance module of the plurality of reactance modules adapted to provide a selected reactance in response to the control voltage to maintain the first frequency substantially constant in a first operating mode;
a first divider coupled to the reference oscillator, the first divider adapted to provide a second reference signal at a second frequency; and

50. The configurable integrated circuit of claim 49, further comprising:
a control circuit coupled to the locking circuit, the control circuit adapted to provide a time-dependent configuration of the divide ratio of the locking circuit to provide a spread-spectrum third reference signal having a plurality of different third frequencies over time.

51. The integrated circuit of claim 49, further comprising:
a second plurality of controlled reactance modules;
a coefficient register coupled to the second plurality of controlled reactance modules, the coefficient register adapted to store a plurality of coefficients and to provide a corresponding coefficient to control switching of a corresponding controlled reactance module of the second plurality of controlled reactance modules to the reference oscillator.

52. The configurable integrated circuit of claim 49, further comprising:
a control circuit coupled to the coefficient register, the control circuit adapted to provide, in a second operating mode, a time-dependent switching of the second plurality of controlled reactance modules to the reference oscillator to provide a spread-spectrum first reference signal having a plurality of different first frequencies over time.

53. The configurable integrated circuit of claim 49, wherein the oscillator has at least one configuration of the following configurations: a double-balanced, differential LC configuration; a differential n-MOS cross-coupled topology; a differential p-MOS cross-coupled topology; a single-ended Colpitts LC configuration; a single-ended Hartley LC configuration; a differential, common base Colpitts LC configuration; a differential, common collector Colpitts LC configuration; a differential, common base Hartley LC configuration; a differential, common collector Hartley LC configuration; a single-ended Pierce LC oscillator, or a quadrature LC oscillator configuration.